



Technology Innovator

Puya

PY32T090 Datasheet

32-bit ARM[®] Cortex[®]-M0+ Microcontroller



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Features

- Core
 - 32-bit ARM® Cortex®-M0+
 - Frequency up to 72 MHz
- Memories
 - 256/192/128/64 KB Flash memory
 - 32/24/16/8 KB SRAM
- Clock management
 - 8/16/24/48/64 MHz High-speed internal RC oscillator (HSI)
 - 2 MHz Medium-speed internal RC oscillator (MSI)
 - 32.768 kHz Low-speed internal RC oscillator (LSI)
 - 4 to 32 MHz High-speed external crystal oscillator (HSE)
 - 32.768 kHz Low-speed external crystal oscillator (LSE)
 - PLL (supports 2 to 18 multiplication of HSI or HSE)
- Power management and reset
 - Operating voltage: 1.8 to 5.5 V
 - Low power modes: Low-power run, Sleep, Low-power sleep, Stop and Standby
 - Power-on/power-down reset (POR/PDR)
 - Brown-out reset (BOR)
 - Programmable voltage detector (PVD)
- Input/output (I/O)
 - Up to 62 I/Os, all available as external interrupts
 - All IOs support 50 mA sink current
 - 8 LED COM pins with configurable ultra-strong sink current:
 - 120/100/80/60 mA
- 16 GPIOs as LED SEG with constant-current drive
- Touch key
 - High-sensitivity design enables non-contact touch sensing
 - 10 V dynamic CS test-passed anti-interference mode
 - 33 touch channels with derived functions
- 7-channel DMA controller
- 1 x 12-bit ADC
 - Up to 25 external input channels
 - Voltage reference options: V_{CC} , embedded 0.6V/1.024V/1.5V/2.048V/2.5V
 - Input range: 0 to V_{REFP}
- 1 x 12-bit DAC (with 1 channel)
- 2 x comparators
- 1 x operational amplifier
- 8 * 36 / 4 * 40 LCD
- 14 timers
 - 1 x 16-bit advanced-control timer (TIM1)
 - 1 x 32-bit general-purpose timer (TIM2)
 - 4 x 16-bit general-purpose timers
 - 1 x PWM dedicated timer
 - 2 x basic timers (TIM6/TIM7)
 - 2 x low power timer (LPTIM)
 - 1 x independent watchdog timer (IWDG)
 - 1 x window watchdog timer (WWDG)
 - 1 x SysTick timer
- RTC
 - Support perpetual calendar

- Communication interfaces
 - 2 x serial peripheral interfaces (SPIs) with I²S function
 - 2 x universal synchronous/asynchronous receiver/transmitters (USARTs), support automatic baud rate detection, ISO7816, LIN and IrDA
 - 2 x universal asynchronous receiver transmitters (UARTs)
 - 2 x low power universal asynchronous receiver/transmitters (LPUARTs)
- 2 x I²C interfaces support Standard mode (100 kHz), Fast mode (400 kHz) and Fast mode plus (1 MHz), 7-bit/10-bit addressing, SMBus/PMBus compatible
 - Hardware CRC-32 module
 - Unique UID
 - Serial wire debug (SWD)
 - Operating temperature: -40 to 105 °C
 - Packages: LQFP64, QFN64, LQFP48, LQFP44, LQFP32 and SOP28

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1. Introduction

The PY32T090 series incorporate a 32-bit Arm® Cortex®-M0+ core and operates at up to 72 MHz with a wide voltage range. It integrates up to 256 KB Flash and 32 KB SRAM, available in multiple package options. The device integrates multi-channel I²C, SPI, USART, LPUART and other communication peripherals. It has one 12-bit ADC, one DAC, 14 timers, two comparators, one operational amplifier, and one LCD driver.

The PY32T090 microcontrollers operate across a temperature range of -40 to 105°C and a standard voltage range of 1.8 to 5.5 V, provides Low-power run, Sleep, Low-power sleep, Stop0/1/2/3 and Standby low-power operating modes, which can meet different low-power applications.

The PY32T090 series feature excellent touch and control characteristics. Coupled with its outstanding anti-interference performance, it can be adapted to touch buttons and main control in various solutions. Its applications span smart appliances, IoT, wireless communication, gaming devices, industrial controls, and consumer electronics.

Table 1-1 PY32T090 series product features and peripheral counts

| Peripherals | PY32T090R2CT7 | PY32T090R2BU7 | PY32T090C1CT7 | PY32T090C1BT7 | PY32T090S1CT7 | PY32T090S1BT7 | PY32T090K1BT7 | PY32T090G5CS7 | PY32T090G5BS7 |
|---------------------------|--------------------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|---------------|
| Flash (KB) | 256 | 128 | 256 | 128 | 256 | 128 | 128 | 256 | 128 |
| SRAM (KB) | 32 | 16 | 32 | 16 | 32 | 16 | 16 | 32 | 16 |
| Timers | Advanced control | 1 (16-bit) | | | | | | | |
| | General purpose | 4 (16-bit) | | | | | | | |
| | | 1 (32-bit) | | | | | | | |
| | Basic | 2 | | | | | | | |
| | PWM | 1 | | | | | | | |
| | Low power | 2 | | | | | | | |
| | SysTick | 1 | | | | | | | |
| Watchdog | 2 | | | | | | | | |
| Comm. Interfaces | SPI[I ² S] | 2[2] | | | | | | | |
| | I ² C | 2 | | | | | | | |
| | USART | 2 | | | | | | | |
| | UART | 2 | | | | | | | |
| | LPUART | 2 | | | | | | | |
| DMA | 7ch | | | | | | | | |
| RTC | Yes (perpetual calendar) | | | | | | | | |
| GPIOs | 62 | 62 | 46 | 46 | 42 | 42 | 30 | 26 | 26 |
| ADC (external + internal) | 1 (25+5) | 1 (25+5) | 1 (21+5) | 1 (21+5) | 1 (20+5) | 1 (20+5) | 1 (17+5) | 1 (13+5) | 1 (13+5) |
| DAC (number of channels) | 1(1) | | | | | | | | |
| Comparators | 2 | | | | | | 1 | 2 | |
| OPA | 1 | | | | | | | | |
| LCD (COM*SEG) | 8*36/4*40 | 8*36/4*40 | 8*26/4*30 | 8*26/4*30 | 8*23/4*27 | 8*23/4*27 | 5*16 | - | |
| Touch key | 33 | 33 | 25 | 25 | 23 | 23 | 19 | 22 | |
| Max. CPU frequency | 72 MHz | | | | | | | | |
| Operating voltage | 1.8 to 5.5 V | | | | | | | | |
| Operating temperature | -40 to 105 °C | | | | | | | | |
| Packages | LQFP64 | QFN64 | LQFP48 | | LQFP44 | | LQFP32 | SOP28 | |

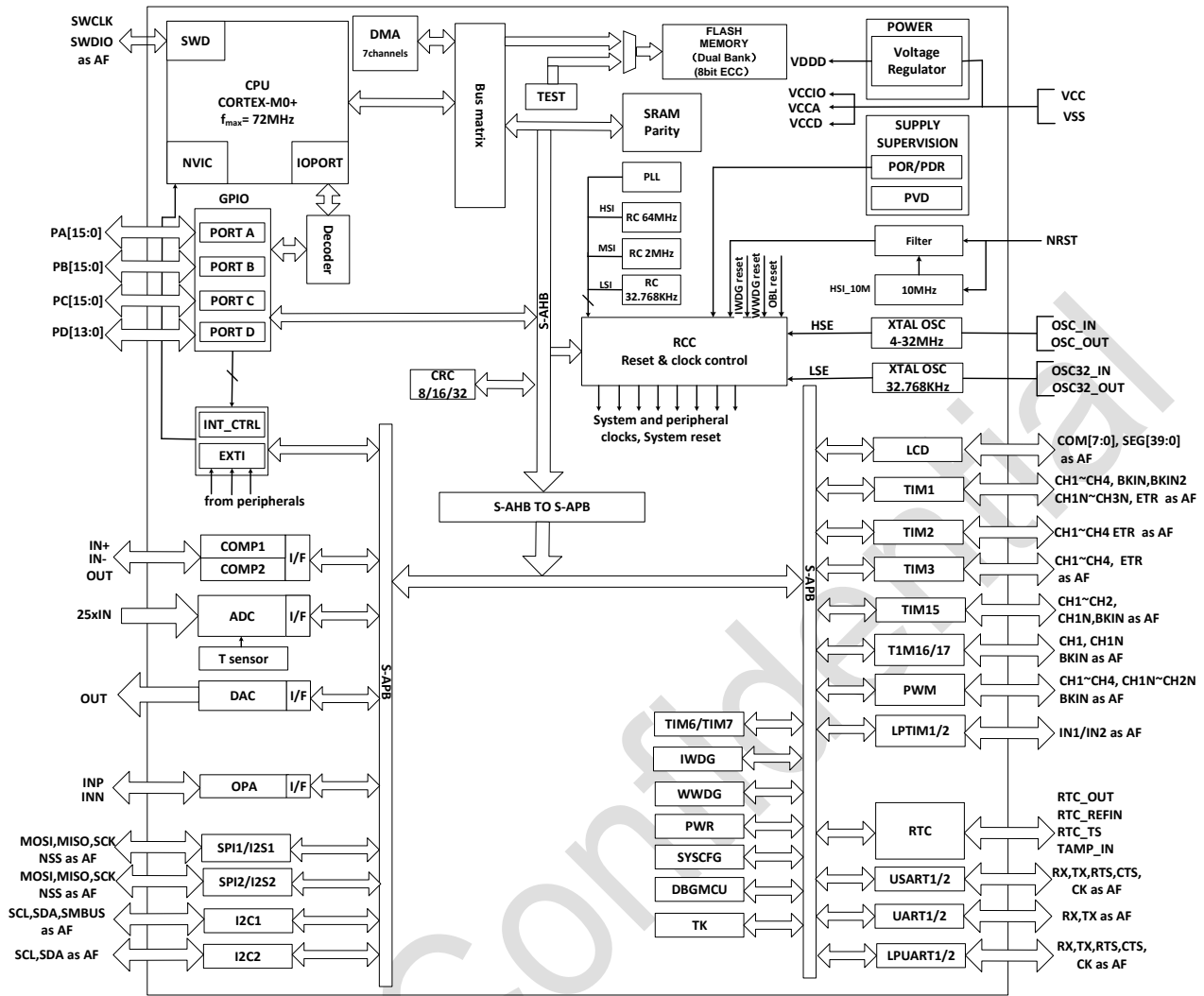


Figure 1-1 System block diagram

2. Functional overview

2.1. Arm® Cortex®-M0+ core

The Arm® Cortex®-M0+ is an entry-level Arm 32-bit Cortex processor designed for embedded systems. It provides developers with significant benefits, including:

- Simple architecture for easy learning and programming
- Ultra-low power consumption for energy-efficient operation
- Reduced code density

The Arm® Cortex®-M0+ processor is a 32-bit core optimized for area and power consumption and is a 2-stage pipeline Von Neumann architecture. It delivers high performance through a streamlined instruction set and hardware enhancements like a single-cycle multiplier. Outperforms 8/16-bit MCUs in code efficiency.

The Arm® Cortex®-M0+ is tightly coupled with a nested vectored interrupt controller (NVIC).

2.2. Memories

Embedded SRAM is accessed by byte (8 bits), half-word (16 bits) or word (32 bits) and supports write protection and byte parity check.

Embedded Flash, including 8-bit-Flash ECC, contains two different physical areas:

- Main flash area supports dual-bank structure for application/user data
- 8 KB of Information area:
 - User data
 - Parameter bytes
 - Option bytes
 - UID bytes
 - System memory

The protection of Main flash area includes the following mechanisms:

- Read protection (RDP) blocks external access
- Write protection (WRP) prevents unintended writes (caused by confusion of program). The minimum protection unit for write protection is 8 KB.
- Option byte write protection is a special design for unlock.
- proprietary code read out protection (PCROP)

The integrated error correction code (ECC) in Flash supports:

- 1-bit error detection and correction
- 2-bit errors detection

2.3. Boot modes

At startup, the BOOT0 pin and boot selector option bit nBOOT1 are used to select one of the four boot options in the following table:

Table 2-1 Boot mode configuration

| BOOT_LOCK | Boot modes | | Mode |
|-----------|------------|-----------|-----------------------------|
| | nBOOT1 bit | BOOT0 pin | |
| 1 | X | X | Forced Boot from Main flash |
| 0 | X | 0 | Boot from Main flash |
| 0 | 1 | 1 | Boot from System memory |
| 0 | 0 | 1 | Boot from SRAM |

The Boot loader is located in the System memory and is used to reprogram the Flash memory by using USART.

2.4. Flash accelerator (ACC)

In order to utilize the full performance of the processor, the gas pedal will implement instruction prefetch queuing and branch caching, thus increasing the speed of program execution in Flash. According to CoreMark benchmarks, the performance obtained by this gas pedal needs to reach the equivalent of Flash executing the program with wait cycles at CPU frequencies up to 72 MHz.

- Command prefetch
- The instruction cache supports 32 branch entries with a 64-bit data bus width
- The data cache supports 2 branches with a 64-bit data bus width

2.5. Clock management

System clock selection is performed on startup, however the internal RC 8 MHz oscillator is selected as default CPU clock on reset. After the program is operating the system clock frequency and system clock source can be reconfigured. The frequency clocks that can be selected are:

- An 8/16/24/48/64 MHz internal high-precision configurable HSI clock
- A 2 MHz internal high-precision MSI clock
- A 32.768 kHz configurable LSI clock
- A 4 to 32 MHz HSE clock, and used to enable the CSS function to detect HSE. If CSS fails, the hardware will automatically convert the system clock to HSI, and software configures the HSI frequency. Simultaneously, CPU NMI interrupt is generated.
- A 32.768 kHz LSE clock, and used to enable the CSS function to detect LSE. If CSS fails, the hardware will automatically convert the system clock to LSI, and software configures the LSI frequency. Simultaneously, CPU NMI interrupt is generated.
- PLL clock has HSI or HSE source. If the HSE source is selected, when CSS is enabled and CSS fails, the PLL and HSE will be turned off, and the hardware selects the system clock source as HSI.

The AHB clock can be divided based on the system clock, and the APB clock can be divided based on the AHB clock. The maximum frequency of the AHB and the APB domains is 72 MHz.

2.6. Power management

2.6.1. Power block diagram

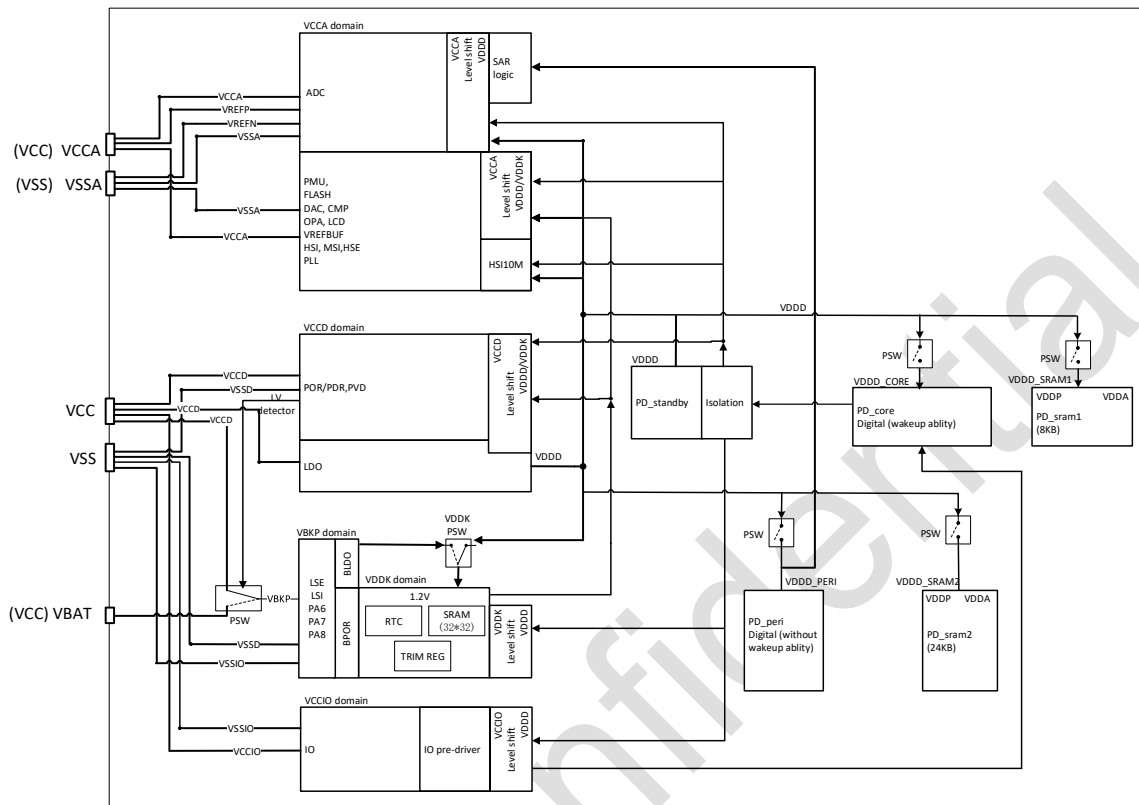


Figure 2-2 Power block diagram

Table 2-2 Power block diagram

| No. | Power supply | Value | Descriptions |
|-----|-------------------|--------------|---|
| 1 | V _{CC} | 1.8 to 5.5 V | The power is supplied to the device through the power pins, with the power supply module comprising: Partial analog circuits |
| 2 | V _{CC} | 1.8 to 5.5 V | Powers for most analog modules, sourced from the V _{CC} PAD (a dedicated power PAD can also be designed separately). |
| 3 | V _{REFP} | 1.8 to 5.5 V | Reference voltage for ADC and DAC |
| 4 | V _{DD} | 1.2 V | VR supplies power to the main logic circuits (CPU, bus, RCC, PWR and peripheral IPs) and SRAM inside the device. When the MR is powered, it outputs 1.2 V. According to the software configuration, when entering the Stop or Standby mode it powered by MR, LPR and DLPR. |

2.6.2. Power monitoring

2.6.2.1. Power-on reset /power-down reset (POR/PDR)

The Power-on reset (POR) and Power-down reset (PDR) module is designed to provide power-on and power-down reset for the device. The module keeps working in all modes.

2.6.2.2. Brown-out reset (BOR)

In addition to POR/ PDR, BOR (Brown-out reset) is also implemented. BOR can only be enabled and disabled through the option byte.

When the BOR is turned on, the BOR threshold can be selected by the option byte.

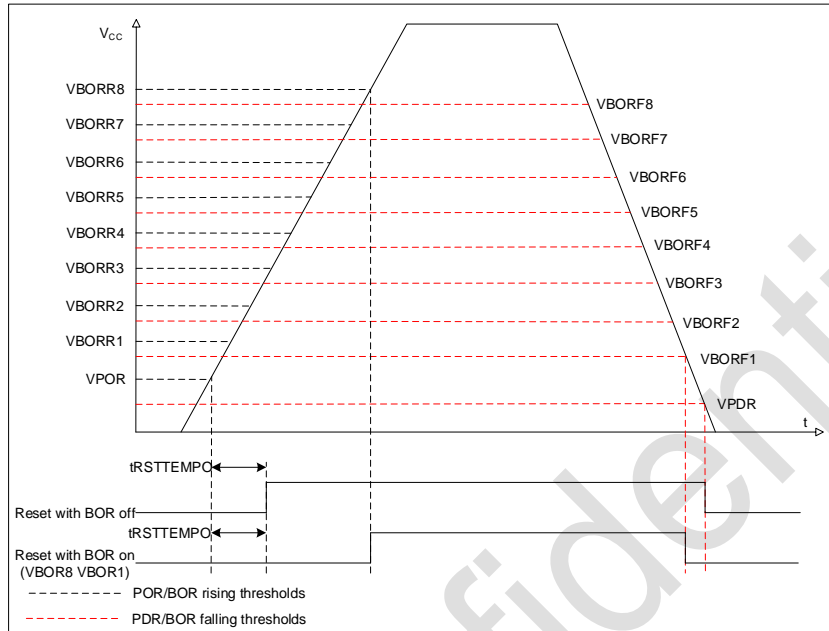


Figure 2-3 POR/PDR/BOR threshold

2.6.2.3. Programmable voltage detector (PVD)

Programmable voltage detector (PVD) module can be used to detect the V_{CC} power supply and the detection point is configured through the register. When V_{CC} is higher or lower than the detection point of PVD, the corresponding reset flag is generated.

This event is internally connected to line 16 of EXTI, depending on the rising/falling edge configuration of EXTI line 16, when V_{CC} rises above the detection point of PVD, or V_{CC} falls below the detection point of PVD, an interrupt is generated. In the service program, users can perform urgent shutdown tasks.

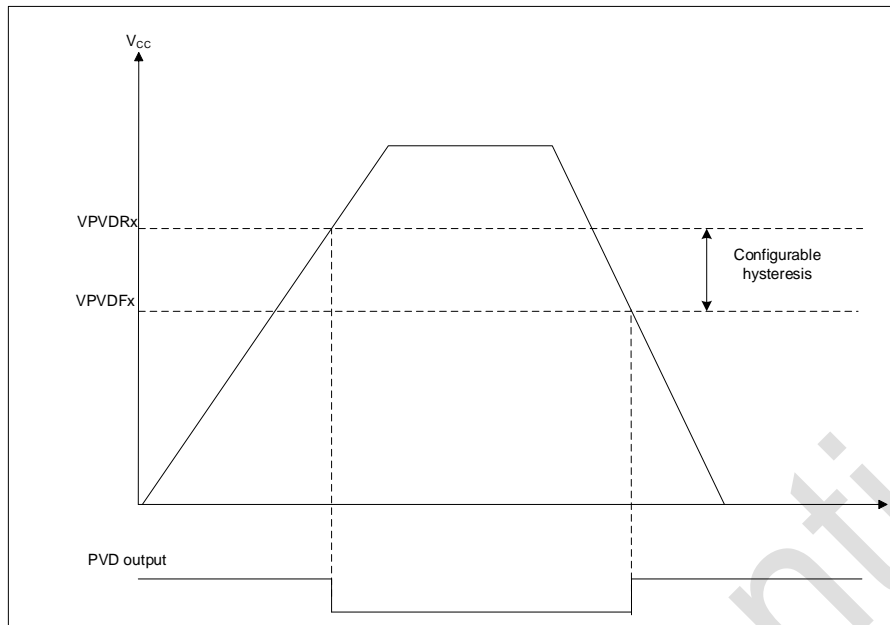


Figure 2-4 PVD threshold

2.6.3. Voltage regulator

The regulator has three operating modes:

- Main regulator (MR) is used in normal operating mode (Run).
- Low power regulator (LPR) provides an option for even lower power consumption in low power mode.
- Deep low power regulator (DLPR) ensures the lowest power consumption in low power mode.

2.6.4. Low-power mode

In addition to the normal operating mode, there are five low-power modes:

- Sleep mode: Peripherals can be configured to keep working when the CPU clock is off (NVIC, SysTick, etc.). It is recommended only to enable the modules that must work, and close the module after the module works.
- Low-power run mode: The Max. CPU frequency is 2 MHz and the voltage regulator operates in low-power mode to save energy.
- Low-power sleep mode: entered only from Low-power run mode and CPU core clock is turned off. The system returns to Low-power run mode when awakened by an event or interrupt.
- Stop0/Stop1/Stop2/Stop3 modes: SRAM and register contents are retained. Clocks (PLL, HSI, MSI, HSE) and most module clocks in the V_{DD} domain are disabled. Specific modules can be configured to power down. Wake-up sources: GPIO, PVD, COMP, LPUART, I²C, IWDG, TK, RTC, TAMP and LPTIM.
- Standby mode: partial digital logic and SRAM in the V_{DD} domain are powered off. Exit conditions: External reset via NRST, IWDG reset, RTC alarm wakeup, and valid edge on the WKUP pin.

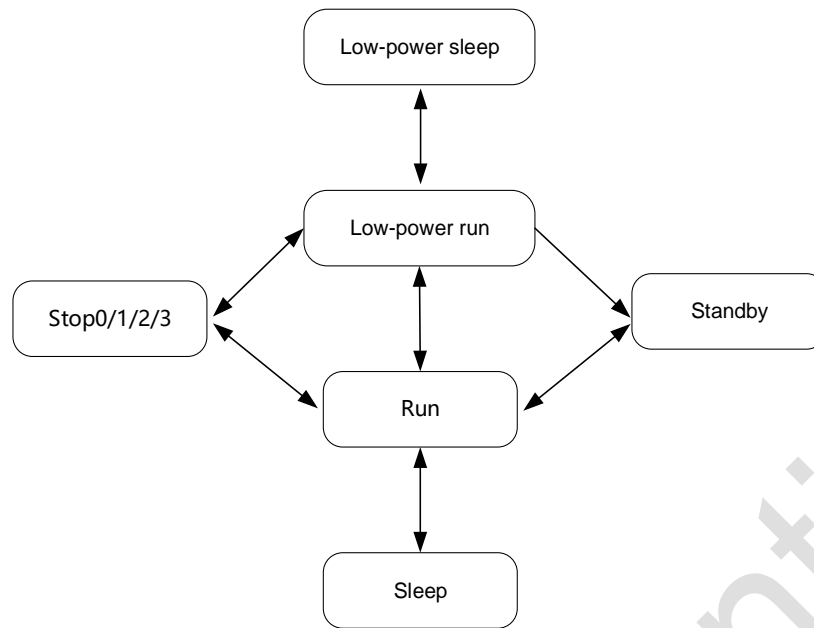


Figure 2-5 Power consumption state transition diagram

2.7. Reset

Two resets are designed in the device: power reset and system reset.

2.7.1. Power reset

A power reset occurs in the following situations:

- Power-on/power-down reset (POR/PDR)
- Brown-out reset (BOR)

2.7.2. System reset

A system reset occurs when the following events occur:

- Reset of NRST pin
- Window watchdog reset (WWDG)
- Independent watchdog reset (IWDG)
- SYSRESETREQ software reset
- Option byte load reset (OBL)

2.8. General-purpose inputs/outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (floating, pull-up or pull-down and analog) or as peripheral alternate function. The I/O configuration can be locked if needed following a specific sequence in order to avoid spurious writing to the I/Os registers. GPIO features are summarized as follows:

- Support read/write operations via IO Port or AHB bus
- Output states: push-pull or open drain + pull-up/down
- Output data from output data register (GPIOx_ODR) or peripheral (alternate function output)
- Speed selection for each I/O

- Input states: floating, pull-up/down, and analog
- Input data to input data register (GPIOx_IDR) or peripheral (alternate function input)
- Bit set and reset register (GPIOx_BSRR) for bitwise write access to GPIOx_ODR
- Locking mechanism (GPIOx_LCKR) provided to freeze the I/O port configurations
- Analog function
- Alternate function selection registers (Max. 16 alternate functions for each IO)
- Fast toggle capable of changing every clock cycles
- Highly flexible pin multiplexing allows the use of I/O pins as GPIOs or as one of several peripheral functions

2.9. Direct memory access controller (DMA)

Direct memory access (DMA) is used to provide a high-speed data transfer between peripherals and memory as well as from memory to memory. Data can be quickly moved by DMA without any CPU actions. This keeps the CPU resources free for other operations. The DMA controller have 7 channels in total, each one dedicated to manage memory access requests from one or more peripherals. Each controller has an arbiter for handling the priority between DMA requests.

The DMA supports:

- 7 configurable channels
- Each channel is associated either with a DMA request signal coming from a peripheral, or with a software trigger in memory-to-memory transfers. This configuration is done by software.
- Priority between multiple requests on the same DMA module is software-programmable. For equal priorities, hardware resolves conflicts (lower channel number = higher priority).
- The transfer sizes of the source and destination are independent (byte, half word and word), simulating packing and unpacking. Source and destination addresses must be aligned to the transfer width.
- Programmable address modes: Up, down, or fixed
- Each channel has 4 event flags: transfer complete (circular mode), block transfer, half-block transfer and transfer error. They are logically ORed to generate a single interrupt request.
- Support transfers between memory to memory, peripheral to memory, memory to peripheral and peripheral to peripheral
- SRAM, APB and AHB peripherals can act as source or destination. Flash can only act as a source.
- Support single-trigger mode and four circular modes:
 - Peripheral address retained, memory address retained
 - Peripheral address reloaded, memory address retained
 - Peripheral address retained, memory address reloaded
 - Both addresses reloaded
- Single-trigger mode: Programmable transfer count (0 to 65,535)

- Circular mode: Infinite looping or finite looping (1 to 255 cycles)
- Support single transfer and bulk transfer
 - Single transfer: Generates 1 ACK per data transfer
 - Bulk transfer: Generates 1 ACK after all configured data is transferred (bus released post-completion).
- Two transfer modes
 - Fast mode: Holds the bus until all data is transferred
 - Round-robin mode: Releases the bus after each transfer for re-arbitration
- Support pausing transfers upon entering the block transfer Complete interrupt in circular mode.

2.10. Interrupts and events

The PY32T090 handles exceptions through the Cortex-M0+ processor's embedded a nested vectored interrupt controller (NVIC) and an extended interrupt/event controller (EXTI).

2.10.1. Nested vectored interrupt controller (NVIC)

NVIC is a tightly coupled IP inside the Cortex-M0+ processor. The NVIC can handle non-maskable interrupts (NMI) and maskable external interrupts from outside the processor and Cortex-M0+ internal exceptions. NVIC provides flexible priority management.

The tight coupling of the processor core to the NVIC greatly reduces the delay between an interrupt event and the initiation of the corresponding interrupt service routine (ISR). The ISR vectors are listed in a vector table, stored at a base address of the NVIC. The vector table base address determines the vector address of the ISR to execute, and the ISR is used as the offset composed of serial numbers.

If a higher-priority interrupt event occurs and a lower-priority interrupt event is just waiting to be serviced, the later-arriving higher-priority interrupt event will be serviced first. Another optimization is called tail-chaining. When returning from a higher-priority ISR and then starting a pending lower-priority ISR, unnecessary pushes and pops of processor contexts will be skipped. This reduces latency and improves power efficiency.

NVIC features:

- Low latency interrupt handling
- Level 4 interrupt priority
- Support 1 NMI
- Support 32 maskable external interrupts
- High-priority interrupts can interrupt low-priority interrupt responses
- Support tail-chaining optimization
- Hardware interrupt vector retrieval

2.10.2. Extended interrupt/event controller (EXTI)

EXTI adds flexibility to handle physical wire events and generates wake-up events by GPIO and modules (PVD, COMP, RTC, TAMP, I²C, LPUART, TK and LPTIM).

The EXTI controller has multiple channels, including up to 62 GPIOs multiplexed using 16 EXTI lines, one PVD output, two COMP outputs, two LPUART signals, two I²C, two LPTIM wake-up signals, TK, RTC, TAMP and LSE CSS signal. GPIO, PVD and COMP can be configured to be triggered by a rising edge, falling edge or double edge. Any GPIO signal can be configured as EXTI0 to 15 channel through the select signal.

- Each EXTI line can be independently masked through registers.
- The EXTI controller can capture pulses shorter than the internal clock period.
- Registers in the EXTI controller latch each event. Even in Stop mode, after the processor wakes up from Stop mode, it can identify the wake-up source or identify the GPIO and event that caused the interrupt.

2.11. Analog-to-digital converter (ADC)

The PY32T090 has a 12-bit SARADC. The module has a total of up to 30 channels to be measured, including 25 external and 5 internal channels, including 3 pairs of differential channels.

The internal channels are: T_{S_VIN} , V_{REFINT} , $V_{CC}/3$, OPA and DAC.

- A/D conversion of the various channels can be performed in single, continuous, or discontinuous mode. The result of the ADC is stored in a left-aligned or right-aligned 16-bit data register.
- The analog watchdog feature allows the application to detect if the input voltage goes outside the user-defined higher or lower thresholds.
- Interrupt generation at ADC ready, the end of sampling, the end of conversion, end of sequence conversion, analog watchdog or overrun events
- The ADC is configurable with 12/10/8/6-bit resolutions.
- Maximum ADC sampling rate: 2 MSPS
- Support self-calibration (initiated by software)
- Support programmable sampling time
- The data register allows configurable data alignment
- Support DMA requests for regular channel data conversion
- Support configurable conversion of 16 regular channels
- Support configurable conversion of 4 injected sequences
- The oversampling is equipped with a 16-bit data register. The oversampling rate can be adjusted from 2 to 256, and the programmable data shift can reach up to 8 bits.
- Data processing supports gain compensation and offset compensation.

2.12. Digital-to-analog converter (DAC)

The two 12-bit buffered DAC channels can be used to convert digital signals into analog voltage signal outputs. The DAC can be configured in 8-bit or 12-bit mode, or can be used in conjunction with a DMA controller. When the DAC is operating in 12-bit mode, the data can be left justified or right justified. The DAC module has one output channel. The main features are as follows:

- Left or right data alignment in 12-bit mode
- Synchronized update capability
- Noise-wave generation
- Triangular-wave generation
- DMA support for each channel
- Support DMA underflow error detection
- External triggers for conversion
- Input reference voltages: V_{CC} , V_{REFP} , and V_{REFBUF}
 - The V_{REFBUF} of the DAC only supports 2.5 V

2.13. Comparators (COMP)

The PY32T090 integrates two general-purpose comparators (COMP), namely COMP1 and COMP2. The COMP1/2 module can be used as a separate module or in combination with timer.

The COMP features:

- Triggered by analog signal to wake-up function from low-power mode
- Analog signal conditioning
- Cycle by cycle current control loop when comparators are connected with PWM output from timer
- Voltage comparison function is supported. Each comparator has configurable positive or negative input for flexible voltage selection:
 - Multiple I/O pins
 - 64 steps voltage of V_{CC}/V_{REFBUF}
 - Temperature sensor output
 - DAC output
 - OPA output
 - V_{REFINT}
- Programmable speed and power consumption
- Programmable hysteresis function
- Write protection for configuration registers (LOCK function)
- The output can be triggered by a connection to the I/O or timer input
- Each COMP has interrupt generation capability and is used to wake up the device from low power mode (Sleep/Stop) (via EXTI)
- Provide software to configure the digital filtering time to enhance the anti-interference capability of the device
- Support output blanking to reduce switching noise
- Support the window comp function

2.14. Operational amplifier (OPA)

The OPA module can be flexibly configured and is suitable for simple amplifiers.

OPA features are summarized as follows:

- One independently configured operational amplifier
- The inputs can be individually configured to select from two channels, and the outputs can be configured to select from four IO channels. The outputs can be internally directed to the comparator and ADC.
- The input range of the OPA is from 0 to V_{CC} , and the output range is from 0.2 V to $V_{CC}-0.2$ V.
- Can be configured for the following models
 - General purpose OPA

2.15. Liquid crystal display controller (LCD)

The liquid crystal display (LCD) controller is a digital controller/driver for monochrome passive LCD, with up to 8 common terminals (COM) and 40 segment terminals (SEG) to drive 160 (4 * 40) or 288 (8 * 36) LCD pixels. The exact number of terminals depends on the device pins described in the data manual. LCD functions are summarized as follows:

- Highly flexible frame rate control
- Support static, 1/2, 1/3, 1/4, 1/6, and 1/8 duty cycle
- Support 1/2, 1/3 and 1/4 bias voltage
- Supported display modes: Type A or Type B
- Three ways to generate driving waveforms: internal resistor voltage division, external resistor voltage division, and external capacitor voltage division
 - With internal resistor voltage division, power consumption can be reduced by using software to configure the conduction time of the internal high-drive voltage-dividing resistors, thus matching the capacitance charge required by the LCD panel. The contrast of the LCD can also be configured via software to adjust the brightness of the LCD panel
 - For external resistor voltage division, the capacitance charge required by the LCD panel can be matched by adjusting the resistance value of the external resistors
 - In the case of external capacitor voltage division, the capacitance charge required by the LCD panel can be matched by using software to configure the number of capacitor driving times
- Support LCD flashing function and configuration of multiple flicker frequency configuration
- Support the configurable LCD dead time function to adjust the display brightness
- Unused LCD segments and public pin can be configured to digital or analog functions
- Up to 16 registers LCD data RAM
- Dual buffer memory allows the data in the LCD_RAM registers to be updated at any time through the application firmware without affecting the integrity of the displayed data

- Support low power modes: The LCD controller can perform display operations in Run, Low-power run, Sleep, Low-power sleep, and Stop modes
- Configurable frame interrupt

2.16. Touch key

The PY32T090 integrates a 33 channel capacitive touch circuit:

- Optional internal/external CMOD capacitor, no external capacitor needed for internal use
- High-sensitivity for non-contact touch
- 10 V dynamic CS test-passed anti-interference mode
- Support the frequency hopping function
- Support the waterproof compensation function
- Support multi-channel parallel connection
- Supports touch low power mode (Stop3 mode)

2.17. Timers

The different timers feature as blow:

Table 2-3 Timer characteristics

| Timer type | Timers | Counter resolution | Counter type | Prescaler | DMA | Capture/compare channels | Complementary outputs |
|------------------|--------------|--------------------|---------------------|------------|-----|--------------------------|-----------------------|
| Advance control | TIM1 | 16-bit | up, down up/down | 1 to 65536 | Yes | 4 | 3 |
| General purpose | TIM2 | 32-bit | up, down up/down | 1 to 65536 | Yes | 4 | - |
| | TIM3 | 16-bit | up, down up/down | 1 to 65536 | Yes | 4 | - |
| | TIM15 | 16-bit | Up | 1 to 65536 | Yes | 2 | 1 |
| | TIM16, TIM17 | 16-bit | Up | 1 to 65536 | Yes | 1 | 1 |
| Basic | TIM6 | 32-bit | Up | 1 to 65536 | Yes | - | - |
| | TIM7 | 16-bit | Up | 1 to 65536 | Yes | - | - |
| Dedicated timers | PWM | 16-bit | up, down up/down | 1 to 65536 | Yes | 4 | 2 |

2.17.1. Advanced-control timer (TIM1)

The advanced-control timer (TIM1) is consist of a 16-bit auto-reload counter driven by a programmable prescaler. It can be used in various scenarios, including pulse length measurement of input signals (input capture) or generating output waveforms (output compare, output PWM, complementary PWM with dead-time insertion).

The four independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge or center-aligned mode)

- Single pulse mode output
- Support incremental (quadrature) encoders and Hall sensor circuits for positioning.

If configured as a standard 16-bit timer, it has the same features as the TIMx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0 to 100%).

The counter can be frozen in debug mode.

Many features are shared with those of the standard timers which have the same architecture. The advanced control timer can therefore work together with the other timers by the Timer Link feature for synchronization or event chaining.

TIM1 supports the DMA function.

2.17.2. General-purpose timers

2.17.2.1. TIM2/TIM3

The general-purpose timers TIM2/TIM3 are consist of 32/16-bit auto-reload counters and a 32/16-bit prescaler. There are four independent channels each for input capture/output compare, PWM or one-pulse mode output.

- They can work with the TIM1 by the timer link
- Support DMA function
- The counter can be frozen in debug mode

2.17.2.2. TIM15/TIM16/TIM17

- The general-purpose timer (TIM15, TIM16 and TIM17) is consist of a 16-bit auto-reload counter driven by a programmable prescaler.
- TIM15 features two single channel for input capture/output compare, PWM or one-pulse mode output.
- TIM16/TIM17 features one single channel for input capture/output compare, PWM output.
- TIM15/TIM16/TIM17 have complementary outputs with dead time.
- TIM15/TIM16/TIM17 support DMA function.
- The counter can be frozen in debug mode.

2.17.3. Basic timers (TIM6/TIM7)

- The basic timer TIM6 is consist of a 32-bit auto-reload upcounter driven by their programmable prescaler respectively.
- The basic timer TIM7 is consist of a 16-bit auto-reload upcounter driven by their programmable prescaler respectively.
- 16-bit / 32-bit auto-reload upcounter
- Generate interrupt/DMA request on update event (counter overflow).

2.17.4. PWM dedicated timer

This module can generate a pulse width modulation (PWM) signal with a frequency and duty cycle determined by registers. Support external clock counting, and the frequency can exceed the PCLK frequency.

- A 16-bit up, down, or up/down auto-reload counter
- A programmable prescaler that allows the clock frequency of the counter to be divided from 1 to 65,536
- Support write protection for important registers
- Up to 4 independent channels
- Support complementary outputs with programmable dead time for 2 channels.
- Support 1 brake input
- Support DMA function

2.17.5. Low power timer (LPTIM)

LPTIM1/LPTIM2 are 32-bit/16-bit timers. The ability of LPTIM to wake the system from low-power modes makes it suitable for practical low-power applications. LPTIM introduces a flexible clock scheme that can provide the required functionality and performance while minimizing power consumption.

- LPTIM1 is a 32-bit and LPTIM2 is a 16-bit up-counter
- It has a 3-bit prescaler with 8 possible division factors (1, 2, 4, 8, 16, 32, 64, 128)
- Optional clocks include LSE, LSI, APB clock
- Support single-shot and continuous modes
- Support software/hardware input triggering
- The counter can be frozen in debug mode

2.17.6. Independent watchdog (IWDG)

Independent watchdog (IWDG) is integrated in the device, and this module has the characteristics of high-security level, accurate timing and flexible use. IWDG finds and resolves functional confusion due to software failure and triggers a system reset when the counter reaches the specified timeout value.

- The IWDG is clocked by LSI or LSE and can work in Stop and Standby mode.
- IWDG is the best suited for applications that require the watchdog as a standalone process outside of the main application and do not have high timing accuracy constraints.
- Controlling of option byte can enable IWDG hardware mode.
- IWDG is the wake-up source of Stop mode, which wakes up Stop mode and Standby mode by reset.
- The counter can be frozen in debug mode.

2.17.7. System window watchdog (WWDG)

The system window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the APB clock (PCLK). It has an early warning interrupt capability, and the counter can be frozen in debug mode.

2.17.8. SysTick timer

SysTick timer is dedicated to real-time operating systems (RTOS), but could also be used as a standard down counter.

SysTick features:

- A 24-bit down counter
- Auto-reload capability
- Maskable system interrupt generation when the counter reaches 0

2.18. Real-time clock (RTC)

The real-time clock (RTC) is an independent timer that provides an automatic wake-up unit for managing all low-power modes. It is an independent binary-coded decimal (BCD) timer/counter, offering a calendar clock/calendar with programmable alarm interrupt functionality. As long as the power supply voltage remains within the operating range, the RTC will continue to operate regardless of the device's state (run mode, low-power mode, or in reset). The calendar includes subseconds, seconds, minutes, hours (12 or 24 format), day week day, date, month and year, presented in BCD format

- Automatic correction for 28, 29 (leap year), 30, and 31 day of the month
- Two programmable alarms
- Allow in runtime correction of 1 to 32,767 RTC clock pulses for synchronization with the main clock.
- Supports reference clock detection: enable the use of a more accurate secondary clock source (50 or 60 Hz) to enhance calendar accuracy
- Equipped with a digital calibration circuit having a resolution of 0.95 ppm to compensate for quartz crystal oscillator errors.
- Time stamp feature which can be used to save the calendar content. This function can be triggered by an event on the timestamp pin, or by a tamper event.
- Comes with a 17-bit auto-reload wake-up timer (WUT) for periodic events, with programmable resolution and period.
- The following three RTC clock sources can be selected:
 - HSE clock divided by 32
 - LSE clock
 - LSI clock
- Three dedicated maskable interrupts:
 - Alarm interrupt

- Timestamp interrupt
- Wake-up timer interrupt

2.19. Cyclic redundancy check calculation unit (CRC)

CRC computing unit is based on a fixed generation polynomial to obtain CRC computing results. In other applications, CRC technology is mainly used to verify the correctness and integrity of data transmission or data storage. The CRC calculation unit contains a 32-bit data register:

- When writing to this register, it serves as an input register, allowing you to input new data for CRC calculation
- When reading from this register, it returns the result of the previous CRC calculation
- Each time data is written to the register, the calculation result is a combination of the previous CRC calculation result and the new one (CRC calculation is performed on the entire 32-bit word rather than byte by byte)
- You can reset the register CRC_DR to 0xFFFFFFFF by setting the RESET bit in the register CRC_CR. This operation does not affect the data in the register CRC_IDR
- Support configuration of the initial CRC value
- Support configuration of the CRC polynomial
- Support inverting the input data in units of 8/16/32 bits
- Support output inversion
- The input data bit width supports 8/16/32 bits.
- The polynomial bit width can be configured as 7/8/16/32 bits, which is equivalent to the bit width of the output data

2.20. System configuration controller (SYSCFG)

The SYSCFG module provides the following functions:

- Enable and disable IO filter
- Enable and disable I²C Fast mode plus
- Mapping the initial program area according to different boot modes
- DMA peripheral channel selection control
- Analog input channel enable
- Analog PAD2 enable
- Enable and disable Noise filter for all GPIOs
- Enable and disable PVD Lock
- Enable and disable Cortex-M0+ LOCKUP
- Enable and disable ECC Lock
- Enable and disable SRAM parity check
- LED IO control

2.21. Debug support (DBG)

The MCU DBG module assists the debugger with the following functions:

- Support Sleep, Stop and Standby mode
- When the CPU enters the HALT mode, the control timer or watchdog stops counting or continues counting
- Block I²C1 and I²C2 SMBUS timeouts when the CPU is in HALT mode

The MCUIDBG register also provides device ID encoding. This ID encoding can be accessed by a SW debug interface, or by a user program.

2.22. Inter-integrated circuit interface (I²C)

The I²C bus interface handles communications between the microcontroller and the serial I²C bus. It can controls all I²C bus-specific sequencing, protocol, arbitration and timing. It supports Standard-mode (Sm), Fast-mode (Fm) and Fast-mode plus (Fm+).

I²C features:

- Two I²C interface
- Can be master or slave
- Support different communication speeds
 - Standard mode (Sm): up to 100 kHz
 - Fast mode (Fm): up to 400 kHz
 - Fast mode plus (Fm+): up to 1 MHz
- As Master
 - Generate clock
 - Generate start and stop
- As Slave
 - Programmable I²C address detection
 - Dual-address capability that responds to two secondary addresses
 - Discovery of the STOP bit
- 7-bit/10-bit addressing mode
- General call
- Status flag
 - Transmit/receive mode flags
 - Byte transfer complete flag
 - I²C busy flag bit
- Error flag
 - Master arbitration loss
 - ACK failure after address/data transfer

- Start/stop error
- Overrun/underrun (clock stretching function disable)
- Optional clock stretching
- Single-byte buffer with DMA capability
- Software reset
- Analog noise filter function
- Hardware packet error checking (PEC) generation and verification with ACK control
- Support SMBus
- Support low-power modes, wakes up from Stop mode on address matching.

2.23. Universal synchronous/asynchronous receiver transmitter (USART)

PY32T090 contains 2 USARTs and supports ISO7816, LIN and IrDA.

The USARTs provide a flexible method for full-duplex data exchange with external devices using the industry-standard NRZ asynchronous serial data format. The USART utilizes a fractional baud rate generator to provide a wide range of baud rate options.

It supports simultaneous one-way communication and half-duplex single-wire communication, and it also allows multi-processor communication.

High-speed data communication can be achieved by using the DMA method of the multi-buffer configuration.

To distinguish it from the UART described in Section 2.24, the term SCI is used in this section to refer to the asynchronous mode of the USART.

USART features:

- Full-duplex asynchronous communication(SCI)
- NRZ standard format
- Configurable 16 times or 8 times oversampling for increased flexibility in speed and clock tolerance
- Programmable baud rate shared by transmit and receive, up to 4.5 Mbit/s
- Automatic baud rate detection
- Programmable data length of 8 or 9 bits
- Configurable STOP bits (0.5, 1, 1.5 or 2 bits)
- Synchronous mode and clock output function for synchronous communication
- Single-wire half-duplex communication
- Independent transmit and receive enable bits
- Hardware flow control
- Receive/transmit bytes by DMA buffer
- Transfer detection flag

- Receive buffer full
- Send empty buffer
- End of transmission flags
- Parity control
 - Transmit parity bit
 - Check the received data byte
- Configurable Tx and Rx pin SWAP
- MSB First data transmission and reception format
- Support LIN master transmit sync break and slave detect break
 - Generates 13-bit break and detects 10/11-bit breaks when configured for LIN
- IRDA SIR encoder/decoder
 - Support a 3/16-bit duration in normal mode
- Smart card emulation function
 - Smart card interface supports ISO7816-3 asynchronous protocol
 - 0.5 and 1.5 STOP bits for the smart card
 - Configurable MSB or LSB transmission
 - The NACK signal width can be configured to 1/1.5/2 ETU
 - Support transmission error retransmit
 - Support an EGT setting from 0 to 256 and multiple timeout interrupts
- Flagged interrupt sources
 - CTS change
 - Transmit data register empty
 - Transmission complete
 - Receive data register full
 - Bus idle detected
 - Overflow error
 - Frame error
 - Noise operation
 - Error detection
- Multiprocessor communication
 - If the address does not match, enter silent mode
- Wake-up from silent mode: by idle detection and address flag detection

2.24. Universal asynchronous receivers/transmitter (UART)

The PY32T090 features two universal asynchronous receivers/transmitters (UARTs):

- Support 5/6/7/8/9-bit serial data

- Support 1/2 STOP bits (1/1.5 STOP bits for 5-bit data)
- Support sending address/data
- Support fixed parity check
- Support break frames
- Detect start bit errors
- Support programmable fractional baud rates
- Support Tx/Rx pin swapping
- Support MSB FIRST endianness switching
- Full-duplex asynchronous communication
- NRZ standard format
- Support DMA transmission
- Support 4-bit fractional baud

2.25. Low-power universal asynchronous receivers/transmitters (LPUART)

The PY32T090 integrates two LPUARTs, supporting wake-up from Sleep and Stop modes.

Features:

- Full-duplex asynchronous communication
- NRZ standard format
- Programmable baud rate
- 32.768 kHz clock with baud rate range 300-9600, higher rates need higher clock freq
- Dual clock domains: PCLK and dedicated kernel clock
- Programmable data word length (7/8/9 bits)
- Programmable data order with MSB-first or LSB-first shifting
- Configurable STOP bits (1/2 STOP bits)
- Single-wire half-duplex communications
- Support continuous DMA transfer
- Independent enable for transmission and reception
- Independent polarity control for Tx/Rx signals
- Interchangeable Tx/Rx pins
- Support hardware RS-485/modem flow control
- Parity control: generates parity bit on transmission, checks on reception
- Four error detection flags:
 - Overrun error
 - Noise error
 - Frame error

- Parity error
- Interrupt sources with flags:
 - CTS change
 - Transmit data register empty
 - Transmission complete
 - Receive data register full
 - Bus idle detected
 - Overflow error
 - Frame error
 - Noise operation
 - Error detection
 - Match address byte
- Support 5/6/7/8/9-bit serial data
- Support wake-up from Stop, Sleep, Low-power run, and Low-power sleep modes

2.26. Serial peripheral interface (SPI)

The PY32T090 contains two SPI/I²S module.

SPIs allow the device to communicate with external devices in half-duplex, full-duplex, and simplex synchronous serial communication. This interface can be configured in Master mode and provides the serial clock (SCK) for external slave devices. The interface can also work in a multi-master configuration.

The SPI features are as follows:

- Master or Slave mode
- Full-duplex synchronous transfers on three lines
- Half-duplex synchronous transfer on two lines (with bidirectional data line)
- Simplex synchronous transfers on two lines (with unidirectional data line)
- 8-bit or 16-bit transmission frame selection
- Support multi-master mode
- 8 Master mode baud rate prescalers (Max $f_{PCLK}/2$)
- Slave mode frequency (Max $f_{PCLK}/2$)
- Both Master and Slave modes can be managed by software or hardware NSS: dynamic change of Master/Slave operating mode
- Programmable clock polarity and phase
- Programmable data order with MSB-first or LSB-first shifting
- Dedicated transmission and reception flags with interrupt capability
- SPI bus busy status flag

- Support Motorola mode and TI mode
- Master mode fault, overrun flags with interrupt capability
- CRC Error flag
- Two embedded Rx and Tx FIFOs with DMA capability, depth of four, and width of 16 bits (8 bits when data frame is set to 8 bits)

I²S features:

- Half-duplex communication (only transmitter or receiver)
- Master or slave operations
- 8-bit programmable linear prescaler to reach accurate audio sample frequencies (from 8 kHz to 192 kHz)
- Data format may be 16-bit, 24-bit or 32-bit
- Packet frame is fixed to 16-bit (16-bit data frame) or 32-bit (16-bit, 24-bit, 32-bit data frame) by audio channel
- Programmable clock polarity (steady state)
- Underrun flag in slave transmission mode, overrun flag in reception mode (master and slave) and frame error flag in reception and transmitter mode (slave only)
- 16-bit register for transmission and reception with one data register for both channel sides
- Support I²S protocols:
 - I²S Phillips standard
 - MSB-justified standard (left-justified)
 - LSB-justified standard (right-justified)
 - PCM standard (with short and long frame synchronization on 16-bit channel frame or 16-bit data frame extended to 32-bit channel frame)
- Data direction is always MSB first
- DMA capability for transmission and reception
- Master clock may be output to drive an external audio component. Ratio is fixed at $256 \times f_s$ (where f_s is the audio sampling frequency)

2.27. Serial wire debug (SWD)

An ARM SWD interface allows serial wire debugging tools to be connected to the PY32T090.

3. Pinouts and pin descriptions

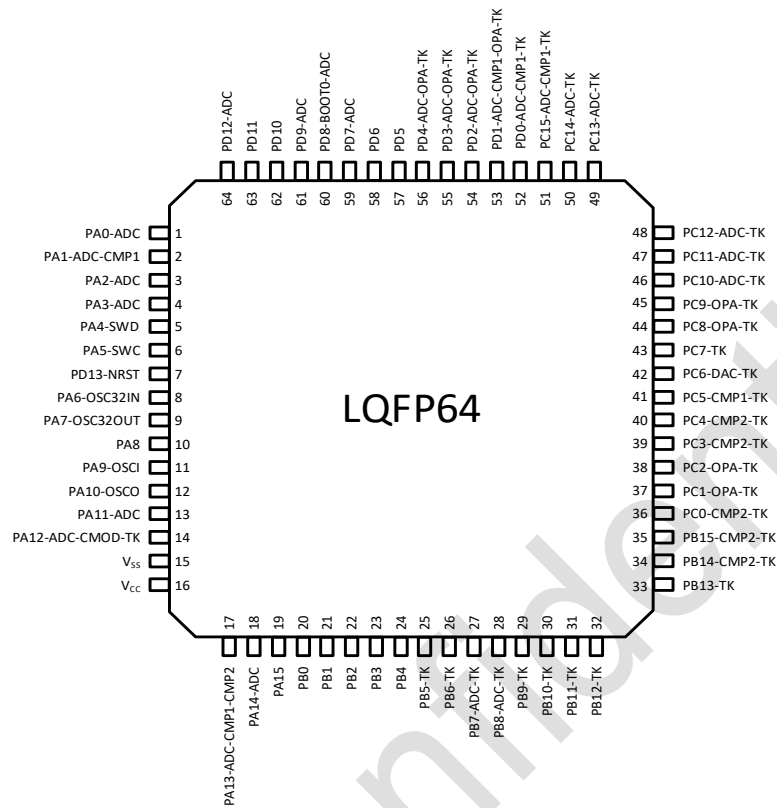


Figure 3-1 LQFP64 Pinout2 PY32T090R2xT7 (Top view)

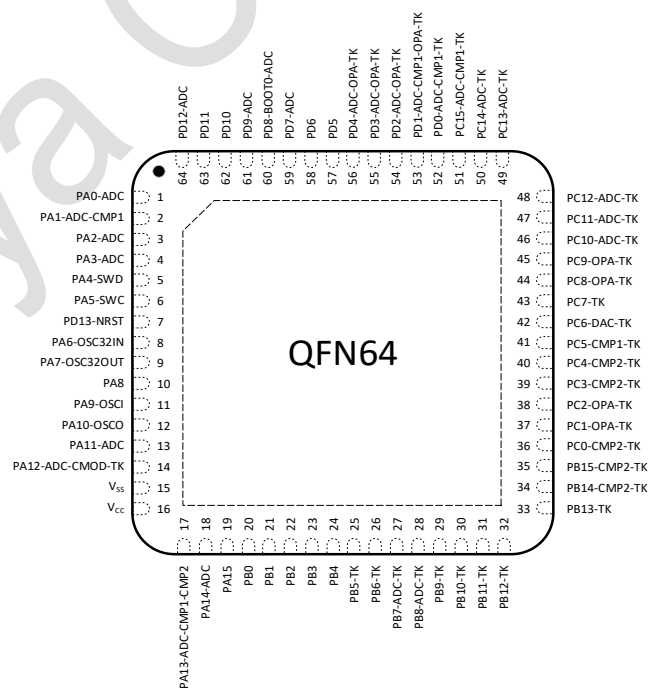


Figure 3-2 QFN64 PY32T090R2xU7-E Pinout2 (Top view)

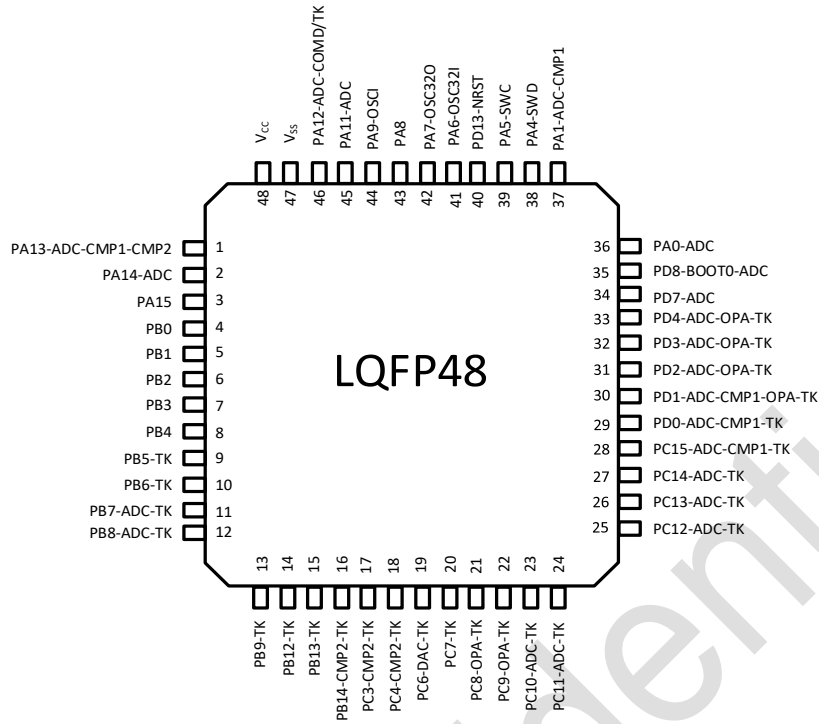


图 3-3 LQFP48 Pinout1 PY32T090C1xT7 (Top view)

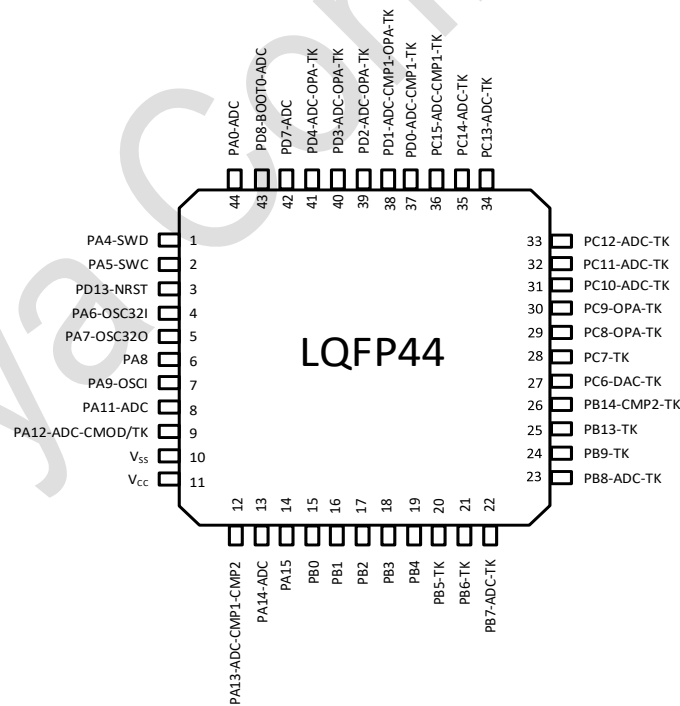


Figure 3-4 LQFP44 Pinout1 PY32T090S1xT7 (Top view)

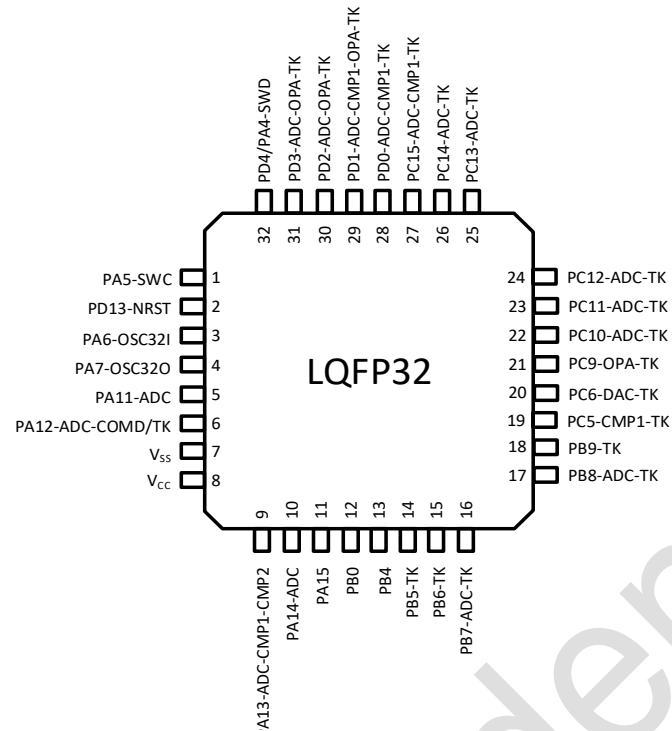


Figure 3-5 LQFP32 Pinout1 PY32T090K1xT7 (Top view)

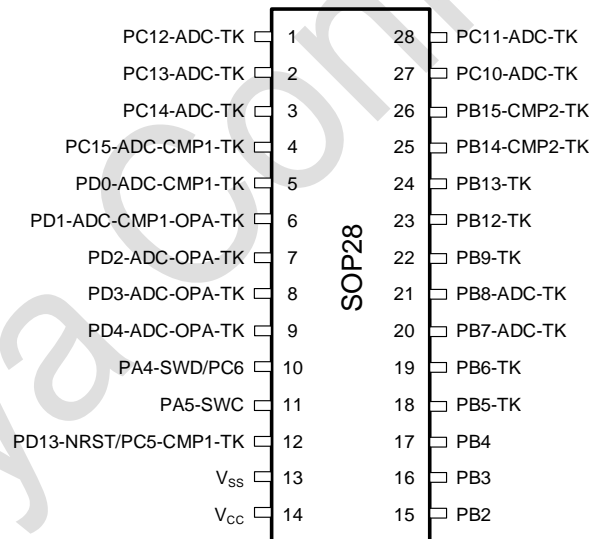


Figure 3-6 SOP28 Pinout 5 PY32T090G5xS7 (Top view)

Table 3-1 Legend/abbreviations used in the pinout table

| Timer type | | Symbol | Definition |
|---------------|----------------------|--------|---|
| Pin type | | S | Supply pin |
| | | G | Ground pin |
| | | I | Input-only pin |
| | | I/O | Input / output pin |
| | | NC | No internal connection |
| I/O structure | | COM | Standard 5 V I/O, with Analog switch function |
| | | NRST | Bidirectional reset pin with embedded weak pull-up resistor |
| | | COM_L | LED COM port supports 120 mA sink current and analog input/output functions |
| | | COM_C | LED SEG port supports constant-current drive and analog input/output functions |
| | | COM_F | I ² C Fm+ with analog input function |
| | | COM_T | Tolerant I/O, allowing input voltage range greater than V _{CC} |
| | | COM_FT | I ² C Fm + with analog input capability and Tolerant port capability |
| Notes | | - | Unless otherwise specified, all ports are used as floating inputs between and after reset |
| Pin functions | Alternate functions | - | Function selected through GPIOx_AFR register |
| | Additional functions | - | Functions directly selected/enabled through peripheral registers |

3.1. Pin definitions

Table 3-2 Pin definitions

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|--------------------|-----------|----------------|---|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 1 | 36 | 44 | - | - | PA0 ⁽⁷⁾ | I/O | COM | USART2_TX TIM1_CH3 LPTIM1_OUT_IN1 COMP2_OUT | ADC0 |
| 2 | 37 | - | - | - | PA1 | I/O | COM | TIM1_CH4 TIM1_CH3N TIM3_ETR TIM16_BRK LPTIM2_OUT_IN1 WKUP4 | ADC1 COMP1_INM1 |
| 3 | - | - | - | - | PA2 | I/O | COM | SPI1_NSS/I2S1_WS TIM15_CH2 TIM15_CH1_ETR TIM15_BRK | ADC2 |
| 4 | - | - | - | - | PA3 | I/O | COM | SPI1_SCK/I2S1_CK TIM2_CH1_ETR | ADC3 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|------------------------------|-----------|----------------|--|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 5 | 38 | 1 | 32 | 10 | PA4-SWDIO ^{(2) (3)} | I/O | COM_T | DEBUG-SWD IR_OUT | - |
| 6 | 39 | 2 | 1 | 11 | PA5-SWCLK ^{(2) (3)} | I/O | COM_T | DEBUG-SWC WKUP5 | - |
| 7 | 40 | 3 | 2 | 12 | PD13-NRST ⁽¹⁾ | I/O | NRST | USART1_CK TIM2_CH3 | - |
| 8 | 41 | 4 | 3 | - | PA6 ⁽⁶⁾ | I/O | COM | USART1_TX USART1_CTS TIM1_BRK TIM2_CH4 TIM15_CH1 EVENTOUT | OSC32_IN |
| 9 | 42 | 5 | 4 | - | PA7 ⁽⁶⁾ | I/O | COM | TIM1_CH1 EVENTOUT | OSC32_OUT |
| 10 | 43 | 6 | - | - | PA8 ⁽⁶⁾ | I/O | COM | RTC_OUT/TAMPIN | - |
| 11 | 44 | 7 | - | - | PA9 | I/O | COM | USART1_RX USART1_TX TIM15_ETR TIM15_CH1 | OSC_IN |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-----------------|-----------|----------------|---------------------|-----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | EVENTOUT | |
| 12 | - | - | - | - | PA10 | I/O | COM | USART1_RX | OSC_OUT |
| | | | | | | | | USART1_TX | |
| | | | | | | | | TIM15_CH2 | |
| | | | | | | | | | |
| 13 | 45 | 8 | 5 | - | PA11 | I/O | COM_F | SPI1_MISO/I2S_MCK | ADC17 |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_ETR | |
| | | | | | | | | TIM15_CH1 | |
| | | | | | | | | LPTIM1_OUT_IN1 | |
| | | | | | | | | LPTIM2_OUT_IN1 | |
| 14 | 46 | 9 | 6 | - | PA12 | I/O | COM_F | I2C1_SCL/I2C1_SDA | ADC18 TK_CMOD/TK32 |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | SPI1_MOSI/I2S1_SD | |
| | | | | | | | | TIM1_CH1N | |
| | | | | | | | | TIM15_CH1 | |
| | | | | | | | | TIM15_CH1N | |
| | | | | | | | | TIM15_ETR | |
| 15 | 47 | 10 | 7 | 13 | V _{SS} | G | - | Ground | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|----------------------|---|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 16 | 48 | 11 | 8 | 14 | Vcc | S | - | Digital power supply | |
| 17 | 1 | 12 | 9 | - | PA13 | I/O | COM_F | USART1_RTS | ADC19 COM0 COMP1_INM7 COMP2_INM0 |
| | | | | | | | | I2C1_SCL | |
| | | | | | | | | I2C2_SCL | |
| | | | | | | | | TIM1_BRK | |
| | | | | | | | | PWM_CH1 | |
| | | | | | | | | EVENTOUT | |
| WKUP6 | | | | | | | | | |
| 18 | 2 | 13 | 10 | - | PA14 | I/O | COM_F | USART2_RX | ADC20 COM1 |
| | | | | | | | | USART2_CTS | |
| | | | | | | | | I2C1_SDA | |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM15_CH1 | |
| | | | | | | | | PWM_CH1N | |
| | | | | | | | | COMP2_OUT | |
| | | | | | | | | MCO | |
| EVENTOUT | | | | | | | | | |
| 19 | 3 | 14 | 11 | - | PA15 | I/O | COM_F | USART2_TX | COM2 |
| | | | | | | | | USART2_RTS | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|--|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | UART1_TX UART1_RX I2C1_SMBA TIM15_CH2 TIM16_CH1 PWM_CH3 | |
| 20 | 4 | 15 | 12 | - | PB0 | I/O | COM_F | TIM16_CH1N USART2_CK UART1_TX UART1_RX I2C2_SMBA SPI2_NSS/I2S_WS PWM_CH3 PWM_CH4 EVENTOUT PVD_OUT | COM3 |
| 21 | 5 | 16 | - | - | PB1 | I/O | COM | SPI2_SCK/I2S2_CK TIM2_CH3 TIM2_CH1_ETR TIM16_BRK | COM4/SEG36 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|-------------------------|---------------------|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | PWM_CH4 | |
| | | | | | | | | EVENTOUT | |
| 22 | 6 | 17 | - | 15 | PB2 | I/O | COM_L COM_C | SPI2_MISO/I2S2_MCK | COM5/ SEG37 |
| | | | | | | | | LPUART1_TX | |
| | | | | | | | | TIM15_ETR | |
| | | | | | | | | LPTIM1_OUT_IN1 | |
| | | | | | | | | EVENTOUT | |
| 23 | 7 | 18 | - | 16 | PB3 | I/O | COM_L COM_C | SPI2_NSS/I2S_WS | COM6/SEG38 |
| | | | | | | | | SPI2_MOSI/I2S2_SD | |
| | | | | | | | | LPUART1_TX | |
| | | | | | | | | TIM2_CH2 | |
| | | | | | | | | LPTIM2_OUT | |
| | | | | | | | | LPTIM2_IN1 | |
| | | | | | | | | EVENTOUT | |
| 24 | 8 | 19 | 13 | 17 | PB4 | I/O | COM_F COM_L COM_C | SPI2_SCK/I2S2_CK | COM7/SEG39 |
| | | | | | | | | I2C1_SCL | |
| | | | | | | | | I2C2_SCL | |
| | | | | | | | | TIM1_BRK | |
| | | | | | | | | TIM2_CH3 | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|------------------------------|-----------|-------------------------|---------------------|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | EVENTOUT | |
| | | | | | | | | WKUP7 | |
| 25 | 9 | 20 | 14 | 18 | PB5(SWCLK) ⁽³⁾⁽⁴⁾ | I/O | COM_F COM_L COM_C | SPI2_MOSI/I2S2_SD | SEG0 TK0 |
| | | | | | | | | UART1_RX | |
| | | | | | | | | I2C1_SDA | |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM2_CH4 | |
| | | | | | | | | DEBUG-SWC | |
| 26 | 10 | 21 | 15 | 19 | PB6(SWDIO) ⁽³⁾⁽⁴⁾ | I/O | COM_L COM_C | SPI2_MISO/I2S2_MCK | SEG1 TK1 |
| | | | | | | | | UART1_TX | |
| | | | | | | | | TIM1_CH3 | |
| | | | | | | | | TIM2_ETR | |
| | | | | | | | | EVENTOUT | |
| | | | | | | | | DEBUG-SWD | |
| 27 | 11 | 22 | 16 | 20 | PB7 | I/O | COM_L COM_C | SPI1_MISO/I2S_MCK | ADC4 SEG2 TK2 |
| | | | | | | | | SPI1_NSS/I2S_WS | |
| | | | | | | | | TIM1_CH4 | |
| | | | | | | | | TIM1_ETR | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|-------------------------|---------------------|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | EVENTOUT | |
| 28 | 12 | 23 | 17 | 21 | PB8 | I/O | COM_F COM_L COM_C | SPI1_MOSI/I2S1_SD | ADC5 SEG3 TK3 |
| | | | | | | | | USART2_CTS | |
| | | | | | | | | UART1_RX | |
| | | | | | | | | LPUART1_RX | |
| | | | | | | | | I2C1_SDA | |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM1_CH4 | |
| | | | | | | | | TIM2_ETR | |
| | | | | | | | | EVENTOUT | |
| 29 | 13 | 24 | 18 | 22 | PB9 | I/O | COM_F COM_L COM_C | SPI1_SCK/I2S1_CK | SEG4 TK4 |
| | | | | | | | | USART1_TX | |
| | | | | | | | | USART2_RTS | |
| | | | | | | | | UART1_TX | |
| | | | | | | | | LPUART1_TX | |
| | | | | | | | | I2C2_SCL | |
| | | | | | | | | TIM1_BRK | |
| | | | | | | | | TIM2_CH4 | |
| | | | | | | | | PWM_BRK | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|------------------|---------------------|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | LPTIM1_ETR | |
| | | | | | | | | IR_OUT | |
| | | | | | | | | COMP1_OUT | |
| | | | | | | | | MCO | |
| 30 | - | - | - | - | PB10 | I/O | COM_C | SPI1_NSS/I2S1_WS | SEG5 TK5 |
| | | | | | | | TIM2_CH1 | | |
| | | | | | | | TIM15_CH1_ETR | | |
| | | | | | | | LPTIM2_IN2 | | |
| | | | | | | | EVENTOUT | | |
| | | | | | | | WKUP0 | | |
| 31 | - | - | - | - | PB11 | I/O | COM_C | SPI2_NSS/I2S2_WS | SEG6 TK6 |
| | | | | | | | USART1_RX | | |
| | | | | | | | LPUART1_CTS | | |
| | | | | | | | TIM2_CH1_ETR | | |
| 32 | 14 | - | - | 23 | PB12 | I/O | COM_F COM_C | SPI1_MISO/I2S1_MCK | SEG7 TK7 |
| | | | | | | | SPI2_SCK/I2S2_CK | | |
| | | | | | | | USART1_TX | | |
| | | | | | | | USART2_TX | | |
| | | | | | | | LPUART1_RTS_DE | | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|---------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM17_CH1 | |
| | | | | | | | | LPTIM1_ETR | |
| | | | | | | | | TIM1_CH1 | |
| 33 | 15 | 25 | - | 24 | PB13 | I/O | COM_F COM_C | SPI1_MOSI/I2S1_SD | SEG8 TK8 |
| | | | | | | | | SPI2_MOSI/SPI2_SD | |
| | | | | | | | | USART2_RX | |
| | | | | | | | | UART1_RX/UART2_RX | |
| | | | | | | | | LPUART1_RX | |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH1N | |
| | | | | | | | | TIM17_CH1N | |
| | | | | | | | | LPTIM2_ETR | |
| | | | | | | | | MCO | |
| | | | | | | | | EVENTOUT | |
| 34 | 16 | 26 | - | 25 | PB14 | I/O | COM_C | SPI2_MISO/I2S2_MCK | SEG9 TK9 COMP2_INP2 |
| | | | | | | | | USART2_TX | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|-----------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | UART1_TX/UART2_TX LPUART1_TX TIM1_CH1 TIM17_BRK RTC_REFIN LPTIM2_IN2 EVENTOUT | |
| 35 | - | - | - | 26 | PB15 | I/O | COM_C | SPI2_NSS/I2S2_WS USART2_CK TIM2_CH1_ETR TIM3_CH3 EVENTOUT | SEG10 TK10 COMP2_INM1 |
| 36 | - | - | - | - | PC0 | I/O | COM_C | USART2_TX TIM2_CH3 TIM3_CH4 TIM15_CH1_ETR PWM_BRK EVENTOUT | SEG11 TK11 COMP2_INM7 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|-----------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 37 | - | - | - | - | PC1 | I/O | COM_C | SPI1_NSS/I2S1_WS USART2_CTS PWM_CH1 | SEG12 TK12 OPA_INM2 |
| 38 | - | - | - | - | PC2 | I/O | COM | SPI1_SCK/I2S1_CK SPI2_MISO/I2S2_MCK TIM15_CH1N TIM16_BRK PWM_CH1N | SEG13 TK13 OPA_INP2 |
| 39 | 17 | - | - | - | PC3 | I/O | COM | SPI1_MISO/I2S1_MCK SPI2_NSS/I2S2_WS USART1_CTS UART1_TX/UART2_TX UART1_RX/UART2_RX TIM1_CH4 TIM16_CH1N PWM_CH2N TIM15_CH1 LPTIM1_IN2 LPTIM2_OUT_IN1 | SEG14 TK14 COMP2_INP3 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|-----------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 40 | 18 | - | - | - | PC4 | I/O | COM | SPI1_MOSI/I2S1_SD SPI2_SCK/I2S2_CK USART1_RTS UART1_TX/UART2_TX UART1_RX/UART2_RX TIM1_CH3N TIM16_CH1 PWM_ETR_HS LPTIM1_IN2 LPTIM1_OUT_IN1 | SEG15 TK15 COMP2_INP4 |
| 41 | - | - | 19 | 12 | PC5 | I/O | COM_F | SPI3_SCK/I2S2_CK USART1_CTS LPUART1_TX LPUART1_RX I2C1_SCL I2C2_SCL TIM1_CH3 TIM1_ETR WKUP1 | SEG16 TK16 COMP1_INM0 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|--------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | LPTIM1_IN1 | |
| | | | | | | | | EVENTOUT | |
| 42 | 19 | 27 | 20 | 10 | PC6 | I/O | COM_F | SPI2_MOSI/I2S2_SD | SEG17 TK17 DAC_OUT |
| | | | | | | | | LPUART1_TX | |
| | | | | | | | | LPUART1_RX | |
| | | | | | | | | LPUART2_RX | |
| | | | | | | | | USART1_RTS | |
| | | | | | | | | UART2_RX | |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH3N | |
| | | | | | | | | TIM3_CH4 | |
| | | | | | | | | LPTIM1_OUT_IN1 | |
| | | | | | | | | EVENTOUT | |
| 43 | 20 | 28 | - | - | PC7 | I/O | COM_F | SPI2_MISO/I2S2_MCK | SEG18 TK18 |
| | | | | | | | | USART2_TX | |
| | | | | | | | | UART2_TX | |
| | | | | | | | | LPUART1_TX | |
| | | | | | | | | LPUART2_TX | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|---------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | I2C1_SDA | |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM15_ETR | |
| | | | | | | | | TIM16_CH1N | |
| | | | | | | | | EVENTOUT | |
| 44 | 21 | 29 | - | - | PC8 | I/O | COM | SPI1_MISO/I2S1_MCK | SEG19 TK19 OPA_OUT3 |
| | | | | | | | | USART1_RX | |
| | | | | | | | | USART1_TX | |
| | | | | | | | | UART1_RX | |
| | | | | | | | | TIM1_BRK | |
| | | | | | | | | TIM15_CH2 | |
| | | | | | | | | LPTIM2_OUT_IN1 | |
| | | | | | | | | EVENTOUT | |
| 45 | 22 | 30 | 21 | - | PC9 | I/O | COM_F | SPI1_MOSI/I2S1_SD | SEG20 TK20 OPA_OUT4 |
| | | | | | | | | USART1_RX | |
| | | | | | | | | USART1_TX | |
| | | | | | | | | USART2_CK | |
| | | | | | | | | UART1_TX | |
| | | | | | | | | I2C1_SDA | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM15_CH1 | |
| | | | | | | | | TIM15_ETR | |
| | | | | | | | | LPTIM2_ETR | |
| | | | | | | | | EVENTOUT | |
| 46 | 23 | 31 | 22 | 27 | PC10 | I/O | COM_F | SPI1_SCK/I2S1_CK | ADC21 SEG21 TK21 |
| | | | | | | | | USART2_RX | |
| | | | | | | | | USART2_TX | |
| | | | | | | | | LPUART2_CTS | |
| | | | | | | | | I2C1_SCL | |
| | | | | | | | | I2C2_SCL | |
| | | | | | | | | TIM1_CH1N | |
| | | | | | | | | TIM2_CH1_ETR | |
| | | | | | | | | EVENTOUT | |
| | | | | | | | | PVD_OUT | |
| | | | | | | | | TIM3_CH3 | |
| | | | | | | | | WKUP2 | |
| 47 | 24 | 32 | 23 | 28 | PC11 | I/O | COM | SPI1_NSS/I2S1_WS | ADC22 SEG22 TK22 |
| | | | | | | | | SPI2_MOSI/I2S2_SD | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|-----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | USART2_RX | |
| | | | | | | | | USART2_TX | |
| | | | | | | | | LPUART2_RTS_DE | |
| | | | | | | | | TIM1_CH2N | |
| | | | | | | | | TIM3_CH4 | |
| | | | | | | | | TIM3_ETR | |
| 48 | 25 | 33 | 24 | 1 | PC12 | I/O | COM_F | USART2_CK | ADC6 SEG23 TK23 |
| | | | | | | | | LPUART1_RX | |
| | | | | | | | | SPI1_NSS/I2S1_WS | |
| | | | | | | | | UART2_RX | |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH1 | |
| | | | | | | | | TIM3_CH3 | |
| | | | | | | | | PWM_CH3 | |
| | | | | | | | | TIM3_ETR | |
| 49 | 26 | 34 | 25 | 2 | PC13 | I/O | COM_F | USART2_TX | ADC7 SEG24 TK24 |
| | | | | | | | | UART2_TX | |
| | | | | | | | | LPUART2_TX | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|-------------------------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH2 | |
| | | | | | | | | TIM2_CH3 | |
| | | | | | | | | TIM17_BRK | |
| | | | | | | | | PWM_CH4 | |
| | | | | | | | | EVENTOUT | |
| | | | | | | | | PVD_OUT | |
| 50 | 27 | 35 | 26 | 3 | PC14 | I/O | COM_F | SPI1_NSS/I2S1_WS | ADC8 SEG25 TK25 |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH3 | |
| | | | | | | | | TIM2_CH4 | |
| | | | | | | | | TIM15_BRK | |
| | | | | | | | | EVENTOUT | |
| 51 | 28 | 36 | 27 | 4 | PC15 | I/O | COM_F | SPI1_SCK/I2S1_CK | ADC9 SEG26 TK26 COMP1_INP2 |
| | | | | | | | | I2C1_SCL/I2C1_SDA | |
| | | | | | | | | I2C2_SCL/I2C2_SDA | |
| | | | | | | | | TIM1_CH4 | |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---------------------|--|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | TIM2_ETR | |
| | | | | | | | | TIM15_CH1 | |
| | | | | | | | | PWM_CH2 | |
| 52 | 29 | 37 | 28 | 5 | PD0 | I/O | COM | SPI1_NSS/I2S1_WS | ADC10 SEG27 TK27 COMP1_INP3 |
| | | | | | | | | USART1_CK | |
| | | | | | | | | UART1_TX | |
| | | | | | | | | UART1_RX | |
| | | | | | | | | TIM1_CH3N | |
| | | | | | | | | TIM15_CH1N | |
| | | | | | | | | PWM_CH2N | |
| | | | | | | | | MCO | |
| 53 | 30 | 38 | 29 | 6 | PD1 | I/O | COM | SPI1_SCK/I2S1_CK | ADC11 SEG28 TK28 COMP1_INP4 OPA_OUT2 |
| | | | | | | | | USART1_TX | |
| | | | | | | | | UART1_TX | |
| | | | | | | | | UART1_RX | |
| | | | | | | | | TIM2_ETR | |
| | | | | | | | | TIM3_ETR | |
| | | | | | | | | PWM_CH1 | |
| 54 | 31 | 39 | 30 | 7 | PD2 | I/O | COM | SPI1_MISO/I2S1_MCK | ADC12 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|--|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | USART1_RX USART1_TX UART2_RX UART2_TX LPUART2_CTS TIM1_CH2 TIM2_CH1 TIM3_CH1 TIM15_BRK | SEG29 TK29 OPA_INM1 |
| 55 | 32 | 40 | 31 | 8 | PD3 | I/O | COM | SPI1_MOSI/I2S1_SD USART1_RX USART1_TX UART2_RX UART2_TX LPUART2_RTS_DE TIM1_CH2N TIM2_CH2 TIM3_CH2 PWM_ETR | ADC13 SEG30/VLCD0 TK30 OPA_INP1 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|--|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | EVENTOUT | |
| 56 | 33 | 41 | 32 | 9 | PD4 | I/O | COM | USART1_CK TIM1_CH1N TIM1_ETR PWM_CH1N EVENTOUT WKUP3 | ADC14 SEG31/VLCD1 TK31 OPA_OUT1 |
| 57 | - | - | - | - | PD5 | I/O | COM_F | SPI2_NSS/I2S2_WS USART1_RX LPUART2_RX I2C1_SMBA PWM_BRK LPTIM1_OUT_IN1 | SEG32/VLCD2 |
| 58 | - | - | - | - | PD6 | I/O | COM_F | SPI2_SCK/I2S2_CK USART1_TX LPUART2_TX I2C1_SCL I2C2_SCL TIM1_CH3N | SEG33/VLCD3 |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|--------------------------|-----------|----------------|---------------------|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | LPTIM2_OUT_IN1 | |
| | | | | | | | | EVENTOUT | |
| 59 | 34 | 42 | - | - | PD7 | I/O | COM_F | SPI1_MOSI/I2S1_SD | ADC15 SEG34/MLCDH |
| | | | | | | | | SPI2_MOSI/I2S2_SD | |
| | | | | | | | | USART2_RX | |
| | | | | | | | | I2C1_SDA | |
| | | | | | | | | I2C2_SDA | |
| | | | | | | | | TIM15_CH1_ETR | |
| | | | | | | | | EVENTOUT | |
| 60 | 35 | 43 | - | - | PD8-BOOT0 ⁽⁵⁾ | I/O | COM | SPI2_MISO/I2S2_MCK | ADC16 |
| | | | | | | | | USART2_TX | |
| | | | | | | | | TIM2_CH1_ETR | |
| | | | | | | | | TIM3_CH1 | |
| 61 | - | - | - | - | PD9 | I/O | COM_F | USART2_RX | ADC23 SEG35 |
| | | | | | | | | I2C2_SMBA | |
| | | | | | | | | TIM3_CH2 | |
| | | | | | | | | TIM15_CH1N | |
| | | | | | | | | EVENTOUT | |
| 62 | - | - | - | - | PD10 | I/O | COM_FT | USART1_RX | - |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|---|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| | | | | | | | | USART2_TX UART2_RX LPUART1_CTS LPUART2_RX TIM17_CH1N I2C1_SCL/I2C1_SDA I2C2_SCL/I2C2_SDA PWM_CH2 LPTIM2_IN2 EVENTOUT | |
| 63 | - | - | - | - | PD11 | I/O | COM_FT | USART1_TX UART2_TX LPUART1_RTS_DE LPUART2_TX I2C1_SCL/I2C1_SDA I2C2_SCL/I2C2_SDA TIM3_CH3 TIM17_CH1 PWM_CH2N | - |

| Packages | | | | | Reset | Port type | Port structure | Functions | |
|--------------------|-----------|-----------|-----------|----------|-------|-----------|----------------|--|----------------------|
| LQFP64 R2/QFN64 R2 | LQFP48 C1 | LQFP44 S1 | LQFP32 K1 | SOP28 G5 | | | | Alternate functions | Additional functions |
| 64 | - | - | - | - | PD12 | I/O | COM_F | USART2_RX COMP1_OUT TIM3_CH4 I2C2_SMBA TIM17_CH1 | ADC26 |

- Configured by option bytes to choose PD13 or NRST.
- After reset, when the option byte is configured to 0/0 (default state), PA5 and PA4 are configured as SWCLK and SWDIO.
- PA4, PA5, PB6, and PB5 can be configured via options to select GPIO functionality or SWC/SWD functionality. Internal pull-up resistors for PA4 and PB6, and internal pull-down resistors for PA5 and PB5 are activated.

| option[1:0] | PA5 | PA4 | PB6 | PB5 |
|--------------|-------|-------|-------|-------|
| 0/0(default) | SWCLK | SWDIO | GPIO | GPIO |
| 0/1 | GPIO | GPIO | SWDIO | SWCLK |
| 1/0 | SWCLK | GPIO | SWDIO | GPIO |
| 1/1 | GPIO | SWDIO | GPIO | SWCLK |

- Pins configured for SWD/SWC functions cannot be used as TK channels.
- PD8-BOOT0 defaults to digital input mode and pull-down is enabled.
- PA6, PA7 and PA8 in V_{BKP} domain are powered via a current-limited switch (3 mA sourcing). GPIO from PA6 to PA8 output mode restrictions:
 - Maximum rate 2 MHz, load ≤ 30 pF.
 - Cannot be used as current sources (e.g., LED driving).

7. PA0 requires 1 μ F external capacitor when using V_{REFBUF} . ADC/DAC cannot use V_{REFBUF} as reference if PA0 is not routed.
8. Two I/O ports are multiplexed on the same pin. Only one of the I/O ports can be used at any given time, while the other must be configured in analog mode (by setting $\text{MODEy}[1:0]$ to 0B11).

3.2. Alternate functions selected through GPIOA_AFR registers for port A

Table 3-3 Port A alternate functions mapping

| PortA | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|-------|----------------|----------------|----------------|-----------|----------|----------|----------|-----------|------------|-----------|------------|------------------------|-----------|------|--------|----------|
| PA0 | - | TIM1_CH3 | LPTIM1_OUT_IN1 | - | - | - | - | - | - | - | - | USART2_TX | COMP2_OUT | - | - | - |
| PA1 | TIM1_CH4 | LPTIM2_OUT_IN1 | TIM16_BRK | - | - | - | - | - | - | - | TIM1_CH3N | TIM2_ETR | - | - | - | - |
| PA2 | TIM15_CH2 | TIM15_CH1_ETR | TIM15_BRK | - | - | - | - | - | - | - | - | SPI1_NSS/ I2S1_WS | - | - | - | - |
| PA3 | TIM2_CH1_ETR | - | - | - | - | - | - | - | - | - | - | SPI1_SCK/ I2S1_CK | - | - | - | - |
| PA4 | DEBUG_SWD | - | - | - | - | - | - | - | - | - | - | - | - | - | IR_OUT | - |
| PA5 | DEBUG_SWC | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - |
| PA6 | TIM1_BRK | - | - | - | - | - | - | - | TIM15_CH1 | - | USART1_CTS | USART1_TX | TIM2_CH4 | - | - | EVENTOUT |
| PA7 | - | - | - | - | - | - | - | - | TIM1_CH1 | - | - | - | - | - | - | EVENTOUT |
| PA8 | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - | - |
| PA9 | TIM15_ETR | USART1_TX | USART1_RX | - | - | - | - | - | TIM15_CH1 | - | - | - | - | - | - | EVENTOUT |
| PA10 | USART1_TX | USART1_RX | - | - | - | - | - | - | TIM15_CH2 | - | - | - | - | - | - | - |
| PA11 | LPTIM2_OUT_IN1 | LPTIM1_OUT_IN1 | TIM15_CH1 | I2C1_SCL | I2C1_SDA | I2C2_SCL | I2C2_SDA | - | TIM1_ETR | - | - | SPI1_MISO/ I2S1_MCK | - | - | - | - |
| PA12 | TIM15_CH1 | I2C1_SCL | I2C1_SDA | I2C2_SCL | I2C2_SDA | - | - | TIM1_CH1N | TIM15_CH1N | TIM15_ETR | - | SPI1_MOSI/ I2S1_SD | - | - | - | - |
| PA13 | - | PWM_CH1 | I2C1_SCL | I2C2_SCL | - | - | - | - | - | - | USART1_RTS | - | TIM1_BRK | - | - | EVENTOUT |
| PA14 | MCO | PWM_CH1N | I2C1_SDA | I2C2_SDA | - | - | - | - | - | COMP2_OUT | USART2_CTS | USART2_RX | TIM15_CH1 | - | - | EVENTOUT |
| PA15 | TIM16_CH1 | UART1_TX | UART1_RX | I2C1_SMBA | - | - | - | PWM_CH3 | - | - | USART2_RTS | USART2_TX | TIM15_CH2 | - | - | - |

3.3. Alternate functions selected through GPIOB_AFR registers for port B

Table 3-4 Port B alternate function mapping

| PortB | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|-------|------------|---------------|----------------------|------------------------|------------------------|------------------------|----------------------|----------|------------------------------|-----------|----------------|------------------------|------------|------------|------------|----------|
| PB0 | TIM16_CH1N | UART1_TX | UART1_RX | I2C2_SMBA | - | - | - | PWM_CH4 | - | - | USART2_CK | SPI2_NSS/ I2S2_WS | PWM_CH3 | - | PVD_OUT | EVENTOUT |
| PB1 | TIM2_CH3 | TIM2_CH1_ETR | TIM16_BRK | - | - | - | - | - | - | - | - | SPI2_SCK/ I2S2_CK | PWM_CH4 | - | - | EVENTOUT |
| PB2 | - | - | LPTIM1_OUT_IN1 | LPUART1_TX | - | - | - | - | - | - | - | SPI2_MISO/ I2S2_MCK | TIM15_ETR | - | - | EVENTOUT |
| PB3 | - | - | LPTIM2_OUT | LPUART1_TX | SPI2_NSS/ I2S2_WS | - | - | - | - | TIM2_CH2 | - | SPI2_MOSI/ I2S2_SD | LPTIM2_IN1 | - | - | EVENTOUT |
| PB4 | - | - | TIM2_CH3 | SPI2_SCK/ I2S2_CK | I2C1_SCL | - | I2C2_SCL | - | - | - | - | TIM1_BRK | - | - | - | EVENTOUT |
| PB5 | DEBUG_SWC | - | TIM2_CH4 | SPI2_MOSI/ I2S2_SD | I2C1_SDA | - | I2C2_SDA | - | - | - | - | UART1_RX | - | - | - | - |
| PB6 | DEBUG_SWD | - | TIM1_CH3 | TIM2_ETR | SPI2_MISO/ I2S2_MCK | - | - | - | - | - | - | UART1_TX | - | - | - | EVENTOUT |
| PB7 | - | - | - | TIM1_CH4 | TIM1_ETR | SPI1_MISO/ I2S1_MCK | SPI1_NSS/ I2S1_WS | - | - | - | - | - | - | - | - | EVENTOUT |
| PB8 | - | - | - | TIM1_CH4 | TIM2_ETR | SPI1_MOSI/ I2S1_SD | I2C1_SDA | - | I2C2_SDA | - | USART2_CTS | UART1_RX | LPUART1_RX | - | - | EVENTOUT |
| PB9 | MCO | - | TIM2_CH4 | TIM1_BRK | SPI1_SCK/ I2S1_CK | I2S2_SCL | - | I2C2_SCL | USART1_TX/ USART2_7816_IO | COMP1_OUT | USART2_RTS | UART1_TX | LPUART1_TX | PWM_BRK | LPTIM1_ETR | IR_OUT |
| PB10 | - | TIM15_CH1_ETR | SPI1_NSS/ I2S1_WS | - | LPTIM2_IN2 | - | - | - | - | - | - | - | - | - | - | EVENTOUT |
| PB11 | - | TIM2_CH1_ETR | SPI2_NSS/ I2S2_WS | - | - | - | - | - | - | - | LPUART1_CTS | USART1_RX | - | - | - | - |
| PB12 | - | TIM1_CH1 | USART2_TX | SPI2_SCK/ I2S2_CK | SPI1_MISO/ I2S1_MCK | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | LPUART1_RTS_DE | USART1_TX | - | TIM17_CH1 | LPTIM1_ETR | - |
| PB13 | MCO | TIM1_CH1N | USART2_RX | SPI2_MOSI/ I2S2_SD | SPI1_MOSI/ I2S1_SD | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | UART2_RX | UART1_RX | LPUART1_RX | TIM17_CH1N | LPTIM2_ETR | EVENTOUT |
| PB14 | - | TIM1_CH1 | USART2_TX | SPI2_MISO/ I2S2_MCK | LPTIM2_IN2 | - | - | - | - | - | UART2_TX | UART1_TX | LPUART1_TX | TIM17_BRK | RTC_REFIN | EVENTOUT |
| PB15 | - | TIM2_CH1_ETR | SPI2_NSS/ I2S2_WS | - | - | - | - | - | - | - | USART2_CK | TIM3_CH3 | - | - | - | EVENTOUT |

3.4. Alternate functions selected through GPIOC_AFR registers for port C

Table 3-5 Port C alternate function mapping

| PortC | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|-------|----------------|----------------------|----------------------|------------------------|------------------------|------------------------|----------|----------|----------|----------|--|-----------------------|------------|------------------------------|------------|----------|
| PC0 | - | TIM15_CH1_ETR | PWM_BRK | TIM2_CH3 | - | - | - | - | - | - | USART2_TX/ USART2_7816_IO | TIM3_CH4 | - | - | - | EVENTOUT |
| PC1 | - | PWM_CH1 | SPI1_NSS/ I2S1_WS | - | - | - | - | - | - | - | - | - | - | USART2_CTS | - | - |
| PC2 | PWM_CH1N | SPI1_SCK/ I2S1_CK | - | - | SPI2_MISO/ I2S2_MCK | - | - | - | - | - | - | - | - | TIM15_CH1N | - | - |
| PC3 | LPTIM2_OUT_IN1 | TIM15_CH1 | UART1_TX | UART1_RX | SPI1_MISO/ I2S1_MCK | - | - | - | UART2_TX | UART2_RX | USART1_CTS | SPI2_NSS/ I2S2_WS | LPTIM1_IN2 | PWM_CH2N | TIM1_CH4 | - |
| PC4 | LPTIM1_OUT_IN1 | TIM16_CH1 | UART1_TX | UART1_RX | SPI1_MOSI/ I2S1_SD | - | - | - | UART2_TX | UART2_RX | USART1_RTS | SPI2_SCK/ I2S2_CK | LPTIM1_IN2 | TIM1_CH3N | PWM_ETR_HS | - |
| PC5 | TIM1_CH3 | TIM1_ETR | LPUART1_TX | LPUART1_RX | SPI2_SCK/ I2S2_CK | I2C1_SCL | - | - | I2C1_SCL | - | - | LPTIM1_IN1 | - | USART1_CTS | - | EVENTOUT |
| PC6 | TIM3_CH4 | LPTIM1_OUT_IN1 | LPUART1_TX | LPUART1_RX | SPI2_MOSI/ I2S2_SD | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | TIM1_CH3N | - | LPUART2_RX | USART1_RTS | UART2_RX | EVENTOUT |
| PC7 | TIM15_ETR | TIM16_CH1N | LPUART1_TX | SPI2_MISO/ I2S2_MCK | I2C1_SDA | - | - | I2C2_SDA | - | - | - | - | LPUART2_TX | USART2_TX/ USART2_7816_IO | UART2_TX | EVENTOUT |
| PC8 | TIM15_CH2 | LPTIM2_OUT_IN1 | TIM1_BRK | USART1_TX | USART1_RX | SPI1_MISO/ I2S1_MCK | - | - | - | - | - | - | UART1_RX | - | - | EVENTOUT |
| PC9 | TIM15_CH1 | TIM15_ETR | USART1_TX | USART1_RX | SPI1_MOSI/ I2S1_SD | I2C1_SDA | - | I2C2_SDA | - | - | USART2_CK | - | UART1_TX | - | LPTIM2_ETR | EVENTOUT |
| PC10 | - | TIM3_CH3 | TIM2_CH1_ETR | USART2_TX | USART2_RX | SPI1_SCK/ I2S1_CK | I2C1_SCL | I2C2_SCL | I2C2_SCL | - | LPUART2_CTS | - | TIM1_CH1N | - | PVD_OUT | EVENTOUT |
| PC11 | - | TIM3_CH4 | TIM3_ETR | USART2_TX | USART2_RX | SPI1_NSS/ I2S1_WS | - | - | - | - | LPUART2_RTS_DE | SPI2_MOSI/ I2S2_SD | TIM1_CH2N | - | - | - |
| PC12 | - | TIM3_CH3 | TIM3_ETR | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | - | UART2_RX | USART2_CK | LPUART1_RX | TIM1_CH1 | SPI1_NSS/ I2S1_WS | PWM_CH3 | - |
| PC13 | - | TIM2_CH3 | TIM17_BRK | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | - | UART2_TX | USART2_TX/ USART2_RX/ USART2_7816_IO | LPUART2_TX | TIM1_CH2 | PVD_OUT | PWM_CH4 | EVENTOUT |
| PC14 | - | TIM2_CH4 | TIM15_BRK | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | - | - | - | SPI1_NSS/ I2S1_WS | TIM1_CH3 | - | - | EVENTOUT |
| PC15 | - | TIM2_ETR | TIM15_CH1 | I2C1_SCL | I2C1_SDA | - | I2C2_SCL | I2C2_SDA | - | PWM_CH2 | - | SPI1_SCK/ I2S1_CK | TIM1_CH4 | - | - | - |

3.5. Alternate functions selected through GPIOD_AFR registers for port D

Table 3-6 Port D alternate function mapping

| PortD | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|-------|----------------------|----------------------|------------------------|-----------|-----------|----------|----------|----------|----------------|-----------|---|------------------------|-----------------------|-----------|------------|----------|
| PD0 | MCO | TIM15_CH1N | UART1_TX | UART1_RX | - | - | - | - | - | PWM_CH2N | USART1_CK | SPI1_NSS/ I2S1_WS | TIM1_CH3N | - | - | - |
| PD1 | - | TIM3_ETR | PWM_CH1 | UART1_TX | UART1_RX | - | - | - | - | - | UART1_TX/ USART1_RX/ USART2_7816_ IO | SPI1_SCK/ I2S1_CK | TIM2_ETR | - | - | - |
| PD2 | - | TIM3_CH1 | TIM15_BRK | USART1_TX | USART1_RX | - | - | - | - | TIM1_CH2N | LPUART2_CTS | SPI1_MISO/ I2S1_MCK | TIM2_CH1 | UART2_TX | UART2_RX | - |
| PD3 | - | TIM3_CH2 | PWM_ETR | USART1_TX | USART1_RX | - | - | - | - | TIM1_CH2N | LPUART2_RTS _DE | SPI1_MOSI/ I2S1_SD | TIM2_CH2 | UART2_TX | UART2_RX | EVETNOUT |
| PD4 | - | TIM1_CH1N | PWM_CH1N | - | - | - | - | - | - | - | USART1_CK | - | TIM1_ETR | - | - | EVETNOUT |
| PD5 | PWM_BRK | SPI2_NSS/ I2S2_WS | - | I2C1_SMBA | - | - | - | - | LPTIM1_OUT_IN1 | - | - | USART1_RX | LPUART2_RX | - | - | - |
| PD6 | SPI2_SCK/ I2S2_CK | I2C1_SCL | I2C2_SCL | - | - | - | - | - | LPTIM2_OUT_IN1 | TIM1_CH3N | - | USART1_TX | LPUART2_TX | - | - | EVETNOUT |
| PD7 | TIM15_CH1_ ETR | USART2_RX | SPI2_MOSI/ I2S2_SD | I2C1_SDA | I2C2_SDA | - | - | - | - | - | - | - | SPI1_MOSI/ I2S1_SD | - | - | EVETNOUT |
| PD8 | TIM2_CH1_ ETR | USART2_TX | SPI2_MISO/ I2S2_MCK | - | - | - | - | - | - | - | - | TIM3_CH1 | - | - | - | - |
| PD9 | - | TIM15_CH1N | USART2_RX | - | - | - | - | - | - | - | - | TIM3_CH2 | - | I2C2_SMBA | - | EVETNOUT |
| PD10 | - | TIM17_CH1N | USART2_TX | - | I2C1_SCL | I2C1_SDA | I2C1_SCL | I2C1_SDA | UART2_RX | PWM_CH2 | LPUART1_CTS | USART1_RX | LPUART2_RX | - | LPTIM2_IN2 | EVETNOUT |
| PD11 | - | PWM_CH2N | - | - | I2C1_SCL | I2C1_SDA | I2C1_SCL | I2C1_SDA | UART2_TX | - | LPUART1_RTS _DE | USART1_TX | LPUART2_TX | TIM3_CH3 | TIM17_CH1 | - |
| PD12 | - | TIM17_CH1 | - | I2C2_SMBA | - | - | - | - | - | - | - | USART2_RX | COMP1_OUT | TIM3_CH4 | - | - |
| PD13 | - | - | - | - | - | - | - | - | - | - | - | USART1_CK | TIM2_CH3 | - | - | - |

4. Memory mapping

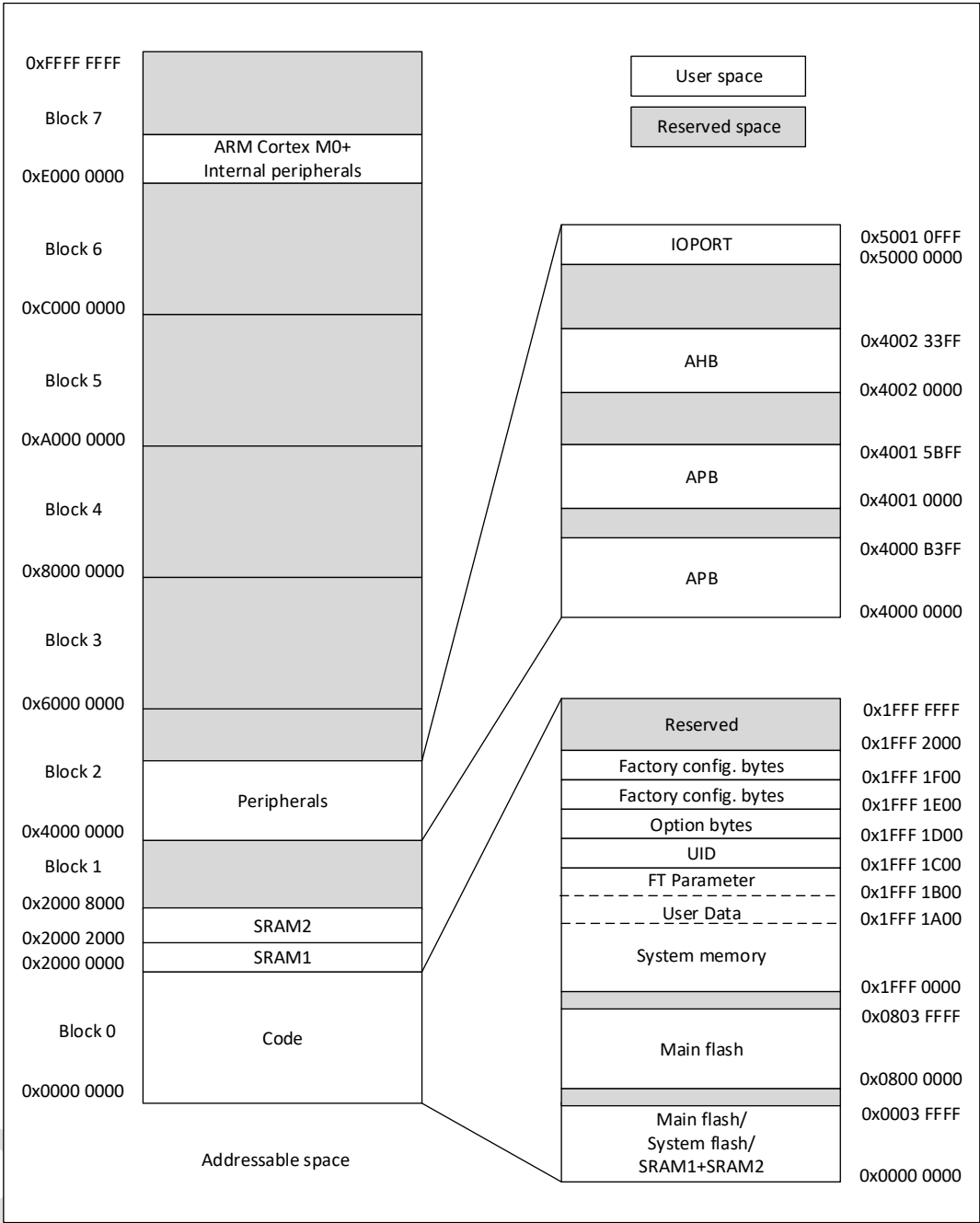


Figure 4-1 Memory map

Table 4-1 Memory boundary address

| Type | Boundary address | Size | Memory area | Description |
|------|-------------------------|-----------|--|--|
| SRAM | 0x2000 8000-0x3FFF FFFF | - | Reserved | - |
| | 0x2000 2000-0x2000 7FFF | 24 KB | SRAM2 | SRAM address space: 0x20000000–0x20001FFF when configured to 8KB on power-on. |
| | 0x2000 0000-0x2000 1FFF | 8 KB | SRAM1 | |
| Code | 0x1FFF 2000-0x1FFF FFFF | - | Reserved | - |
| | 0x1FFF 1F00-0x1FFF 1FFF | 256 bytes | Factory config. bytes | Store trimming data |
| | 0x1FFF 1E00-0x1FFF 1EFF | 256 bytes | Factory config. bytes | HSI trimming data, Flash erase/write time configuration parameters, TS data storage. |
| | 0x1FFF 1D00-0x1FFF 1DFF | 256 bytes | Option bytes | Option bytes information |
| | 0x1FFF 1C00-0x1FFF 1CFF | 256 bytes | UID | Unique ID |
| | 0x1FFF 1B00-0x1FFF 1BFF | 256 bytes | FT | FT info |
| | 0x1FFF 1A00-0x1FFF 1AFF | 256 bytes | User data bytes | User OTP |
| | 0x1FFF 0000-0x1FFF 19FF | 6.5 KB | System memory | Store Boot loader |
| | 0x0804 0000-0x1FFE FFFF | - | Reserved | - |
| | 0x0800 0000-0x0803 FFFF | 256 KB | Main flash memory | - |
| | 0x0004 0000-0x07FF FFFF | - | Reserved | - |
| | 0x0000 0000-0x0003 FFFF | 256 KB | Selection based on Boot configuration: 1) Main flash memory 2) System flash memory 3) SRAM | - |

Table 4-2 Peripheral register address

| Bus | Boundary address | Size | Peripheral |
|--------|-------------------------|------|------------|
| | 0xE000 0000-0xE00F FFFF | 1 MB | M0+ |
| IOPORT | 0x5000 1800-0x5FFF FFFF | - | Reserved |
| | 0x5000 1400-0x5000 17FF | - | Reserved |
| | 0x5000 1000-0x5000 13FF | - | Reserved |
| | 0x5000 0C00-0x5000 0FFF | 1 KB | GPIOD |
| | 0x5000 0800-0x5000 0BFF | 1 KB | GPIOC |
| | 0x5000 0400-0x5000 07FF | 1 KB | GPIOB |
| | 0x5000 0000-0x5000 03FF | 1 KB | GPIOA |
| AHB | 0x4002 3400-0x4FFF FFFF | - | Reserved |
| | 0x4002 3000-0x4002 33FF | 1 KB | CRC |
| | 0x4002 2400-0x4002 2FFF | - | Reserved |
| | 0x4002 2000-0x4002 23FF | 1 KB | Flash |
| | 0x4002 1800-0x4002 1FFF | - | Reserved |
| | 0x4002 1400-0x4002 17FF | - | Reserved |

| Bus | Boundary address | Size | Peripheral |
|-------------------------|-------------------------|-------------------|---------------------|
| | 0x4002 1000-0x4002 13FF | 1 KB | RCC |
| | 0x4002 0400-0x4002 0FFF | - | Reserved |
| | 0x4002 0000-0x4002 03FF | 1 KB | DMA |
| APB | 0x4001 5C00-0x4001 FFFF | - | Reserved |
| | 0x4001 5800-0x4001 5BFF | 1 KB | MCUDBG |
| | 0x4001 5000-0x4001 57FF | - | Reserved |
| | 0x4001 4C00-0x4001 4FFF | 1 KB | PWM |
| | 0x4001 4800-0x4001 4BFF | 1 KB | TIM17 |
| | 0x4001 4400-0x4001 47FF | 1 KB | TIM16 |
| | 0x4001 4000-0x4001 43FF | 1 KB | TIM15 |
| | 0x4001 3C00-0x4001 3FFF | - | Reserved |
| | 0x4001 3800-0x4001 3BFF | 1 KB | USART1 |
| | 0x4001 3400-0x4001 37FF | - | Reserved |
| | 0x4001 3000-0x4001 33FF | 1 KB | SPI1 |
| | 0x4001 2C00-0x4001 2FFF | 1 KB | TIM1 |
| | 0x4001 2800-0x4001 2BFF | 1 KB | TK |
| | 0x4001 2400-0x4001 27FF | 1 KB | ADC |
| | 0x4001 0C00-0x4001 23FF | - | Reserved |
| | 0x4001 0800-0x4001 0BFF | 1KB | V _{REFBUF} |
| | 0x4001 0400-0x4001 07FF | 1 KB | EXTI |
| | 0x4001 0300-0x4001 03FF | 1 KB | OPA |
| | 0x4001 0200-0x4001 02FF | | COMP1/COMP2 |
| | 0x4001 0000-0x4001 01FF | | SYSCFG |
| | 0x4000 B400-0x4000 FFFF | - | Reserved |
| | 0x4000 B000-0x4000 B3FF | 1 KB | BKP(TAMP) |
| | 0x4000 9C00-0x4000 AFFF | - | Reserved |
| | 0x4000 9800-0x4000 9BFF | 1 KB | LPUART2 |
| | 0x4000 9400-0x4000 97FF | 1 KB | LPTIM2 |
| | 0x4000 8400-0x4000 93FF | - | Reserved |
| | 0x4000 8000-0x4000 83FF | 1KB | LPUART1 |
| | 0x4000 7C00-0x4000 7FFF | 1 KB | LPTIM1 |
| | 0x4000 7800-0x4000 7BFF | - | Reserved |
| | 0x4000 7400-0x4000 77FF | 1 KB | DAC |
| | 0x4000 7000-0x4000 73FF | 1 KB | PWR |
| | 0x4000 6400-0x4000 6FFF | - | Reserved |
| | 0x4000 5C00-0x4000 63FF | - | Reserved |
| 0x4000 5800-0x4000 5BFF | 1 KB | I ² C2 | |
| 0x4000 5400-0x4000 57FF | 1 KB | I ² C1 | |
| 0x4000 5000-0x4000 53FF | - | Reserved | |

| Bus | Boundary address | Size | Peripheral |
|-----|-------------------------|------|------------|
| | 0x4000 4C00-0x4000 4FFF | 1KB | UART2 |
| | 0x4000 4800-0x4000 4BFF | 1KB | UART1 |
| | 0x4000 4400-0x4000 47FF | 1 KB | USART2 |
| | 0x4000 3C00-0x4000 43FF | - | Reserved |
| | 0x4000 3800-0x4000 3BFF | 1 KB | SPI2 |
| | 0x4000 3400-0x4000 37FF | - | Reserved |
| | 0x4000 3000-0x4000 33FF | 1 KB | IWDG |
| | 0x4000 2C00-0x4000 2FFF | 1 KB | WWDG |
| | 0x4000 2800-0x4000 2BFF | 1 KB | RTC |
| | 0x4000 2400-0x4000 27FF | 1 KB | LCD |
| | 0x4000 1800-0x4000 23FF | - | Reserved |
| | 0x4000 1400-0x4000 17FF | 1 KB | TIM7 |
| | 0x4000 1000-0x4000 13FF | 1 KB | TIM6 |
| | 0x4000 0800-0x4000 0FFF | - | Reserved |
| | 0x4000 0400-0x4000 07FF | 1 KB | TIM3 |
| | 0x4000 0000-0x4000 03FF | 1 KB | TIM2 |

5. Electrical characteristics

5.1. Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS} .

5.1.1. Minimum and maximum values

Unless otherwise specified, the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100 % of the devices with an ambient temperature at $T_A = 25\text{ }^\circ\text{C}$ and $T_A = T_{A(\text{max})}$ (given by the selected temperature range).

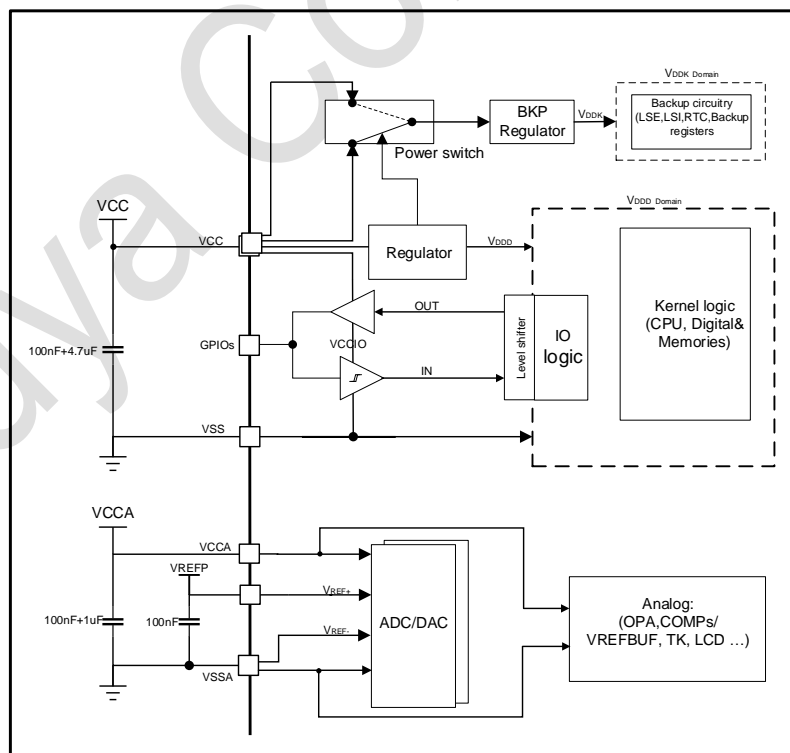
Data based on electrical characterization results, design simulations and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation.

5.1.2. Typical values

Unless otherwise specified, typical data is based on $T_A = 25\text{ }^\circ\text{C}$ and $V_{CC} = 3.3\text{ V}$. These data are for design guidance only and have not been tested.

Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95 % of the devices have an error less than or equal to the value indicated.

5.1.3. Power supply scheme



Note: All decoupling capacitors need to be as close as possible to the pins on the PCB.

Figure 5-1 Power supply scheme

5.2. Absolute maximum ratings

Stresses above the absolute maximum ratings listed in following tables may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5-1 Voltage characteristics⁽¹⁾

| Symbol | Ratings | Min | Max | Unit |
|-----------------------|---|------|--------------|------|
| $V_{CC}-V_{SS}^{(1)}$ | External mains power supply | -0.3 | 6.25 | V |
| $V_{IN}^{(2)}$ | Input voltage on Tolerant IO (COM_T,COM_FT) | -0.3 | 6.25 | V |
| | Input voltage on any other pins | -0.3 | $V_{CC}+0.3$ | |

1. Main power V_{CC} and ground V_{SS} pins must always be connected to the external power supply, in the permitted range.
2. Maximum V_{IN} must always follow allowable maximum injection current limits as per the table.

Table 5-2 Current characteristics

| Symbol | Ratings | Max | Unit |
|----------------------------|---|-----|------|
| ΣI_{VCC} | Total current into sum of all V_{CC} power lines (source) ⁽¹⁾ | 210 | mA |
| ΣI_{VSS} | Total current out of sum of all V_{SS} ground lines (sink) ⁽¹⁾ | 190 | |
| $\Sigma I_{IO(PIN)}^{(2)}$ | Total output current sunk by sum of all I/Os and control pins | 200 | |
| | Total output current sourced by sum of all I/Os and control pins | 180 | |
| $I_{IO}^{(2)}$ | Output current sunk by any I/O and control pin except COM_L I/O | 60 | |
| | Output current sunk by any COM_L I/O | 140 | |
| | Output current source by any I/O and control pin ⁽³⁾ | 25 | |

1. Main power V_{CC} and ground V_{SS} pins must always be connected to the external power supply, in the permitted range.
2. These I/O types refer to the terms and symbols defined by pins.
3. Excluding PA6/PA7/PA8 in V_{BKP} domain, which are powered via a current-limited switch (3 mA sourcing).

Table 5-3 Thermal characteristics

| Symbol | Ratings | Value | Unit |
|-----------|------------------------------|-------------|------|
| T_{STG} | Storage temperature range | -65 to +150 | °C |
| T_J | Maximum junction temperature | 150 | °C |

5.3. Operating conditions

5.3.1. General operating conditions

Table 5-4 General operating conditions

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------|---|------------|------|-----|------|
| f_{HCLK} | Internal AHB clock frequency | - | 0 | 72 | MHz |
| f_{PCLK} | Internal APB clock frequency | - | 0 | 72 | MHz |
| V_{CC} | Standard operating voltage | - | 1.8 | 5.5 | V |
| V_{REFP} | ADC/DAC reference voltage | - | 1.8 | 5.5 | V |
| V_{IN} | Input voltage on Tolerant IO (COM_T,COM_FT) | - | -0.3 | 5.5 | V |

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------|---------------------------------|------------|------|--------------|------|
| | Input voltage on any other pins | - | -0.3 | $V_{CC}+0.3$ | |
| T_A | Ambient temperature | - | -40 | 105 | °C |
| T_J | Junction temperature | - | -40 | 110 | °C |

5.3.2. Operating conditions at power-on / power-down

Table 5-5 Operating conditions at power-on / power-down

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|-----------------------------|-----|----------|-----------------|
| t_{VCC} | V_{CC} rise time rate | - | 10 | ∞ | $\mu\text{s/V}$ |
| | V_{CC} fall time rate | V_{CC} drop synchronously | 20 | ∞ | |

5.3.3. Embedded reset and PVD module characteristics

Table 5-6 POR/PDR/BOR module characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------------------|-------------------------------------|---------------------------------|---------------------|------|---------------------|------|
| $t_{RSTEMPO}^{(1)}$ | Reset temporization | - | - | 4.0 | 7.5 | ms |
| $V_{POR/PDR}$ | Power-on/power-down reset threshold | Rising edge | 1.55 ⁽²⁾ | 1.63 | 1.74 | V |
| | | Falling edge | 1.50 | 1.60 | 1.70 ⁽²⁾ | V |
| $V_{PDRhyst}^{(2)}$ | PDR hysteresis | - | - | 30 | - | mV |
| V_{BOR} | BOR threshold | BOR_LEV[2:0]=000 (Rising edge) | 1.65 ⁽²⁾ | 1.75 | 1.84 | V |
| | | BOR_LEV[2:0]=000 (Falling edge) | 1.56 | 1.65 | 1.74 ⁽²⁾ | |
| | | BOR_LEV[2:0]=001 (Rising edge) | 1.84 ⁽²⁾ | 1.95 | 2.06 | |
| | | BOR_LEV[2:0]=001 (Falling edge) | 1.75 | 1.85 | 1.96 ⁽²⁾ | |
| | | BOR_LEV[2:0]=010 (Rising edge) | 2.02 ⁽²⁾ | 2.14 | 2.26 | |
| | | BOR_LEV[2:0]=010 (Falling edge) | 1.93 | 2.04 | 2.15 ⁽²⁾ | |
| | | BOR_LEV[2:0]=011 (Rising edge) | 2.21 ⁽²⁾ | 2.34 | 2.46 | |
| | | BOR_LEV[2:0]=011 (Falling edge) | 2.11 | 2.23 | 2.36 ⁽²⁾ | |
| | | BOR_LEV[2:0]=100 (Rising edge) | 2.59 ⁽²⁾ | 2.74 | 2.89 | |
| | | BOR_LEV[2:0]=100 (Falling edge) | 2.48 | 2.62 | 2.77 ⁽²⁾ | |
| | | BOR_LEV[2:0]=101 (Rising edge) | 2.87 ⁽²⁾ | 3.04 | 3.2 | |
| | | BOR_LEV[2:0]=101 (Falling edge) | 2.76 | 2.92 | 3.08 ⁽²⁾ | |
| | | BOR_LEV[2:0]=110 (Rising edge) | 3.4 ⁽²⁾ | 3.6 | 3.8 | |
| | | BOR_LEV[2:0]=110 (Falling edge) | 3.33 | 3.52 | 3.72 ⁽²⁾ | |
| BOR_LEV[2:0]=111 (Rising edge) | 3.88 ⁽²⁾ | 4.11 | 4.34 | | | |
| BOR_LEV[2:0]=111 (Falling edge) | 3.78 | 4 | 4.22 ⁽²⁾ | | | |
| $V_{BORhyst}^{(2)}$ | BOR hysteresis | - | - | 100 | - | mV |

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

Table 5-7 PVD module characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------------|----------------|-----------------------------|---------------------|------|---------------------|------|
| V _{PVD} | PVD threshold | PLS[2:0]=000 (Rising edge) | 1.65 ⁽¹⁾ | 1.75 | 1.84 | V |
| | | PLS[2:0]=000 (Falling edge) | 1.56 | 1.65 | 1.74 ⁽¹⁾ | |
| | | PLS[2:0]=001 (Rising edge) | 1.84 ⁽¹⁾ | 1.95 | 2.06 | |
| | | PLS[2:0]=001 (Falling edge) | 1.75 | 1.85 | 1.96 ⁽¹⁾ | |
| | | PLS[2:0]=010 (Rising edge) | 2.02 ⁽¹⁾ | 2.14 | 2.26 | |
| | | PLS[2:0]=010 (Falling edge) | 1.93 | 2.04 | 2.15 ⁽¹⁾ | |
| | | PLS[2:0]=011 (Rising edge) | 2.21 ⁽¹⁾ | 2.34 | 2.46 | |
| | | PLS[2:0]=011 (Falling edge) | 2.11 | 2.23 | 2.36 ⁽¹⁾ | |
| | | PLS[2:0]=100 (Rising edge) | 2.59 ⁽¹⁾ | 2.74 | 2.89 | |
| | | PLS[2:0]=100 (Falling edge) | 2.48 | 2.62 | 2.77 ⁽¹⁾ | |
| | | PLS[2:0]=101 (Rising edge) | 2.87 ⁽¹⁾ | 3.04 | 3.2 | |
| | | PLS[2:0]=101 (Falling edge) | 2.76 | 2.92 | 3.08 ⁽¹⁾ | |
| | | PLS[2:0]=110 (Rising edge) | 3.4 ⁽¹⁾ | 3.6 | 3.8 | |
| | | PLS[2:0]=110 (Falling edge) | 3.33 | 3.52 | 3.72 ⁽¹⁾ | |
| | | PLS[2:0]=111 (Rising edge) | 3.88 ⁽¹⁾ | 4.11 | 4.34 | |
| PLS[2:0]=111 (Falling edge) | 3.78 | 4 | 4.22 ⁽¹⁾ | | | |
| V _{PVDhyst} ⁽¹⁾ | PVD hysteresis | - | - | 100 | - | mV |

1. Data based on characterization results, not tested in production.

5.3.4. Supply current characteristics

Table 5-8 Current consumption in Run mode

| Symbol | Conditions | | | | | | Typ ⁽¹⁾ | | | Unit | |
|--------------------------|------------|----------|----------------------------|----------------------------|----------------------------|----------------|------------------------|------------------------|-------------------------|------|------|
| | Run | Code | Peripheral | System clock | Frequency (MHz) | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | | |
| I _{cc} (Run) | Flash | While(1) | All peripherals enable | PLL ⁽²⁾ | 72 | MR_VSE = 2'b00 | 10.57 | 10.72 | 10.84 | mA | |
| | | | | | 64 | MR_VSE = 2'b00 | 9.45 | 9.65 | 9.77 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 7.20 | 7.36 | 7.48 | | |
| | | | | HSI | 64 | MR_VSE = 2'b00 | 9.23 | 9.37 | 9.46 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 6.98 | 7.18 | 7.28 | | |
| | | | | | 24 | MR_VSE = 2'b00 | 3.66 | 3.80 | 3.94 | | |
| | | | | | 16 | MR_VSE = 2'b00 | 2.53 | 2.67 | 2.83 | | |
| | | | | | 8 | MR_VSE = 2'b10 | 1.25 | 1.35 | 1.49 | | |
| | | | | | LSI(FLASH_LPCR.SLEEP_EN=0) | 32.768 kHz | MR_VSE = 2'b10 | 0.20 | 0.33 | | 0.48 |
| | | | | LSI(FLASH_LPCR.SLEEP_EN=1) | 32.768 kHz | MR_VSE = 2'b10 | 0.14 | 0.27 | 0.42 | | |
| | | | | All peripherals disable | PLL ⁽²⁾ | 72 | MR_VSE = 2'b00 | 5.01 | 5.26 | | 5.39 |
| | | | | | | 64 | MR_VSE = 2'b00 | 4.50 | 4.66 | | 4.78 |
| | | | 48 | | | MR_VSE = 2'b00 | 3.47 | 3.68 | 3.82 | | |
| | | | HSI | | 64 | MR_VSE = 2'b00 | 4.45 | 4.63 | 4.75 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 3.36 | 3.55 | 3.68 | | |
| | | | | | 24 | MR_VSE = 2'b00 | 1.85 | 2.04 | 2.21 | | |
| | | | | | 16 | MR_VSE = 2'b00 | 1.30 | 1.50 | 1.68 | | |
| | | | | | 8 | MR_VSE = 2'b10 | 0.71 | 0.84 | 0.99 | | |
| | | | | | LSI(FLASH_LPCR.SLEEP_EN=0) | 32.768 kHz | MR_VSE = 2'b10 | 0.18 | 0.33 | | 0.48 |
| | | | LSI(FLASH_LPCR.SLEEP_EN=1) | | 32.768 kHz | MR_VSE = 2'b10 | 0.13 | 0.27 | 0.42 | | |

1. Data based on characterization results, not tested in production.

2. HSI 8M is the reference clock source of PLL.

Table 5-9 Current consumption in Low-power run mode

| Sym- bol | Conditions | | | | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | | Unit |
|--------------------------|------------|----------|-------------------------|--------------|-----------------|--------------------|------------------------|------------------------|-------------------------|------|
| | Run | Code | Peripheral | System clock | Frequency (MHz) | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (LPR) | Flash | While(1) | All peripherals enable | MSI | 2 | LPR_VSEL = 2'b00 | 0.49 | 0.67 | 0.87 | mA |
| | | | | | 1 | LPR_VSEL = 2'b10 | 0.36 | 0.54 | 0.74 | |
| | | | | | 250 kHz | LPR_VSEL = 2'b10 | 0.26 | 0.45 | 0.64 | |
| | | | | | 62.5 kHz | LPR_VSEL = 2'b10 | 0.24 | 0.42 | 0.62 | |
| | | | All peripherals disable | MSI | 2 | LPR_VSEL = 2'b00 | 0.35 | 0.53 | 0.72 | |
| | | | | | 1 | LPR_VSEL = 2'b10 | 0.29 | 0.47 | 0.67 | |
| | | | | | 250 kHz | LPR_VSEL = 2'b10 | 0.25 | 0.43 | 0.62 | |
| | | | | | 62.5 kHz | LPR_VSEL = 2'b10 | 0.23 | 0.42 | 0.61 | |

1. Data based on characterization results, not tested in production.

Table 5-10 Current consumption in Sleep mode

| Symbol | Conditions | | | | | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | | Unit |
|----------------------------|------------|----------|-------------------------|--------------------|-----------------|----------------|------------------------|------------------------|-------------------------|----|------|
| | Run | Code | Peripheral | System clock | Frequency (MHz) | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | | |
| I _{cc} (Sleep) | Flash | While(1) | All peripherals enable | PLL ⁽²⁾ | 72 | MR_VSE = 2'b00 | 8.08 | 8.45 | 8.57 | mA | |
| | | | | | 64 | MR_VSE = 2'b00 | 7.23 | 7.56 | 7.69 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 5.51 | 5.80 | 5.93 | | |
| | | | | HSI | 64 | MR_VSE = 2'b00 | 7.05 | 7.35 | 7.46 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 5.35 | 5.62 | 5.74 | | |
| | | | | | 24 | MR_VSE = 2'b00 | 2.83 | 3.04 | 3.20 | | |
| | | | | | 16 | MR_VSE = 2'b00 | 1.97 | 2.17 | 2.34 | | |
| | | | | | 8 | MR_VSE = 2'b10 | 0.99 | 1.14 | 1.28 | | |
| | | | | | LSI | 32.768 kHz | MR_VSE = 2'b10 | 0.18 | 0.33 | | 0.48 |
| | | | All peripherals disable | PLL ⁽²⁾ | 72 | MR_VSE = 2'b00 | 2.15 | 2.34 | 2.51 | | |
| | | | | | 64 | MR_VSE = 2'b00 | 1.94 | 2.14 | 2.31 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 1.54 | 1.73 | 1.91 | | |
| | | | | HSI | 64 | MR_VSE = 2'b00 | 1.91 | 2.10 | 2.27 | | |
| | | | | | 48 | MR_VSE = 2'b00 | 1.49 | 1.68 | 1.86 | | |
| | | | | | 24 | MR_VSE = 2'b00 | 0.90 | 1.09 | 1.28 | | |
| | | | | | 16 | MR_VSE = 2'b00 | 0.68 | 0.87 | 1.06 | | |
| | | | | | 8 | MR_VSE = 2'b10 | 0.42 | 0.58 | 0.73 | | |
| | | | | | LSI | 32.768 kHz | MR_VSE = 2'b10 | 0.18 | 0.33 | | 0.48 |

1. Data based on characterization results, not tested in production.

2. HSI 8M is the reference clock source of PLL.

Table 5-11 Current consumption in Low-power sleep mode

| Symbol | Conditions | | | | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | | Unit |
|--------------------------|------------|----------|-------------------------|--------------|-----------------|--------------------|------------------------|------------------------|-------------------------|------|
| | Run | Code | Peripheral | System clock | Frequency (MHz) | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{CC} (LPS) | Flash | While(1) | All peripherals enable | MSI | 2 | LPR_VSEL = 2'b00 | 0.43 | 0.64 | 0.80 | mA |
| | | | | | 1 | LPR_VSEL = 2'b10 | 0.33 | 0.51 | 0.70 | |
| | | | | | 250 kHz | LPR_VSEL = 2'b10 | 0.25 | 0.45 | 0.62 | |
| | | | | | 62.5 kHz | LPR_VSEL = 2'b10 | 0.23 | 0.41 | 0.60 | |
| | | | All peripherals disable | MSI | 2 | LPR_VSEL = 2'b00 | 0.27 | 0.50 | 0.69 | |
| | | | | | 1 | LPR_VSEL = 2'b10 | 0.25 | 0.44 | 0.64 | |
| | | | | | 250 kHz | LPR_VSEL = 2'b10 | 0.23 | 0.41 | 0.60 | |
| | | | | | 62.5 kHz | LPR_VSEL = 2'b10 | 0.22 | 0.41 | 0.59 | |

1. Data based on characterization results, not tested in production.

Table 5-12 Current consumption in Stop0 mode

| Symbol | Conditions | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | Unit |
|-------------------------|-----------------------------|-------------------|------------------------|------------------------|-------------------------|------|
| | - | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (Stop0) | RTC + IWDG + LPTIM with LSI | LPR_VSEL = 2'b11 | 40.2 | 198.6 | 332.2 | μA |
| | IWDG with LSI | LPR_VSEL = 2'b11 | 39.9 | 198.2 | 332.4 | |
| | LPTIM with LSI | LPR_VSEL = 2'b11 | 40.1 | 198.4 | 332.3 | |
| | RTC with LSI | LPR_VSEL = 2'b11 | 40.1 | 198.3 | 332.3 | |
| | Peripheral I shutdown | LPR_VSEL = 2'b11 | 39.7 | 197.9 | 332.6 | |
| | RTC + IWDG + LPTIM with LSI | DLPR_VSEL = 2'b00 | 13.1 | 165.9 | 334.9 | |
| | IWDG with LSI | DLPR_VSEL = 2'b01 | 10.3 | 126.5 | 272.8 | |
| | LPTIM with LSI | DLPR_VSEL = 2'b01 | 10.5 | 126.7 | 273.1 | |
| | RTC with LSI | DLPR_VSEL = 2'b01 | 10.4 | 126.6 | 273.0 | |
| | Peripheral I shutdown | DLPR_VSEL = 2'b01 | 10.1 | 126.3 | 272.6 | |

1. Data based on characterization results, not tested in production.

Table 5-13 Current consumption in Stop1 mode

| Symbol | Conditions | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | Unit |
|-------------------------|-----------------------------|-------------------|------------------------|------------------------|-------------------------|------|
| | - | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (Stop1) | RTC + IWDG + LPTIM with LSI | LPR_VSEL = 2'b11 | 38.2 | 152.0 | 288.9 | μA |
| | IWDG with LSI | LPR_VSEL = 2'b11 | 37.9 | 151.7 | 288.6 | |
| | LPTIM with LSI | LPR_VSEL = 2'b11 | 38.1 | 151.9 | 288.9 | |
| | RTC with LSI | LPR_VSEL = 2'b11 | 38.0 | 151.8 | 288.6 | |
| | Peripheral shutdown | LPR_VSEL = 2'b11 | 37.7 | 151.5 | 288.4 | |
| | RTC + IWDG + LPTIM with LSI | DLPR_VSEL = 2'b00 | 12.4 | 122.8 | 260.9 | |
| | IWDG with LSI | DLPR_VSEL = 2'b01 | 7.73 | 91.1 | 196.0 | |
| | LPTIM with LSI | DLPR_VSEL = 2'b01 | 7.8 | 91.3 | 196.3 | |
| | RTC with LSI | DLPR_VSEL = 2'b01 | 7.8 | 91.3 | 196.2 | |
| | Peripheral shutdown | DLPR_VSEL = 2'b01 | 7.5 | 90.9 | 195.9 | |

1. Data based on characterization results, not tested in production.

Table 5-14 Current consumption in Stop2 mode

| Symbol | Conditions | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | Unit |
|-------------------------|-----------------------------|-------------------|------------------------|------------------------|-------------------------|------|
| | - | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (Stop2) | RTC + IWDG + LPTIM with LSI | LPR_VSEL = 2'b11 | 36.2 | 142.6 | 266.0 | μA |
| | IWDG with LSI | LPR_VSEL = 2'b11 | 36.0 | 142.2 | 265.4 | |
| | LPTIM with LSI | LPR_VSEL = 2'b11 | 36.1 | 142.5 | 265.9 | |
| | RTC with LSI | LPR_VSEL = 2'b11 | 36.1 | 142.4 | 265.7 | |
| | Peripheral shutdown | LPR_VSEL = 2'b11 | 35.5 | 142.0 | 265.2 | |
| | RTC + IWDG + LPTIM with LSI | DLPR_VSEL = 2'b00 | 10.3 | 113.2 | 235.2 | |
| | IWDG with LSI | DLPR_VSEL = 2'b01 | 7.4 | 87.4 | 183.8 | |
| | LPTIM with LSI | DLPR_VSEL = 2'b01 | 7.5 | 87.6 | 184.0 | |
| | RTC with LSI | DLPR_VSEL = 2'b01 | 7.5 | 87.6 | 183.9 | |
| | Peripheral shutdown | DLPR_VSEL = 2'b01 | 7.2 | 87.2 | 184.4 | |

1. Data based on characterization results, not tested in production.

Table 5-15 Current consumption in Stop3 mode

| Symbol | Conditions | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | Unit |
|-------------------------|-----------------------------|-------------------|------------------------|------------------------|-------------------------|------|
| | - | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (Stop3) | RTC + IWDG + LPTIM with LSI | LPR_VSEL = 2'b11 | 34.2 | 97.5 | 171.7 | μA |
| | IWDG with LSI | LPR_VSEL = 2'b11 | 33.9 | 97.1 | 171.1 | |
| | LPTIM with LSI | LPR_VSEL = 2'b11 | 34.1 | 97.3 | 171.5 | |
| | RTC with LSI | LPR_VSEL = 2'b11 | 34.0 | 97.3 | 171.4 | |
| | Peripheral shutdown | LPR_VSEL = 2'b11 | 33.6 | 96.9 | 171.0 | |
| | RTC + IWDG + LPTIM with LSI | DLPR_VSEL = 2'b00 | 6.6 | 67.4 | 140.6 | |
| | IWDG with LSI | DLPR_VSEL = 2'b01 | 4.7 | 52.0 | 109.8 | |
| | LPTIM with LSI | DLPR_VSEL = 2'b01 | 4.8 | 52.2 | 110.0 | |
| | RTC with LSI | DLPR_VSEL = 2'b01 | 4.8 | 52.1 | 110.0 | |
| | Peripheral shutdown | DLPR_VSEL = 2'b01 | 4.5 | 51.8 | 110.2 | |

1. Data based on characterization results, not tested in production.

Table 5-16 Current consumption in Standby mode

| Symbol | Conditions | | Typ ⁽¹⁾ | Max ⁽¹⁾ | | Unit |
|---------------------------|---------------------|-------------------|------------------------|------------------------|-------------------------|------|
| | - | Voltage mode | T _A = 25 °C | T _A = 85 °C | T _A = 105 °C | |
| I _{cc} (Standby) | RTC + IWDG with LSI | DLPR_VSEL = 2'b01 | 3.1 | 27.7 | 57.3 | μA |
| | IWDG with LSI | DLPR_VSEL = 2'b01 | 3.0 | 27.6 | 57.2 | |
| | RTC with LSI | DLPR_VSEL = 2'b01 | 3.1 | 27.7 | 57.3 | |
| | Peripheral shutdown | DLPR_VSEL = 2'b01 | 2.9 | 27.4 | 56.8 | |

1. Data based on characterization results, not tested in production.

Table 5-17 Current consumption in TK mode

| Symbol | Conditions | | | | | Typ ⁽¹⁾⁽²⁾ | Max | Unit |
|----------------------|---------------------------------------|-------------------------|------------------------|--------------|-----------------|-----------------------|-----|------|
| | Mode | Voltage mode(Stop mode) | Voltage mode(Run mode) | System clock | Frequency (MHz) | | | |
| I _{cc} (TK) | From Stop2 to Run mode | DLPR_VSEL = 2'b01 | MR_VSE = 2'b10 | HSI | 8.0 | 14.2 | - | μA |
| | From Stop3 to Run mode ⁽³⁾ | DLPR_VSEL = 2'b01 | MR_VSE = 2'b10 | | 8.0 | 13.1 | - | |

1. Data based on characterization results, not tested in production.

2. Test in V_{CC} = 5 V, T_A = 25 °C.

3. Only SRAM1 is reserved for use in this mode condition, SRAM2 will be powered down and data cannot be saved.

5.3.5. Wake-up time from low-power mode

Table 5-18 Wake-up time from low-power mode

| Symbol | Parameter ⁽¹⁾ | Power Supply ⁽²⁾ | Conditions | Typ ⁽³⁾ | Max | Unit |
|-----------------------------------|--|---|-------------------------------------|-----------------------------|-----|------------|
| t _{WUSLEEP} | Wake-up from Sleep mode to Run mode in Flash | | | 10 | - | CPU cycles |
| t _{WULPSLEEP} | Wake-up time from Low-power sleep mode to Low-power run mode | | | 10 | - | |
| t _{WULPRUN} | Wake-up from Low-power run to Run mode in Flash | Regulator in LPR,LPR_VSEL = 00/10 | HSI (8 MHz) as system clock | 5 | - | μs |
| t _{WUSTOP⁽⁴⁾} | Wake-up from Stop0 to Run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 13 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 20 | - | |
| | Wake-up from Stop1 to Run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 13 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 20 | - | |
| | Wake-up from Stop2 to Run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 14 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 21 | - | |
| | Wake-up from Stop3 to Run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 14 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 21 | - | |
| | Wake-up from Stop0 to Low-power run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 22 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 30 | - | |
| | Wake-up from Stop1 to Low-power run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 23 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 31 | - | |
| | Wake-up from Stop2 to Low-power run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 31 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 39 | - | |
| | Wake-up from Stop3 to Low-power run mode in Flash | Regulator in LPR,LPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 31 | - | |
| | | Regulator in DLPR,DLPR_VSEL = 00/01 | MSI (2 MHz) as system clock | 39 | - | |
| | t _{WUSTB} | Wake-up from Standby to Run mode in Flash(Load after power-on) | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 230 | |
| | | Wake-up from Standby to Run mode in Flash(no load after power-on) | Regulator in DLPR,DLPR_VSEL = 00/01 | HSI (8 MHz) as system clock | 25 | - |

1. The wake-up time is measured from the wake-up time until the first instruction is read by the user program.
2. Power supply mode before wake-up.
3. Data based on characterization results, not tested in production.
4. PWR_CR1.HSION_CTRL = 1'b1, PWR_CR1.FLS_SLPTIME = 2'b00 when Regulator in LPR.
PWR_CR1.HSION_CTRL=1'b0, PWR_CR1.FLS_SLPTIME=2'b01 when Regulator in DLPR.

5.3.6. External clock source characteristics

5.3.6.1. High-speed external clock generated from an external source

In bypass mode of HSE (the HSEBYP of RCC_CR is set), when the high-speed start-up circuit in the device stops working, the corresponding I/O is used as a standard GPIO.

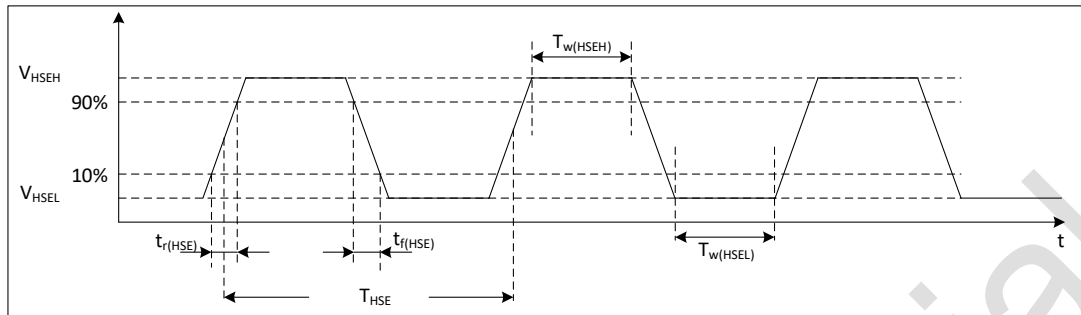


Figure 5-2 High-speed external clock timing diagram

Table 5-19 High-speed external clock characteristics⁽¹⁾

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------------------------|---------------------------------|--------------------|-----|--------------------|------|
| f_{HSE_ext} | External clock source frequency | 1 | 8 | 32 | MHz |
| V_{HSEH} | Input pin high level voltage | $0.7 \cdot V_{CC}$ | - | V_{CC} | V |
| V_{HSEL} | Input pin low level voltage | V_{SS} | - | $0.3 \cdot V_{CC}$ | |
| $t_w^{(HSEH)}$ $t_w^{(HSEL)}$ | High or low time | 15 | - | - | ns |
| $t_r^{(HSE)}$ $t_f^{(HSE)}$ | Rise or fall time | - | - | 20 | ns |

1. Guaranteed by design, not tested in production.

5.3.6.2. Low-speed external clock generated from an external source

In the bypass mode of LSE (the LSEBYP of RCC_BDCR is set), the low-speed start-up circuit in the device stops working, and the corresponding I/O is used as a standard GPIO.

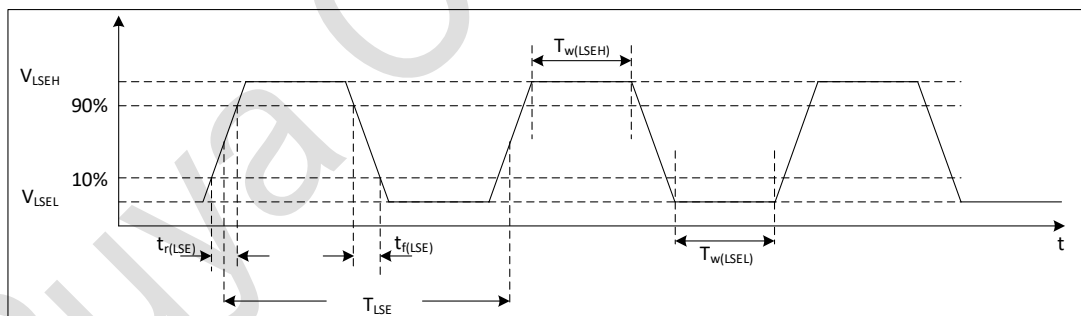


Figure 5-3 Low-speed external clock timing diagram

Table 5-20 Low-speed external clock characteristics⁽¹⁾

| Symbol | Parameter ⁽¹⁾ | Min | Typ | Max | Unit |
|----------------------------------|---------------------------------|--------------------|--------|--------------------|------|
| f_{LSE_ext} | External clock source frequency | - | 32.768 | 1000 | kHz |
| V_{LSEH} | Input pin high level voltage | $0.7 \cdot V_{CC}$ | - | - | V |
| V_{LSEL} | Input pin low level voltage | - | - | $0.3 \cdot V_{CC}$ | V |
| $t_w^{(LSEH)}$ $t_w^{(LSEL)}$ | High or low time | 450 | - | - | ns |
| $t_r^{(LSE)}$ $t_f^{(LSE)}$ | Rise or fall time | - | - | 50 | ns |

1. Guaranteed by design, not tested in production.

5.3.6.3. High-speed external clock generated from a crystal/ceramic resonator

The high-speed external (HSE) clock can be supplied with 4 to 32 MHz crystal/ceramic resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-21 HSE oscillator characteristics

| Symbol | Parameter | Conditions ⁽¹⁾ | Min ⁽²⁾ | Typ | Max ⁽²⁾ | Unit |
|---|-------------------------|--|--------------------|------|--------------------|------|
| f _{OSC_IN} | Oscillator frequency | - | 4 | - | 32 | MHz |
| I _{CC} ⁽⁴⁾ | HSE current consumption | Startup time | - | - | 5.5 | mA |
| | | V _{CC} =3.3 V, R _m =100 Ω, C _L =12 pF@4 MHz, HSE_DRV[1:0] = 00 | - | 0.5 | - | |
| | | V _{CC} =3.3 V, R _m =150 Ω, C _L =12 pF@8 MHz, HSE_DRV[1:0] = 00 | - | 0.59 | - | |
| | | V _{CC} =3.3 V, R _m =150 Ω, C _L =12 pF@8 MHz, HSE_DRV[1:0] = 01 | - | 1.1 | - | |
| | | V _{CC} =3.3 V, R _m =70 Ω, C _L =12 pF@16 MHz, HSE_DRV[1:0] = 01 | - | 1.28 | - | |
| | | V _{CC} =3.3 V, R _m =40 Ω, C _L =20 pF@24 MHz, HSE_DRV[1:0] = 10 | - | 1.55 | - | |
| | | V _{CC} =3.3 V, R _m =40 Ω, C _L =10 pF@32 MHz, HSE_DRV[1:0] = 10 | - | 1.46 | - | |
| t _{SU(HSE)} ^{(3) (4)} | Startup time | V _{CC} =3.3 V, R _m =100 Ω, C _L =12 pF@4 MHz, HSE_DRV[1:0] = 00 | - | 2.6 | - | ms |
| | | V _{CC} =3.3 V, R _m =150 Ω, C _L =12 pF@8 MHz, HSE_DRV[1:0] = 00 | - | 6.04 | - | |
| | | V _{CC} =3.3 V, R _m =150 Ω, C _L =12 pF@8 MHz, HSE_DRV[1:0] = 01 | - | 1.54 | - | |
| | | V _{CC} =3.3 V, R _m =70 Ω, C _L =12 pF@16 MHz, HSE_DRV[1:0] = 01 | - | 1.8 | - | |
| | | V _{CC} =3.3 V, R _m =40 Ω, C _L =20 pF@24 MHz, HSE_DRV[1:0] = 10 | - | 0.7 | - | |
| | | V _{CC} =3.3 V, R _m =40 Ω, C _L =10 pF@32 MHz, HSE_DRV[1:0] = 10 | - | 0.4 | - | |

1. Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.

2. Guaranteed by design, not tested in production.

3. t_{SU(HSE)} is the startup time from enable (by software) to when the clock oscillation reaches a stable state, measured for a standard crystal/resonator, which can vary considerably from one crystal/resonator to another.

4. Data based on characterization results, not tested in production.

5.3.6.4. Low-speed external clock generated from a crystal resonator

The low-speed external (LSE) clock can be supplied with a 32.768 kHz crystal resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-22 LSE oscillator characteristics

| Symbol | Parameter | Conditions ⁽¹⁾ | Min ⁽²⁾ | Typ | Max ⁽²⁾ | Unit |
|--------------------------------|-------------------------|--|--------------------|-----|--------------------|------|
| I _{CC} ⁽⁴⁾ | LSE current consumption | C _L =6 pF, R _m =70 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 00 | - | 320 | - | nA |
| | | C _L =6 pF, R _m =70 kΩ | - | 520 | - | |

| Symbol | Parameter | Conditions ⁽¹⁾ | Min ⁽²⁾ | Typ | Max ⁽²⁾ | Unit |
|--|--------------|---|--------------------|------|--------------------|------|
| | | LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 01 | | | | |
| | | C _L =12 pF, R _m =45 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 10 | - | 720 | - | |
| | | C _L =12 pF, R _m =45 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 11 | - | 1130 | - | |
| t _{SU(LSE)} ⁽³⁾⁽⁴⁾ | Startup time | C _L =6 pF, R _m =70 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 00 | - | 1.3 | - | s |
| | | C _L =6 pF, R _m =70 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 01 | - | 0.6 | - | |
| | | C _L =12 pF, R _m =45 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 10 | - | 0.9 | - | |
| | | C _L =12 pF, R _m =45 kΩ LSE_STARTUP [1:0] = 00 LSE_DRIVER [1:0] = 11 | - | 0.5 | - | |

- Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.
- Guaranteed by design, not tested in production.
- t_{SU(LSE)} is the startup time from enable (by software) to when the clock oscillation reaches a stable, measured for a standard crystal/resonator, which may vary greatly from crystal to resonator.
- Data based on characterization results, not tested in production.

5.3.7. High-speed internal (HSI) RC oscillator

Table 5-23 HSI oscillator characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------------|---|--|---------------------|-------------------------------------|--------------------|------|
| f _{HSI} | HSI frequency | - | - | 8.0 16.0 24.0 48.0 64.0 | - | MHz |
| ΔTemp(HSI) | HSI 16/24/48 MHz frequency drift over temperature | V _{CC} = 3.3 V, T _A = 25 °C | -1 ⁽²⁾ | - | 1 ⁽²⁾ | % |
| | | V _{CC} = 2.0 to 5.5 V, T _A = -20 to 85 °C | -2 ⁽²⁾ | - | 2 ⁽²⁾ | |
| | | V _{CC} = 1.8 to 5.5 V, T _A = -40 to 105 °C | -3 ⁽²⁾ | - | 3 ⁽²⁾ | |
| | HSI 8/64 MHz frequency drift over temperature | V _{CC} = 3.3 V, T _A = 25 °C | -1 ⁽²⁾ | - | 1 ⁽²⁾ | |
| | | V _{CC} = 2.0 to 5.5 V, T _A = -20 to 105 °C | -2.5 ⁽²⁾ | - | 2.5 ⁽²⁾ | |
| | | V _{CC} = 1.8 to 5.5 V, T _A = -40 to 105 °C | -5 ⁽²⁾ | - | 5 ⁽²⁾ | |
| f _{TRIM} ⁽¹⁾ | HSI trimming step | - | 0.02 | 0.1 | 0.2 | % |
| D _{HSI} ⁽¹⁾ | Duty cycle | - | 45 ⁽¹⁾ | - | 55 ⁽¹⁾ | % |
| t _{Stab(HSI)} | HSI stabilization time | - | - | 3 | 4 ⁽¹⁾ | μs |
| I _{CC(HSI)} ⁽²⁾ | HSI power consumption | 8 MHz | - | 108 | - | μA |
| | | 16 MHz | - | 164 | - | |
| | | 24 MHz | - | 221 | - | |
| | | 48 MHz | - | 326 | - | |
| | | 64 MHz | - | 436 | - | |

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

5.3.8. Medium-speed internal (MSI) RC oscillator

Table 5-24 MSI oscillator characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------------|--------------------------------------|--|---------------------|-----|--------------------|---------------|
| f_{MSI} | MSI frequency | - | - | 2.0 | - | MHz |
| $\Delta_{Temp(MSI)}$ | MSI frequency drift over temperature | $V_{CC} = 3.3\text{ V}, T_A = 25\text{ }^\circ\text{C}$ | -1 ⁽²⁾ | - | 1 ⁽²⁾ | % |
| | | $V_{CC} = 1.8\text{ to }5.5\text{ V}, T_A = 0\text{ to }85\text{ }^\circ\text{C}$ | -3 ⁽²⁾ | - | 3 ⁽²⁾ | |
| | | $V_{CC} = 1.8\text{ to }5.5\text{ V}, T_A = -40\text{ to }105\text{ }^\circ\text{C}$ | -4.5 ⁽²⁾ | - | 4.5 ⁽²⁾ | |
| $f_{TRIM}^{(1)}$ | MSI trimming step | - | 0.02 | 0.1 | 0.2 | % |
| $D_{MSI}^{(1)}$ | Duty cycle | - | 45 ⁽¹⁾ | - | 55 ⁽¹⁾ | % |
| $t_{Stab(MSI)}$ | MSI stabilization time | - | - | 6 | 10 ⁽¹⁾ | μs |
| $I_{CC(MSI)}^{(2)}$ | MSI power consumption | 2 MHz | - | 26 | - | μA |

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

5.3.9. Low-speed internal (LSI) RC oscillator

Table 5-25 LSI oscillator characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--------------------------------------|--|-------------------|--------|------------------|---------------|
| f_{LSI} | LSI frequency | - | - | 32.768 | - | kHz |
| $\Delta_{Temp(LSI)}$ | LSI frequency drift over temperature | $T_A = 25\text{ }^\circ\text{C}, V_{CC} = 3.3\text{ V}$ | -3 ⁽²⁾ | - | 3 ⁽²⁾ | % |
| | | $V_{CC} = 1.8\text{ to }5.5\text{ V}, T_A = 0\text{ to }85\text{ }^\circ\text{C}$ | -4 ⁽²⁾ | - | 4 ⁽²⁾ | |
| | | $V_{CC} = 1.8\text{ to }5.5\text{ V}, T_A = -40\text{ to }105\text{ }^\circ\text{C}$ | -7 ⁽²⁾ | - | 7 ⁽²⁾ | |
| $f_{TRIM}^{(1)}$ | LSI trimming step | - | - | 0.2 | - | % |
| $t_{Stab(LSI)}^{(1)}$ | LSI stabilization time | - | - | 150 | - | μs |
| $I_{CC(LSI)}^{(1)}$ | LSI power consumption | - | - | 300 | - | nA |

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

5.3.10. Phase locked loop (PLL) characteristics

Table 5-26 PLL characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|------------------|---|-------------------|-----|-------------------|---------------|
| f_{PLL_IN} | PLL input clock | $T_A = 25\text{ }^\circ\text{C}, V_{CC} = 3.3\text{ V}$ | 8 ⁽¹⁾ | - | 24 ⁽¹⁾ | MHz |
| f_{PLL_OUT} | PLL output clock | $T_A = 25\text{ }^\circ\text{C}, V_{CC} = 3.3\text{ V}$ | 48 ⁽¹⁾ | - | 72 | MHz |
| t_{LOCK} | PLL lock time | $f_{PLL_IN} = 24\text{ MHz}$ | - | 20 | 40 ⁽¹⁾ | μs |

1. Guaranteed by design, not tested in production.

5.3.11. Memory characteristics

Table 5-27 Memory characteristics

| Symbol | Parameter | Conditions | Typ | Max ⁽¹⁾ | Unit |
|-------------|---------------------------------------|------------|-----|--------------------|------|
| t_{prog} | Page programming time | - | 1.0 | 1.5 | ms |
| t_{ERASE} | Page/sector/mass erase time | - | 3.5 | 4.5 | ms |
| I_{CC} | Page programming supply current | - | 2.0 | 3.0 | mA |
| | Page/sector/mass erase supply current | - | 2.0 | 3.0 | |

1. Guaranteed by design, not tested in production.

Table 5-28 Memory endurance and data retention

| Symbol | Parameter | Conditions | Min ⁽¹⁾ | Unit |
|------------------|---------------------|-----------------------------------|--------------------|---------|
| N _{END} | Endurance | T _A = -40 to 85 °C | 100 | kcycles |
| | | T _A = 85 to 105 °C | 10 | |
| t _{RET} | Data retention time | 10 kcycles T _A = 55 °C | 20 | Years |

1. Data based on characterization results, not tested in production.

5.3.12. EFT characteristics

Table 5-29 EFT characteristics

| Symbol | Parameter | Conditions | Grade |
|--------------|-----------|--------------|-------|
| EFT to Power | - | IEC61000-4-4 | 4A |

5.3.13. ESD & LU characteristics

Table 5-30 ESD & LU characteristics

| Symbol | Parameter | Standards | Conditions | Typ | Unit |
|-----------------------|---|------------------------|--|-----|------|
| V _{ESD(HBM)} | Static discharge voltage (human body model) | ESDA/JEDEC JS-001-2017 | Any other pins except Tolerant IO and V _{BKP} domain pins | 8 | kV |
| | | | Tolerant IO and PA6/PA7/PA8 pins in V _{BKP} domain | 6 | |
| V _{ESD(CDM)} | Static discharge voltage (charged device model) | ESDA/JEDEC JS-002-2018 | - | 1 | kV |
| LU | Static Latch-up | JESD78E | - | 200 | mA |

5.3.14. I/O port characteristics

Table 5-31 IO port characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|--------------------------------------|---|-----------------------------------|---|-----|---------------------|------|----|
| V _{IL} | Low level input voltage | 1.8 V ≤ V _{CC} ≤ 5.5 V | - | - | 0.3*V _{CC} | V | |
| | Tolerant I/O input low level | | | | | | |
| V _{IH} | High level input voltage | 1.8 V ≤ V _{CC} ≤ 5.5 V | 0.7*V _{CC} | - | - | V | |
| | Tolerant I/O input high level | | | | | | |
| V _{hys} ⁽¹⁾ | Schmitt trigger hysteresis | - | - | 200 | - | mV | |
| | Tolerant I/O Schmitt trigger hysteresis | | | | | | |
| I _{lkg} ⁽²⁾ | Input leakage current | Standard I/O | V _{SS} ≤ V _{IN} ≤ V _{CC} | - | - | ±1 | μA |
| | | Tolerant I/O | V _{SS} ≤ V _{IN} ≤ V _{CC} | - | - | ±1 | |
| | | | V _{CC} ≤ V _{IN} ≤ V _{CC} +1 V ⁽⁴⁾ | - | - | 3 | |
| | | | V _{CC} +1 V ≤ V _{IN} ≤ 5.5 V | - | - | 1 | |
| R _{PU} ⁽³⁾ | Internal pull-up resistor | V _{IN} = V _{SS} | 30 | 50 | 70 | kΩ | |
| R _{PD} ⁽³⁾ | Internal pull-down resistor | V _{IN} = V _{CC} | 30 | 50 | 70 | kΩ | |
| C _{IO} | Pin capacitance | - | - | 5 | - | pF | |
| t _{ns(EXTI)} ⁽¹⁾ | Input filter width | ENI=1, ENS=1 | 3 | 5 | 10 | ns | |
| t _{ns(I2C)} ⁽¹⁾ | I ² C input filter width | ENI=1, EIIC=1 | 100 | 145 | 300 | ns | |

1. Guaranteed by design, not tested in production.
2. If there is reverse current pouring in adjacent pins, the leakage current may be higher than the maximum value.
3. The pull-up and pull-down resistors are designed to be a real resistor in series with a switchable PMOS/NMOS.

4. The maximum value of $V_{CC}+1$ V should not exceed 5.5 V.

 Table 5-32 Output voltage characteristics⁽³⁾

| Symbol | Parameter ⁽¹⁾ | Driver | Conditions | Min | Max | Unit |
|-------------------|--|------------------|--------------------------------------|--------------|-----|------|
| $V_{OL}^{(2)}$ | Output low level voltage for an I/O pin(all I/Os except COM_L) | GPIOx_OSPEEDR=11 | $I_{OL} = 50$ mA, $V_{CC} \geq 5$ V | - | 0.4 | V |
| | | GPIOx_OSPEEDR=11 | $I_{OL} = 8$ mA, $V_{CC} \geq 2.7$ V | - | 0.4 | |
| | | GPIOx_OSPEEDR=11 | $I_{OL} = 4$ mA, $V_{CC} = 1.8$ V | - | 0.5 | |
| $V_{OL}^{(2)}$ | Output low level voltage for an I/O pin(COM_L) | GPIOx_OSPEEDR=11 | $I_{OL} = 120$ mA, $V_{CC} \geq 5$ V | - | 0.6 | |
| | | GPIOx_OSPEEDR=10 | $I_{OL} = 100$ mA, $V_{CC} \geq 5$ V | - | 0.5 | |
| | | GPIOx_OSPEEDR=01 | $I_{OL}=80$ mA, $V_{CC} \geq 5$ V | - | 0.5 | |
| | | GPIOx_OSPEEDR=00 | $I_{OL}=60$ mA, $V_{CC} \geq 5$ V | - | 0.4 | |
| $V_{OH}^{(2)(4)}$ | Output low level voltage for an I/O pin | GPIOx_OSPEEDR=11 | $I_{OL} =16$ mA, $V_{CC} \geq 3.3$ V | $V_{CC}-0.6$ | - | |
| | | GPIOx_OSPEEDR=11 | $I_{OL} = 8$ mA, $V_{CC} \geq 2.7$ V | $V_{CC}-0.4$ | - | |
| | | GPIOx_OSPEEDR=11 | $I_{OL} = 4$ mA, $V_{CC} = 1.8$ V | $V_{CC}-0.5$ | - | |

- These I/O types refer to the terms and symbols defined by pins.
- Data based on characterization results, not tested in production.
- The combined maximum current across all output pins (including contributions from both V_{OL} and V_{OH} states) must not exceed the $\Sigma I_{O(PIN)}$ maximum rating specified in [Table 5-2 Current Characteristics](#).
- Excluding PA6/PA7/PA8 in V_{BKP} domain, which are powered via a current-limited switch (3 mA sourcing).

5.3.15. Constant current LED SEG driver characteristics

 Table 5-33 Constant current LED SEG driver characteristics⁽¹⁾

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|--|-----|-----|----------|------|
| V_{CC} | Supply voltage | - | 3.3 | - | 5.5 | V |
| I_{OH} | Constant current mode 1 current | $V_{CC} = 3.3$ V, $V_{OH} = V_{CC}/3$ | - | 9.9 | - | mA |
| I_{OH} | Constant current mode 2 current | $V_{CC} = 3.3$ V, $V_{OH} = V_{CC}/3$ | - | 7.4 | - | mA |
| I_{OH} | Constant current mode 3 current | $V_{CC} = 3.3$ V, $V_{OH} = V_{CC}/3$ | - | 5 | - | mA |
| I_{OH} | Constant current mode 4 current | $V_{CC} = 3.3$ V, $V_{OH} = V_{CC}/3$ | - | 2.5 | - | mA |
| $ \Delta I /I$ | Current accuracy (unified calibration) | Constant current source outputs 10 mA current: $(I_{OH}-10) /10$ ($V_{CC} = 3.3$ V, $T_A = +25$ °C) | - | - | ± 15 | % |

- Data based on characterization results, not tested in production.

5.3.16. ADC characteristics

Table 5-34 ADC characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|----------------------------|------------------------------|-----|-----|----------|------|
| V_{CC} | Analog power supply | - | 1.8 | - | 5.5 | V |
| V_{REFP} | Positive reference voltage | - | 1.8 | - | V_{CC} | V |
| V_{REFN} | Negative reference voltage | - | 0 | | | V |
| I_{CC} | V_{CC} pin current | $f_{ADC} = 16$ MHz | - | 1 | - | mA |
| | | $f_{ADC} = 32$ MHz | - | 1 | - | |
| f_{ADC} | ADC clock frequency | 1.8 V $\leq V_{CC}$ <5.5 V | 4 | - | 8 | MHz |
| | | 2.5 V $\leq V_{CC}$ <5.5 V | 4 | - | 16 | |
| | | 2.7 V $\leq V_{CC}$ <5.5 V | 4 | - | 32 | |
| $f_S^{(2)}$ | Sampling rate | $V_{CC} \geq 1.8$ V | - | - | 0.5 | MSPS |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------|---|-----------------------------|-------------|-----|------------|---------------|
| | | $V_{CC} \geq 2.5 \text{ V}$ | - | - | 1 | |
| | | $V_{CC} \geq 2.7 \text{ V}$ | - | - | 2 | |
| V_{AIN} | Conversion voltage range ⁽³⁾ | Single-ended mode | 0 | - | V_{REFP} | V |
| | | Differential mode | $-V_{REFP}$ | - | V_{REFP} | |
| $R_{AIN}^{(2)}$ | External input impedance ⁽⁴⁾ | - | - | - | 33 | k Ω |
| $R_{ADC}^{(2)}$ | Sampling switch resistance | - | - | - | 1.2 | k Ω |
| $C_{ADC}^{(2)}$ | Internal sampling and holding capacitor | - | - | 2.5 | 3 | pF |
| $t_{CAL}^{(2)}$ | Calibration time | $f_{ADC} = 16 \text{ MHz}$ | 12 | | | μs |
| | | - | 192 | | | $1/f_{ADC}$ |
| $t_S^{(2)}$ | Sampling time | $f_{ADC} = 16 \text{ MHz}$ | 0.156 | - | 40.03 | μs |
| | | - | 2.5 | - | 640.5 | $1/f_{ADC}$ |
| $t_{\text{samp_setup}}$ | Sampling time for internal channels | - | 20 | - | - | μs |
| $t_{\text{STAB}}^{(2)}$ | Power-on stabilization time | - | 0 | 0 | 3 | μs |
| $t_{\text{CONV}}^{(2)}$ | Total conversion time | $f_{ADC} = 16 \text{ MHz}$ | 1 | - | 40.875 | μs |
| | | - | 16 to 654 | | | $1/f_{ADC}$ |

- Guaranteed by design, not tested in production.
- Data based on characterization results, not tested in production.
- For some package types, V_{REFP} can be internally connected to V_{CC} , and V_{REFN} can be internally connected to V_{SS} . For details, please refer to the pin definitions.
- When using external triggering, an additional delay of $1/f_{PCLK2}$ is required.
 - $R_{AIN} < \frac{T_S}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$
 - The formula above (Equation 1) is used to determine the maximum external impedance allowed for an error below 1/4 of LSB. N = 12 (referring to 12-bit resolution).

 Table 5-35 R_{AIN} Max for $f_{ADC} = 32 \text{ MHz}^{(1)}$

| Sampling period (T_S) | Sampling time (t_S)(ns) | Maximum value of R_{AIN} (Ω) | |
|---------------------------|-----------------------------|---|--------------|
| | | Fast channel | Slow channel |
| 2.5 | 78.13 | 100 | - |
| 6.5 | 203.13 | 330 | 100 |
| 12.5 | 390.63 | 680 | 470 |
| 24.5 | 765.63 | 1500 | 1200 |
| 47.5 | 1484.38 | 2200 | 1800 |
| 92.5 | 2890.63 | 4700 | 3900 |
| 247.5 | 7734.38 | 12000 | 10000 |
| 640.5 | 20015.63 | 39000 | 33000 |

- Guaranteed by design, not tested in production.

 Table 5-36 ADC static characteristics($(V_{REF} = V_{CC})^{(1)(2)(3)}$)

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit |
|--------|------------------------|---|-------------------|-----|-----------|-----|------|
| ET | Total unadjusted error | $V_{REFP} = V_{CC} = 3.3 \text{ V}$, $f_{ADC} \leq 32 \text{ MHz}$, 12-bit resolution | Single-ended mode | - | ± 4.0 | - | LSB |
| | | | Differential mode | - | ± 3.0 | - | |
| EO | Offset error | | Single-ended mode | - | ± 5.0 | - | |
| | | | Differential mode | - | ± 4.0 | - | |

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit |
|--------|------------------------------|------------|-------------------|-----|-------------|-----|------|
| EG | Gain error | | Single-ended mode | - | ±2.0 | - | |
| | | | Differential mode | - | ±1.5 | - | |
| DNL | Differential linearity error | | Single-ended mode | - | -1.0 to 2.5 | - | |
| | | | Differential mode | - | -1.0 to 2.0 | - | |
| INL | Integral linearity error | | Single-ended mode | - | ±2.5 | - | |
| | | | Differential mode | - | ±5.0 | - | |

1. Guaranteed by design, not tested in production.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy and reverse injection current: Reverse current injection on any standard analog input pin should be avoided, as it will significantly reduce the conversion accuracy of the ongoing conversion on another analog input pin. It is recommended to add a Schottky diode (between the pin and ground) to the standard analog input pins where reverse injection current may occur.

Table 5-37 ADC static characteristics ($V_{REFP} = V_{REFBUF}$)⁽¹⁾⁽²⁾⁽³⁾

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit | |
|--------|------------------------------|--|--|-------------------|-------------|------|------|---|
| ET | Total unadjusted error | $V_{CC} = 3.3\text{ V}$, $V_{REFP} = V_{REFBUF} = 0.6\text{ V}$, $f_{ADC} \leq 32\text{ MHz}$, 12-bit resolution | Single-ended mode | - | ±6.0 | - | LSB | |
| | | | Differential mode | - | ±5.0 | - | | |
| EO | Offset error | | Single-ended mode | - | ±2.5 | - | | |
| | | | Differential mode | - | ±1.0 | - | | |
| EG | Gain error | | Single-ended mode | - | ±3.0 | - | | |
| | | | Differential mode | - | ±2.0 | - | | |
| DNL | Differential linearity error | | Single-ended mode | - | -1.0 to 3.6 | - | | |
| | | | Differential mode | - | -1.0 to 3.5 | - | | |
| INL | Integral linearity error | | Single-ended mode | - | ±3.5 | - | | |
| | | | Differential mode | - | ±3.5 | - | | |
| ET | Total unadjusted error | | $V_{CC} = 3.3\text{ V}$, $V_{REFP} = V_{REFBUF} = 1.024/1.5/2.048/2.5\text{ V}$, $f_{ADC} \leq 32\text{ MHz}$, 12-bit resolution | Single-ended mode | - | ±3.0 | | - |
| | | | | Differential mode | - | ±2.5 | | - |
| EO | Offset error | Single-ended mode | | - | ±2.0 | - | | |
| | | Differential mode | | - | ±2.0 | - | | |
| EG | Gain error | Single-ended mode | | - | ±1.5 | - | | |
| | | Differential mode | | - | ±1.5 | - | | |
| DNL | Differential linearity error | Single-ended mode | | - | -1.0 to 2.5 | - | | |
| | | Differential mode | | - | -1.0 to 2.5 | - | | |
| INL | Integral linearity error | Single-ended mode | | - | ±3.0 | - | | |
| | | Differential mode | | - | ±3.0 | - | | |

1. Guaranteed by design, not tested in production.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy and reverse injection current: Reverse current injection on any standard analog input pin should be avoided, as it will significantly reduce the conversion accuracy of the ongoing conversion on another analog input pin. It is recommended to add a Schottky diode (between the pin and ground) to the standard analog input pins where reverse injection current may occur.

Table 5-38 ADC dynamic characteristics ($V_{REFP} = V_{CC}$)⁽¹⁾⁽²⁾⁽³⁾

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit |
|--------|--------------------------------------|---|-------------------|-----|-------|-----|------|
| ENOB | Effective number of bits | $V_{REFP} = V_{CC} = 3.3 V$, $f_{ADC} \leq 32 MHz$, 12-bit resolution | Single-ended mode | - | 10.0 | - | bit |
| | | | Differential mode | - | 10.3 | - | |
| SINAD | Signal to noise and distortion ratio | | Single-ended mode | - | 62.0 | - | dB |
| | | | Differential mode | - | 63.5 | - | |
| SNR | Signal to noise ratio | | Single-ended mode | - | 62.3 | - | |
| | | | Differential mode | - | 63.7 | - | |
| SFDR | Spurious free dynamic range | | Single-ended mode | - | 80.4 | - | |
| | | | Differential mode | - | 79.6 | - | |
| THD | Total harmonic distortion | | Single-ended mode | - | -73.9 | - | |
| | | | Differential mode | - | -76.6 | - | |
| ENOB | Effective number of bits | $V_{REFP} = V_{CC} = 3.3 V$, $f_{ADC} \leq 32 MHz$, 12-bit resolution, Run in SRAM | Single-ended mode | - | 11.0 | - | bit |
| | | | Differential mode | - | 11.3 | - | |
| SINAD | Signal to noise and distortion ratio | | Single-ended mode | - | 68.1 | - | dB |
| | | | Differential mode | - | 67.0 | - | |
| SNR | Signal to noise ratio | | Single-ended mode | - | 68.5 | - | |
| | | | Differential mode | - | 70.7 | - | |
| SFDR | Spurious free dynamic range | | Single-ended mode | - | 83.6 | - | |
| | | | Differential mode | - | 81.7 | - | |
| THD | Total harmonic distortion | | Single-ended mode | - | -78.7 | - | |
| | | | Differential mode | - | -77.4 | - | |

1. Guaranteed by design, not tested in production.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy and reverse injection current: Reverse current injection on any standard analog input pin should be avoided, as it will significantly reduce the conversion accuracy of the ongoing conversion on another analog input pin. It is recommended to add a Schottky diode (between the pin and ground) to the standard analog input pins where reverse injection current may occur.

Table 5-39 ADC dynamic characteristics ($V_{REFP} = V_{REFBUF}$)⁽¹⁾⁽²⁾⁽³⁾

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit |
|--------|--------------------------------------|---|-------------------|-----|-------|-----|------|
| ENOB | Effective number of bits | $V_{CC} = 3.3 V$, $V_{REFP} = V_{REFBUF} = 0.6 V$, $f_{ADC} \leq 32 MHz$, 12-bit resolution | Single-ended mode | - | 8.0 | - | bit |
| | | | Differential mode | - | 9.8 | - | |
| SINAD | Signal to noise and distortion ratio | | Single-ended mode | - | 49.8 | - | dB |
| | | | Differential mode | - | 61.1 | - | |
| SNR | Signal to noise ratio | | Single-ended mode | - | 49.8 | - | |
| | | | Differential mode | - | 61.1 | - | |
| SFDR | Spurious free dynamic range | | Single-ended mode | - | 85.4 | - | |
| | | | Differential mode | - | 89.1 | - | |
| THD | Total harmonic distortion | | Single-ended mode | - | -81.2 | - | |
| | | | Differential mode | - | -84.1 | - | |

| Symbol | Parameter | Conditions | Mode | Min | Typ | Max | Unit |
|--------|--------------------------------------|--|-------------------|-----|-------|-----|------|
| ENOB | Effective number of bits | $V_{CC} = 3.3\text{ V}$, $V_{REFP} = V_{REFBUF} = 1.024\text{ V}$, $f_{ADC} \leq 32\text{ MHz}$, 12-bit resolution | Single-ended mode | - | 9.0 | - | bit |
| | | | Differential mode | - | 10.3 | - | |
| SINAD | Signal to noise and distortion ratio | | Single-ended mode | - | 56.0 | - | dB |
| | | | Differential mode | - | 64.0 | - | |
| SNR | Signal to noise ratio | | Single-ended mode | - | 56.0 | - | |
| | | | Differential mode | - | 64.1 | - | |
| SFDR | Spurious free dynamic range | | Single-ended mode | - | 84.6 | - | |
| | | | Differential mode | - | 87.8 | - | |
| THD | Total harmonic distortion | | Single-ended mode | - | -81.6 | - | |
| | | | Differential mode | - | -81.3 | - | |
| ENOB | Effective number of bits | $V_{CC} = 3.3\text{ V}$, $V_{REFP} = V_{REFBUF} = 1.5/2.048/2.5\text{ V}$, $f_{ADC} \leq 32\text{ MHz}$, 12-bit resolution | Single-ended mode | - | 9.3 | - | bit |
| | | | Differential mode | - | 10.7 | - | |
| SINAD | Signal to noise and distortion ratio | | Single-ended mode | - | 57.7 | - | dB |
| | | | Differential mode | - | 66.5 | - | |
| SNR | Signal to noise ratio | | Single-ended mode | - | 57.7 | - | |
| | | | Differential mode | - | 67.5 | - | |
| SFDR | Spurious free dynamic range | | Single-ended mode | - | 83.6 | - | |
| | | | Differential mode | - | 74.2 | - | |
| THD | Total harmonic distortion | | Single-ended mode | - | -79.4 | - | |
| | | | Differential mode | - | -73.0 | - | |

1. Guaranteed by design, not tested in production.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy and reverse injection current: Reverse current injection on any standard analog input pin should be avoided, as it will significantly reduce the conversion accuracy of the ongoing conversion on another analog input pin. It is recommended to add a Schottky diode (between the pin and ground) to the standard analog input pins where reverse injection current may occur.

5.3.17. DAC characteristics

 Table 5-40 DAC characteristics ($V_{REFP} = V_{CC}$)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|-------------------------------|---|-----|-----|-----|------------|
| V_{CC} | DAC supply voltage | Buffer ON | 2.2 | - | 5.5 | V |
| | DAC supply voltage | Buffer OFF | 2.2 | - | 5.5 | |
| $R_{LOAD}^{(1)}$ | Resistive load with buffer ON | Load connected to V_{SS} | 5 | - | - | k Ω |
| | | Load connected to V_{CC} | 15 | - | - | |
| $R_O^{(1)}$ | DAC output load | The minimum resistive load between DAC_OUT and V_{SS} to have a 1% accuracy is 1.5 M Ω when the buffer is OFF. | - | - | 15 | k Ω |
| $C_{LOAD}^{(1)}$ | Capacitive load | Maximum capacitive load at DAC_OUT pin (When the buffer is ON). | - | - | 50 | pF |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------------|---|--|-----|-----|-----------------------|------|
| DAC_OUT_min ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | Give the maximum output excursion of the DAC | 0.2 | - | - | V |
| DAC_OUT_max ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | | - | - | V _{CC} -0.2 | V |
| DAC_OUT_min ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | Give the maximum output excursion of the DAC | - | 0.5 | - | mV |
| DAC_OUT_max ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | | - | - | V _{CC} -0.01 | V |
| I _{CC} ⁽¹⁾ | V _{CC} consumption ⁽²⁾ | With no load, middle code (0x800) on the inputs | - | - | 900 | μA |
| | | With no load, worst code (0xF1C) at V _{CC} = 3.6 V in terms of DC consumption on the input | - | - | 1200 | |
| DNL ⁽²⁾ | Differential linearity error | Given for the DAC in 8 bits configuration | - | - | ±1 | LSB |
| | | Given for the DAC in 12 bits configuration | - | - | ±2 | |
| INL ⁽²⁾ | Integral linearity error | Given for the DAC in 8 bits configuration | - | - | ±1 | LSB |
| | | Given for the DAC in 12 bits configuration | - | - | ±4 | |
| Offset ⁽²⁾ | Offset error | Given for the DAC in 8 bits configuration | - | - | ±3 | LSB |
| | | Given for the DAC in 12 bits configuration | - | - | ±12 | |
| Gain error ⁽²⁾ | Gain error | Given for the DAC in 12 bits configuration | - | - | ±0.5 | % |
| t _{SETTLING} ⁽²⁾ | Settling time | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ Full scale: for a input code transition between the lowest and the highest input codes when DAC_OUT reaches final value ±1LSB | - | 4 | 10 | μs |
| Update rate ⁽²⁾ | Max frequency for a correct DAC_OUT change when small variation in the input code (from code i to i+1LSB) | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ | - | - | 1 | MS/s |
| t _{WAKEUP} ⁽²⁾ | Wake-up time | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ, Input code between lowest and highest possible ones. | - | 6.5 | 10 | μs |
| P _{SRR+} ⁽¹⁾ | Power supply rejection ratio (to V _{CC}) (static DC measurement) | No R _{LOAD} , C _{LOAD} = 50 pF | - | -67 | -40 | dB |

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

Table 5-41 DAC characteristics (V_{REFP} = V_{REFBUF} = 2.5 V)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------------------------|--------------------------------------|--|-----|-----|-----|------|
| V _{CC} | DAC supply voltage | Buffer ON | 2.8 | - | 5.5 | V |
| | DAC supply voltage | Buffer OFF | 2.8 | - | 5.5 | |
| R _{LOAD} ⁽¹⁾ | Resistive load with buffer ON | Load connected to V _{SS} | 5 | - | - | kΩ |
| | | Load connected to V _{CC} | 15 | - | - | |
| R _O ⁽¹⁾ | DAC output load | The minimum resistive load between DAC_OUT and V _{SS} to have a 1% accuracy is 1.5 MΩ when the buffer is OFF. | - | - | 15 | kΩ |
| C _{LOAD} ⁽¹⁾ | Capacitive load | Maximum capacitive load at DAC_OUT pin (When the buffer is ON). | - | - | 50 | pF |
| DAC_OUT_min ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | Give the maximum output excursion of the DAC | 0.2 | - | - | V |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------------|---|--|-----|-----|---------------------------|------|
| DAC_OUT_max ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | | - | - | V _{REFBUF} -0.2 | V |
| DAC_OUT_min ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | Give the maximum output excursion of the DAC | - | 0.5 | - | mV |
| DAC_OUT_max ⁽¹⁾ | Highest DAC_OUT voltage (Buffer OFF) | | - | - | V _{REFBUF} -0.01 | V |
| I _{CC} ⁽¹⁾ | V _{CC} consumption ⁽²⁾ | With no load, middle code (0x800) on the inputs | - | - | 900 | μA |
| | | With no load, worst code (0xF1C) at V _{CC} = 3.6 V in terms of DC consumption on the input | - | - | 1200 | |
| DNL ⁽²⁾ | Differential linearity error | Given for the DAC in 8 bits configuration | - | ±1 | - | LSB |
| | | Given for the DAC in 12 bits configuration | - | ±4 | - | |
| INL ⁽²⁾ | Integral linearity error | Given for the DAC in 8 bits configuration | - | ±1 | - | LSB |
| | | Given for the DAC in 12 bits configuration | - | ±4 | - | |
| Offset ⁽²⁾ | Offset error | Given for the DAC in 8 bits configuration | - | - | ±3 | LSB |
| | | Given for the DAC in 12 bits configuration | - | - | ±12 | |
| Gain error ⁽²⁾ | Gain error | Given for the DAC in 12 bits configuration | - | - | ±0.5 | % |
| t _{SETTLING} ⁽²⁾ | Settling time | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ Full scale: for a input code transition between the lowest and the highest input codes when DAC_OUT reaches final value ±1LSB | - | 4 | 10 | μs |
| Update rate ⁽²⁾ | Max frequency for a correct DAC_OUT change when small variation in the input code (from code i to i+1LSB) | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ | - | - | 1 | MS/s |
| t _{WAKEUP} ⁽²⁾ | Wake-up time | C _{LOAD} ≤ 50 pF, R _{LOAD} ≥ 5 kΩ, Input code between lowest and highest possible ones. | - | 6.5 | 10 | μs |
| P _{SRR+} ⁽¹⁾ | Power supply rejection ratio (to V _{CC}) (static DC measurement) | No R _{LOAD} , C _{LOAD} = 50 pF | - | -67 | -40 | dB |

1. Guaranteed by design, not tested in production.

2. Data based on characterization results, not tested in production.

5.3.18. Comparator characteristics

Table 5-42 Comparator characteristics⁽¹⁾

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit | |
|--------------------|---------------------|----------------------------------|-------------------------|-------------------------|------|-----------------|------|----|
| V _{IN} | Input voltage range | | | 0 | - | V _{CC} | V | |
| t _{START} | Startup time | High-speed mode | | - | - | 5 | μs | |
| | | Medium-speed mode | | - | - | 15 | | |
| t _D | Propagation delay | 200 mV step 100 mV over-drive | High-speed mode | V _{CC} ≥ 1.8 V | - | 50 | 2000 | ns |
| | | | | V _{CC} ≥ 2 V | - | | 200 | |
| | | Medium-speed mode | V _{CC} ≥ 1.8 V | - | 1500 | 5000 | | |
| | | | V _{CC} ≥ 2 V | - | | 4000 | | |

| Symbol | Parameter | Conditions | | | Min | Typ | Max | Unit |
|---------------------|--------------------|---|-------------------|----------------------------|---------|----------|------|---------------|
| | | >200 mV step 100 mV overdrive | High-speed mode | $V_{CC} \geq 1.8\text{ V}$ | - | - | 2000 | |
| | | | | $V_{CC} \geq 2\text{ V}$ | - | - | 300 | |
| | | | Medium-speed mode | $V_{CC} \geq 1.8\text{ V}$ | - | - | 5000 | |
| | | | | $V_{CC} \geq 2\text{ V}$ | - | - | 4000 | |
| V_{offset} | Offset voltage | - | - | - | ± 5 | ± 10 | mV | |
| V_{hys} | Hysteresis voltage | No hysteresis | | - | - | 0 | - | mV |
| | | With hysteresis | | - | - | 20 | - | |
| I_{CC} | Consumption | Static | High-speed mode | - | - | 250 | - | μA |
| | | | Medium-speed mode | - | - | 10 | - | |
| | | With 50 kHz and $\pm 100\text{ mV}$ overdrive square signal | High-speed mode | - | - | 250 | - | |
| | | | Medium-speed mode | - | - | 10 | - | |

1. Guaranteed by design, not tested in production.

5.3.19. Operational amplifier characteristics

Table 5-43 OPA characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------|----------------------|---|-----|----------|--------------|------------------|
| V_{CC} | Supply voltage | - | 2.5 | - | 5.5 | V |
| V_{IN} | Input voltage | - | 0 | - | V_{CC} | V |
| V_{OUT} | Output voltage | $C_{LOAD} \leq 25\text{ pF}$, $R_{LOAD} \geq 5\text{ k}\Omega$ | 0.2 | - | $V_{CC}-0.2$ | V |
| I_{LOAD} | Drive current | - | - | - | 1.0 | mA |
| R_{LOAD} | Resister load | - | 5 | - | - | k Ω |
| C_{LOAD} | Capacitive load | - | - | - | 25 | pF |
| t_{start} | Initialization time | $C_{LOAD} \leq 25\text{ pF}$, $R_{LOAD} \geq 5\text{ k}\Omega$ | - | - | 20 | μs |
| V_{IO} | Input offset voltage | $C_{LOAD} \leq 25\text{ pF}$, $R_{LOAD} \geq 5\text{ k}\Omega$ $V_{com}=V_{CC}/2$ | - | ± 10 | - | mV |
| PM | Phase margin | $C_{LOAD} \leq 25\text{ pF}$, $R_{LOAD} \geq 5\text{ k}\Omega$ $V_{com}=V_{CC}/2$ | - | 80 | - | Deg |
| UGBW | Unit gain band width | $C_{LOAD} \leq 25\text{ pF}$, $R_{LOAD} \geq 5\text{ k}\Omega$ $V_{com}=V_{CC}/2$ | - | 10 | - | MHz |
| SR | Slew rate | - | - | 8 | - | V/ μs |

5.3.20. Temperature sensor characteristics

Table 5-44 Temperature sensor characteristics

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------------------|--|-------|---------|---------|------------------------|
| $T_L^{(1)}$ | V_{SENSE} linearity with temperature | - | ± 2 | ± 5 | $^{\circ}\text{C}$ |
| Avg_Slope ⁽¹⁾ | Average slope | 1.9 | 2.5 | 3.5 | mV/ $^{\circ}\text{C}$ |
| V_{30} | Voltage at 30 $^{\circ}\text{C}$ ($\pm 5\text{ }^{\circ}\text{C}$) | 0.742 | 0.76 | 0.785 | V |
| $t_{\text{START}}^{(1)}$ | Start up time | - | 70 | 120 | μs |
| $t_{\text{S_temp}}^{(1)}$ | ADC sampling time when reading the temperature | 20 | - | - | μs |

1. Guaranteed by design, not tested in production.

2. Data based on characterization results, not tested in production.

5.3.21. LCD controller characteristics

Table 5-45 LCD controller characteristics

| Symbol | Parameter | Operating conditions | Min | Typ | Max | Unit |
|-----------------|--|---|-----|------------------|-----|-----------|
| $I_{LCD}^{(4)}$ | LCD supply current | LCD operating current Internal resistance drive mode ⁽¹⁾ | - | 2.6 | - | μA |
| | | External resistance drive mode ⁽²⁾ | - | 0.4 | - | |
| | | External capacitance drive mode ⁽³⁾ | - | 0.5 | - | |
| $R_L^{(4)}$ | Low drive resistance | Internal resistance drive mode | - | 6.2 | - | $M\Omega$ |
| $R_H^{(4)}$ | High drive resistance | Internal resistance drive mode | - | 30 | - | $k\Omega$ |
| C_{ext} | Capacitance of a single external capacitor | External capacitance drive mode | - | 100 | - | nF |
| V_{LCDH} | LCD adjustable highest level voltage | - | - | V_{CC} | - | V |
| V_{LCD3} | LCD highest level voltage | - | - | V_{LCDH} | - | |
| V_{LCD2} | LCD 3/4 level voltage | - | - | $3/4 * V_{LCDH}$ | - | |
| V_{LCD1} | LCD 2/4 level voltage | - | - | $2/4 * V_{LCDH}$ | - | |
| V_{LCD0} | LCD 1/4 level voltage | - | - | $1/4 * V_{LCDH}$ | - | |

1. LCD enabled, $V_{CC} = 3.3 V$, 1/8 duty, 1/4 bias, scanning frequency is 256 Hz, all pixels activated, internal resistance voltage division mode, high drive time. FCCTL [2:0] = 101, no external LCD screen is connected.

2. LCD enabled, $V_{CC} = 3.3 V$, 1/8 duty, 1/4 bias, scanning frequency is 512 Hz, all pixels activated, external resistance voltage division mode, external single-section resistance is 100 $k\Omega$, excluding external resistance current, no external LCD screen is connected.

3. LCD enabled, $V_{CC} = 3.3 V$, 1/8 duty, 1/4 bias, scanning frequency is 512 Hz, all pixels activated, external capacitance voltage division mode, number of times to drive external capacitor SWCAP_DRV_NUM [2:0] = 000, no external LCD screen is connected.

4. Guaranteed by design, not tested in production.

5.3.22. Embedded voltage reference characteristics

Table 5-46 Embedded internal voltage reference (V_{REFINT}) characteristics

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------------|--|------|--------------------|------|------------------|
| V_{REFINT} | Internal reference voltage | 1.17 | 1.2 | 1.23 | V |
| $t_{start_vrefint}$ | Start time of V_{REFINT} | - | 10 | 15 | μs |
| T_{coeff} | Temperature coefficient of V_{REFINT} | - | 150 ⁽¹⁾ | - | ppm/ $^{\circ}C$ |
| I_{VCC} | V_{REFINT} current consumption from V_{CC} | - | 12 | 20 | μA |

1. Guaranteed by design, not tested in production.

Table 5-47 Internal voltage reference buffer (V_{REFBUF}) characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|---|---|-------|-------|-------|------------------|
| V_{REF25} | 2.5 V Internal reference voltage | $T_A = 25^{\circ}C, V_{CC} = 3.3 V$ | 2.455 | 2.5 | 2.545 | V |
| V_{REF20} | 2.048 V Internal reference voltage | $T_A = 25^{\circ}C, V_{CC} = 3.3 V$ | 2.011 | 2.048 | 2.085 | V |
| V_{REF15} | 1.5 V Internal reference voltage | $T_A = 25^{\circ}C, V_{CC} = 3.3 V$ | 1.473 | 1.5 | 1.527 | V |
| $V_{REF1024}$ | 1.024 V Internal reference voltage | $T_A = 25^{\circ}C, V_{CC} = 3.3 V$ | 1.006 | 1.024 | 1.042 | V |
| V_{REF06} | 0.6 V Internal reference voltage | $T_A = 25^{\circ}C, V_{CC} = 3.3 V$ | 0.589 | 0.6 | 0.611 | V |
| $T_{coeff_VREF-}^{(1)}$ T_{coeff_VREF-} $T_{coeff_BUF}^{(1)}$ | Temperature coefficient of V_{REFBUF} | $T_A = -40$ to $105^{\circ}C$, $V_{REFBUF} = 1.024/1.5/2.048/2.5 V$ | - | 150 | - | ppm/ $^{\circ}C$ |
| | | $T_A = -40$ to $105^{\circ}C$, $V_{REFBUF} = 0.6 V$ | - | 300 | - | |
| $t_{start_VREFBUF}$ | Start time of V_{REFBUF} | - | - | 350 | 450 | μs |

1. Guaranteed by design, not tested in production.

5.3.23. COMP Internal voltage reference buffer characteristics(6-bit DAC)

 Table 5-48 Internal voltage reference buffer ($V_{REFCOMP}$) characteristics

| Symbol | Parameter | Conditions | Min | Typ ⁽¹⁾ | Max | Unit |
|------------------|--------------------|------------|-----|--------------------|-----|------|
| ΔV_{abs} | Absolute deviation | - | - | ± 0.5 | - | LSB |

1. Guaranteed by design, not tested in production.

5.3.24. Timer characteristics

Table 5-49 Timer characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|--------------------------------|--------|-----|-----------------|---------------|
| $t_{res(TIM)}$ | Timer resolution time | - | 1 | - | - | $t_{TIMxCLK}$ |
| | | $f_{TIMxCLK} = 72 \text{ MHz}$ | 13.889 | - | - | ns |
| f_{EXT} | Timer external clock frequency on CH1 to CH4 | - | 0 | - | $f_{TIMxCLK}/2$ | MHz |
| | | $f_{TIMxCLK} = 72 \text{ MHz}$ | 0 | - | 36 | |
| $t_{COUNTER}$ | 16-bit counter clock period | - | - | - | 2^{16} | $t_{TIMxCLK}$ |
| | | $f_{TIMxCLK} = 72 \text{ MHz}$ | - | - | 910 | μs |
| | 32-bit counter clock period | - | - | - | 2^{32} | $t_{TIMxCLK}$ |
| | | $f_{TIMxCLK} = 72 \text{ MHz}$ | - | - | 59.65 | s |

Table 5-50 LPTIM1 characteristics (timeout period at 32.768 kHz LSI)

| Prescaler | PRESC[2:0] | Min | Max | Unit |
|-----------|------------|--------|-------------|------|
| /1 | 0 | 0.0305 | 131072000 | ms |
| /2 | 1 | 0.0610 | 262144000 | |
| /4 | 2 | 0.1221 | 524288000 | |
| /8 | 3 | 0.2441 | 1048576000 | |
| /16 | 4 | 0.4883 | 2097152000 | |
| /32 | 5 | 0.9766 | 4194304000 | |
| /64 | 6 | 1.9531 | 8388608000 | |
| /128 | 7 | 3.9063 | 16777216000 | |

Table 5-51 LPTIM2 characteristics (timeout period at 32.768 kHz LSI)

| Prescaler | PRESC[2:0] | Min | Max | Unit |
|-----------|------------|--------|--------|------|
| /1 | 0 | 0.0305 | 2000 | ms |
| /2 | 1 | 0.0610 | 4000 | |
| /4 | 2 | 0.1221 | 8000 | |
| /8 | 3 | 0.2441 | 16000 | |
| /16 | 4 | 0.4883 | 32000 | |
| /32 | 5 | 0.9766 | 64000 | |
| /64 | 6 | 1.9531 | 128000 | |
| /128 | 7 | 3.9063 | 256000 | |

Table 5-52 IWDG characteristics (timeout period at 32.768 kHz LSI)

| Prescaler | PR[2:0] | Min | Max | Unit |
|-----------|---------|-------|-----|------|
| /4 | 0 | 0.122 | 500 | ms |

| Prescaler | PR[2:0] | Min | Max | Unit |
|-----------|---------|-------|-------|------|
| /8 | 1 | 0.244 | 1000 | |
| /16 | 2 | 0.488 | 2000 | |
| /32 | 3 | 0.976 | 4000 | |
| /64 | 4 | 1.952 | 8000 | |
| /128 | 5 | 3.904 | 16000 | |

Table 5-53 WWDG characteristics (timeout period at 48 MHz PCLK)

| Prescaler | WDGTB[1:0] | Min | Max | Unit |
|-----------|------------|-------|--------|------|
| 1*4096 | 0 | 0.085 | 5.461 | ms |
| 2*4096 | 1 | 0.171 | 10.923 | |
| 4*4096 | 2 | 0.341 | 21.845 | |
| 8*4096 | 3 | 0.683 | 43.691 | |

5.3.25. Communication interfaces

5.3.25.1. I²C interface characteristics

I²C interface meets the requirements of the I²C bus specification and user manual:

- Standard-mode (Sm): 100 kHz
- Fast-mode (Fm): 400 kHz
- Fast-mode plus (Fm+): 1 MHz

I²C SDA and SCL pins have analog filtering, see table below.

 Table 5-54 I²C filter characteristics

| Symbol | Parameter | Min | Max | Unit |
|-----------------|--|-----|-----|------|
| t _{AF} | Maximum pulse width of spikes that are suppressed by the analog filter | 50 | 260 | ns |

5.3.25.2. SPI characteristics

Table 5-55 SPI characteristics

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--|-------------------------------|---------------------------------|----------------------|----------------------|------|
| f _{SCK} 1/t _{c(SCK)} | SPI clock frequency | Master mode | - | 36 | MHz |
| | | Slave mode | - | 36 | |
| t _{r(SCK)} t _{f(SCK)} | SPI clock rise and fall time | Capacitive load: C = 15 pF | - | 6 | ns |
| t _{su(NSS)} | NSS setup time | Slave mode | 2*T _{pclk} | - | ns |
| t _{h(NSS)} | NSS hold time | Slave mode | 2*T _{pclk} | - | ns |
| t _{w(SCKH)} t _{w(SCKL)} | SCK high level/low level time | Master mode, presc = 2 | T _{pclk} -2 | T _{pclk} +1 | ns |
| t _{su(MI)} t _{su(SI)} | Data input setup time | Master mode | 1 | - | ns |
| | | Slave mode | 3 | - | |
| t _{h(MI)} t _{h(SI)} | Data input hold time | Master mode | 5 | - | ns |
| | | Slave mode | 2 | - | |
| t _{a(SO)} | Data output access time | Slave mode | 0 | 3*T _{pclk} | ns |
| t _{dis(SO)} | Data output disable time | Slave mode, presc = 2 | 2*T _{pclk} | - | ns |
| t _{v(SO)} t _{v(MO)} | Data output valid time | Slave mode (after enable edge) | 0 | 20 | ns |
| | | Master mode (after enable edge) | - | 5 | ns |
| t _{h(SO)} | Data output hold time | Slave mode | 2 | - | ns |

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-------------|----------------------------------|-------------|-----|-----|------|
| $t_{h(MO)}$ | | Master mode | 1 | - | |
| DuCy(SCK) | SPI slave input clock duty cycle | Slave mode | 45 | 55 | % |

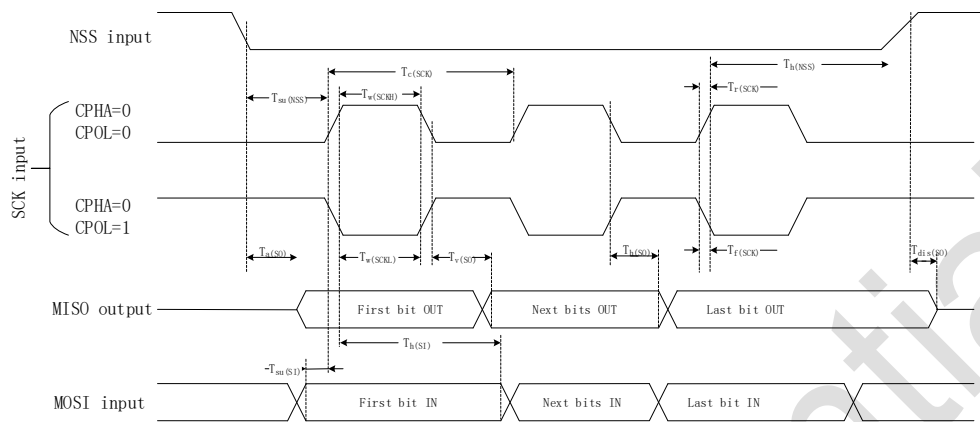


Figure 5-4 SPI timing diagram - Slave mode and CPHA=0

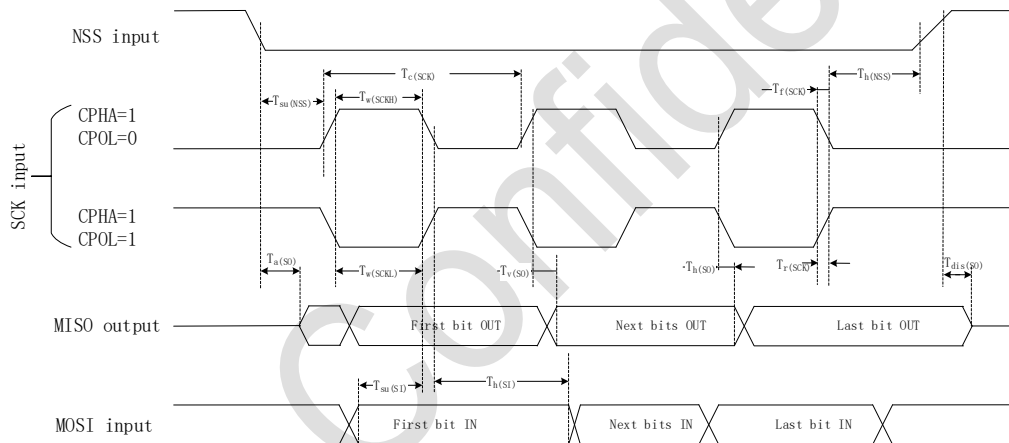


Figure 5-5 SPI timing diagram - Slave mode and CPHA=1

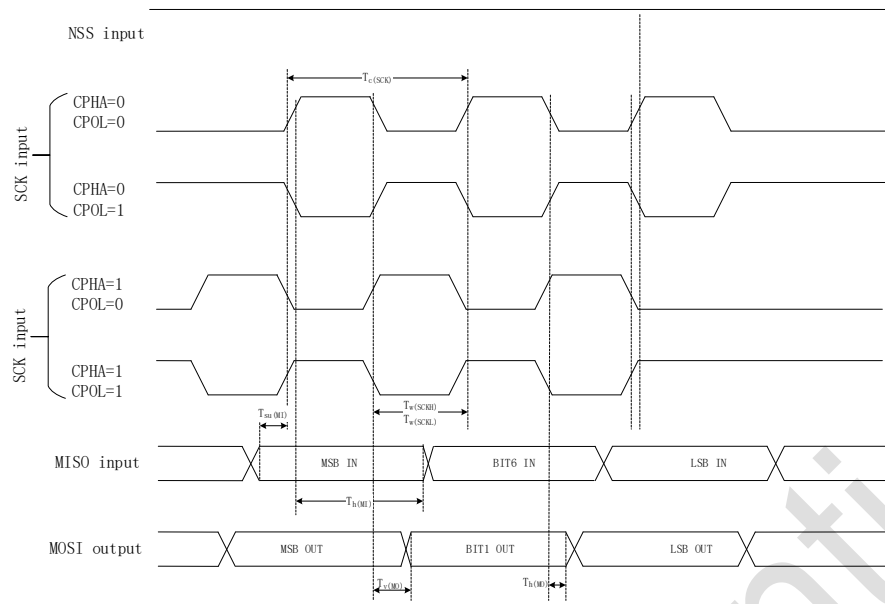


Figure 5-6 SPI timing diagram - Master mode

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5.3.25.3. I²S characteristics

Table 5-56 I²S characteristics

| Symbol | Parameter | Conditions | Min | Max | Unit |
|----------------------------|---|--|------------------|------------------|------|
| f_s | I ² S audio sampling frequency | - | 8 | 192 | kHz |
| f_{MCLK} | I ² S main clock output | - | $256 \times f_s$ | $256 \times f_s$ | kHz |
| f_{CK} $1/t_{c(CK)}$ | I ² S clock frequency | Master mode | - | $64 \times f_s$ | kHz |
| | | Slave mode | - | $64 \times f_s$ | |
| D_{CK} | I ² S clock duty cycle | Slave receiver | 30 | 70 | % |
| $t_{r(CK)}$ $t_{f(CK)}$ | I ² S clock rise and fall time | Capacitive load: $C_L = 50 \text{ pF}$ | - | 8 | ns |
| $t_{v(WS)}$ | WS valid time | Master mode | - | 2 | |
| $t_{h(WS)}$ | WS hold time | Master mode | 3 | - | |
| | | Slave mode | 2 | - | |
| $t_{su(WS)}$ | WS setup time | Slave mode | 4 | - | |
| $t_{su(SD_MR)}$ | Data input setup time | Master mode | 3 | - | |
| $t_{su(SD_SR)}$ | | Slave mode | 4 | - | |
| $t_{h(SD_MR)}$ | Data input hold time | Master mode | 5 | - | |
| $t_{h(SD_SR)}$ | | Slave mode | 2 | - | |
| $t_{v(SD_ST)}$ | Data output valid time | Slave mode (after enable edge) | - | 20 | |
| $t_{v(SD_MT)}$ | | Master mode (after enable edge) | - | 5 | |
| $t_{h(SD_ST)}$ | Data output hold time | Slave mode (after enable edge) | 2 | - | |
| $t_{h(SD_MT)}$ | | Master mode (after enable edge) | 1 | - | |

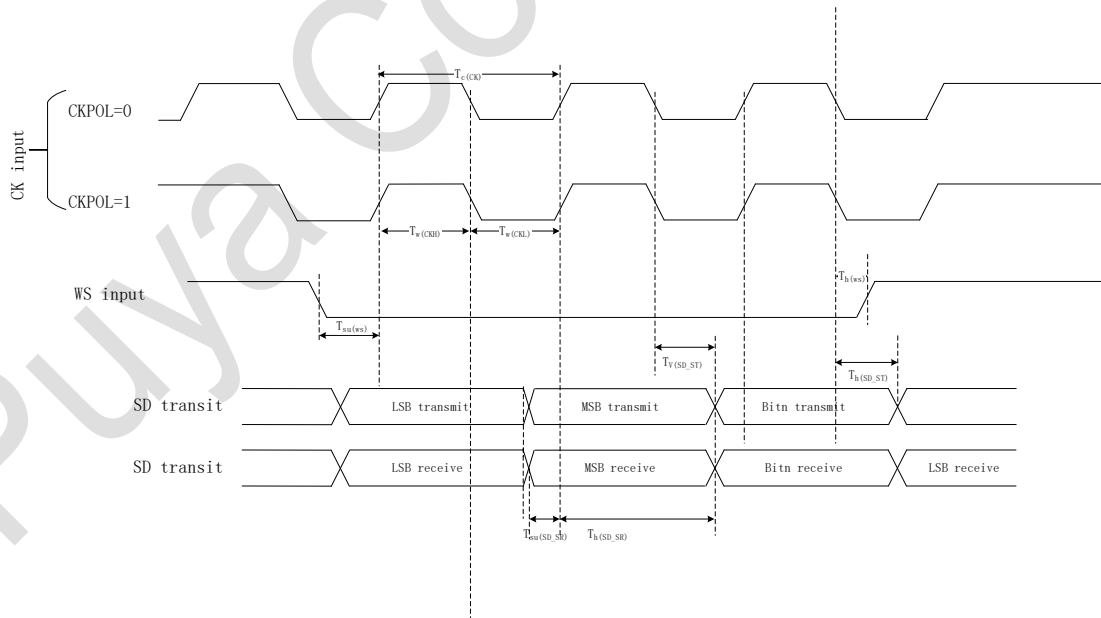


Figure 5-7 I²S timing diagram-Slave mode(Philips protocol)

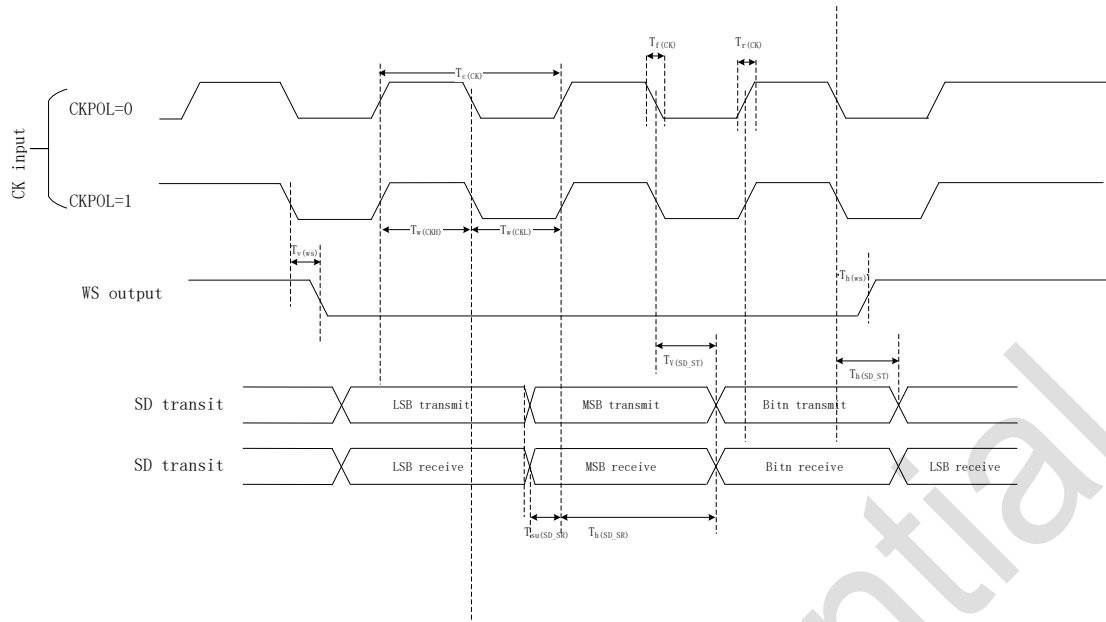
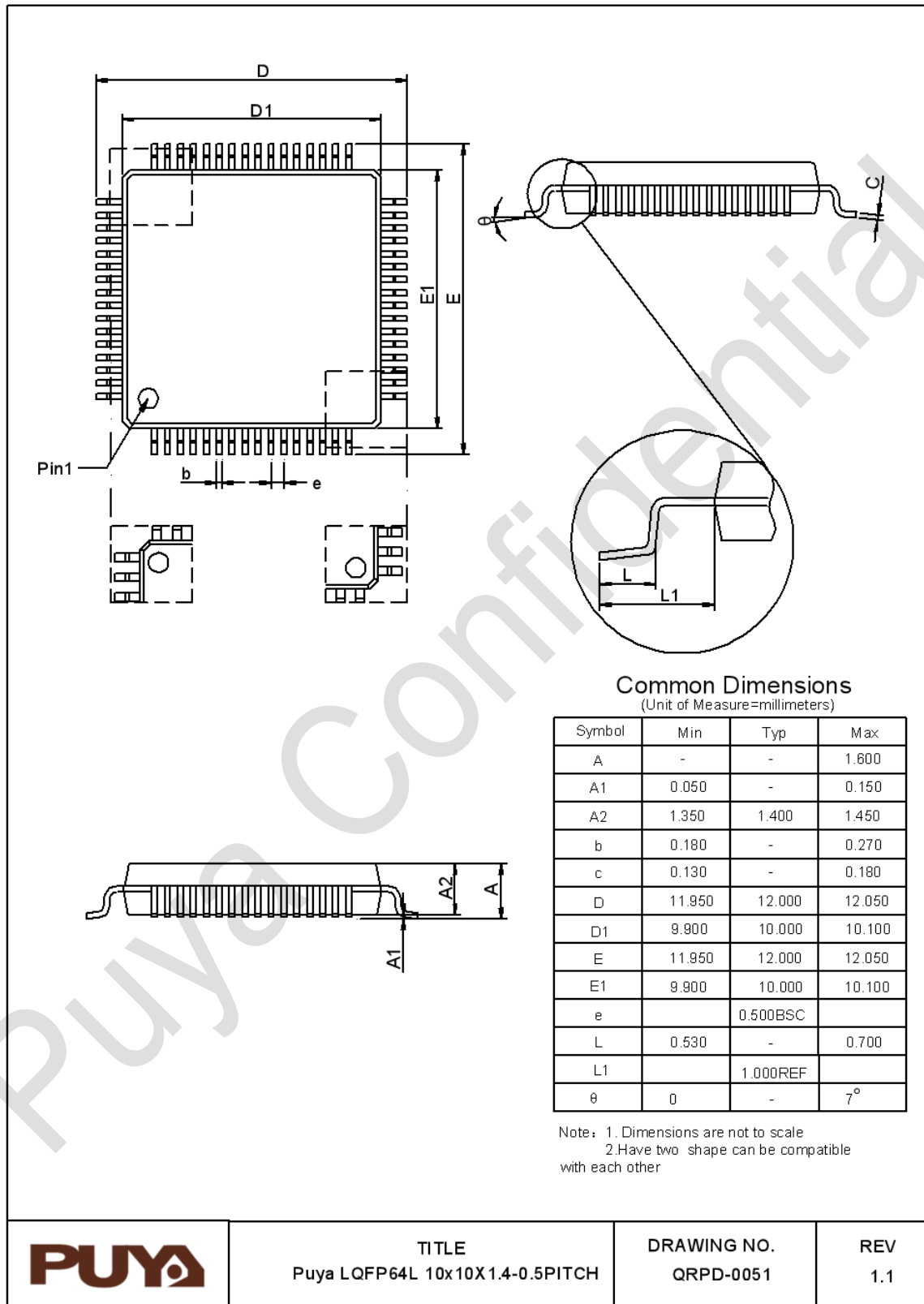


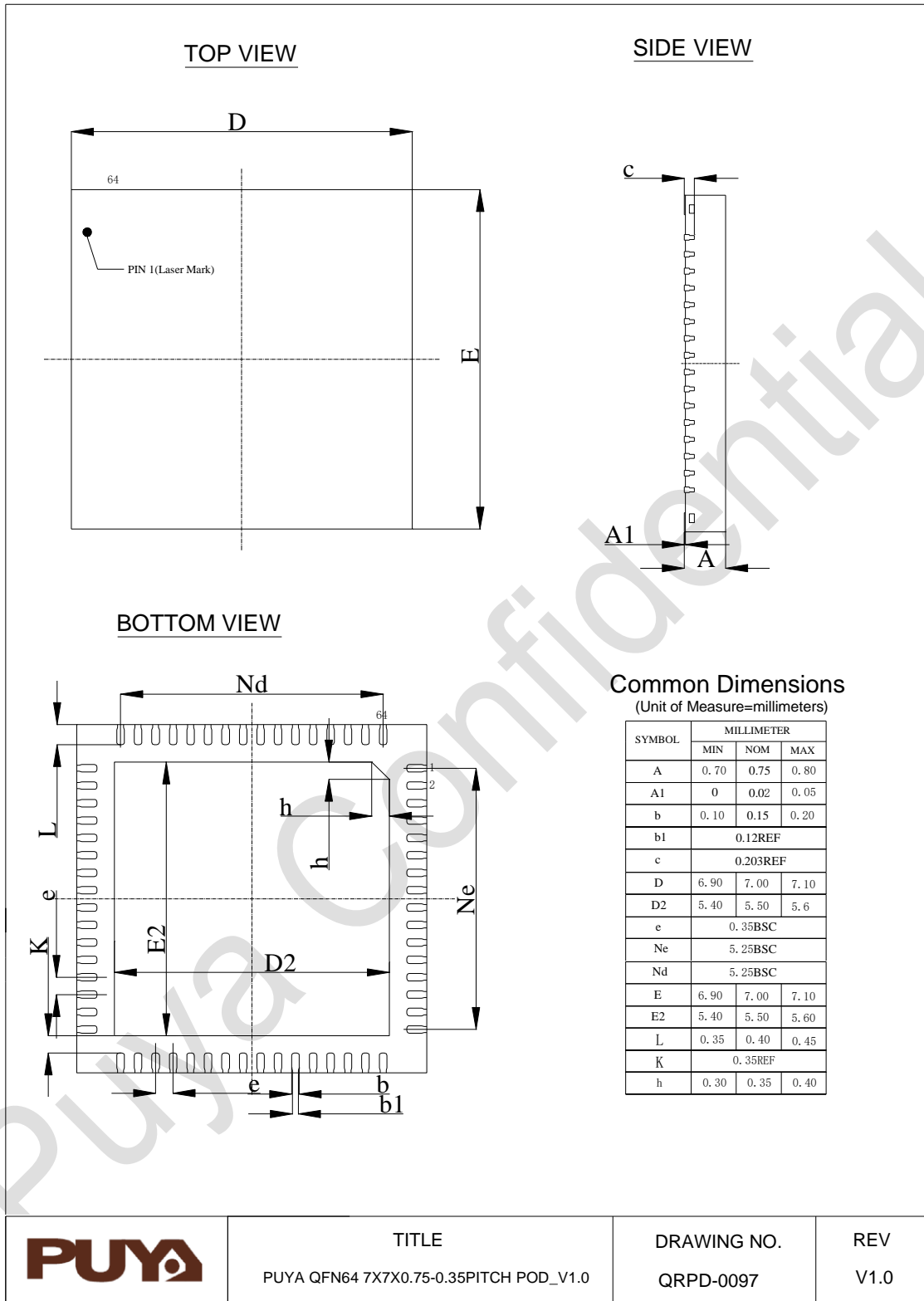
Figure 5-8 I²S timing diagram-Master mode(Philips protocol)

6. Package information

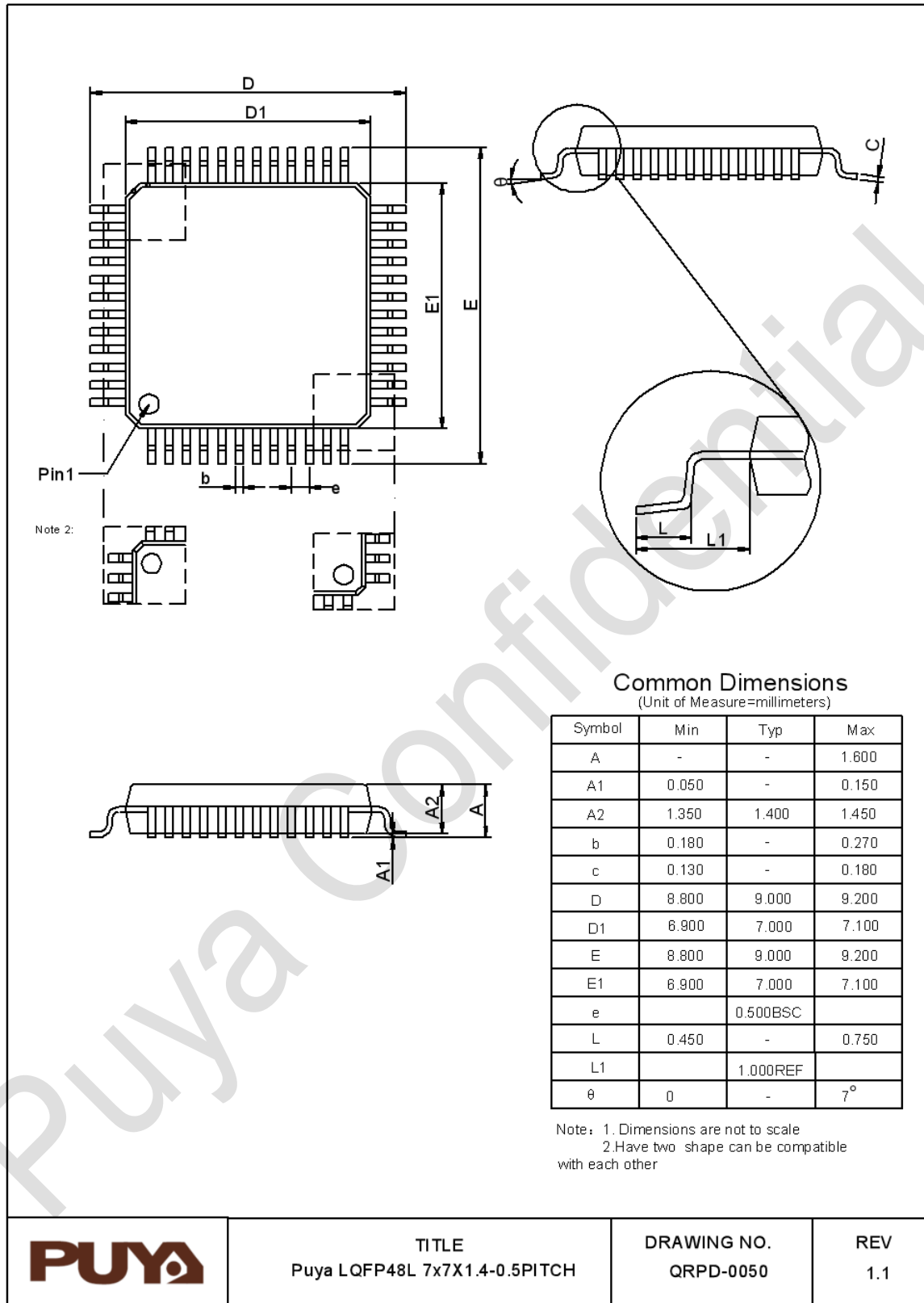
6.1. LQFP64 package size



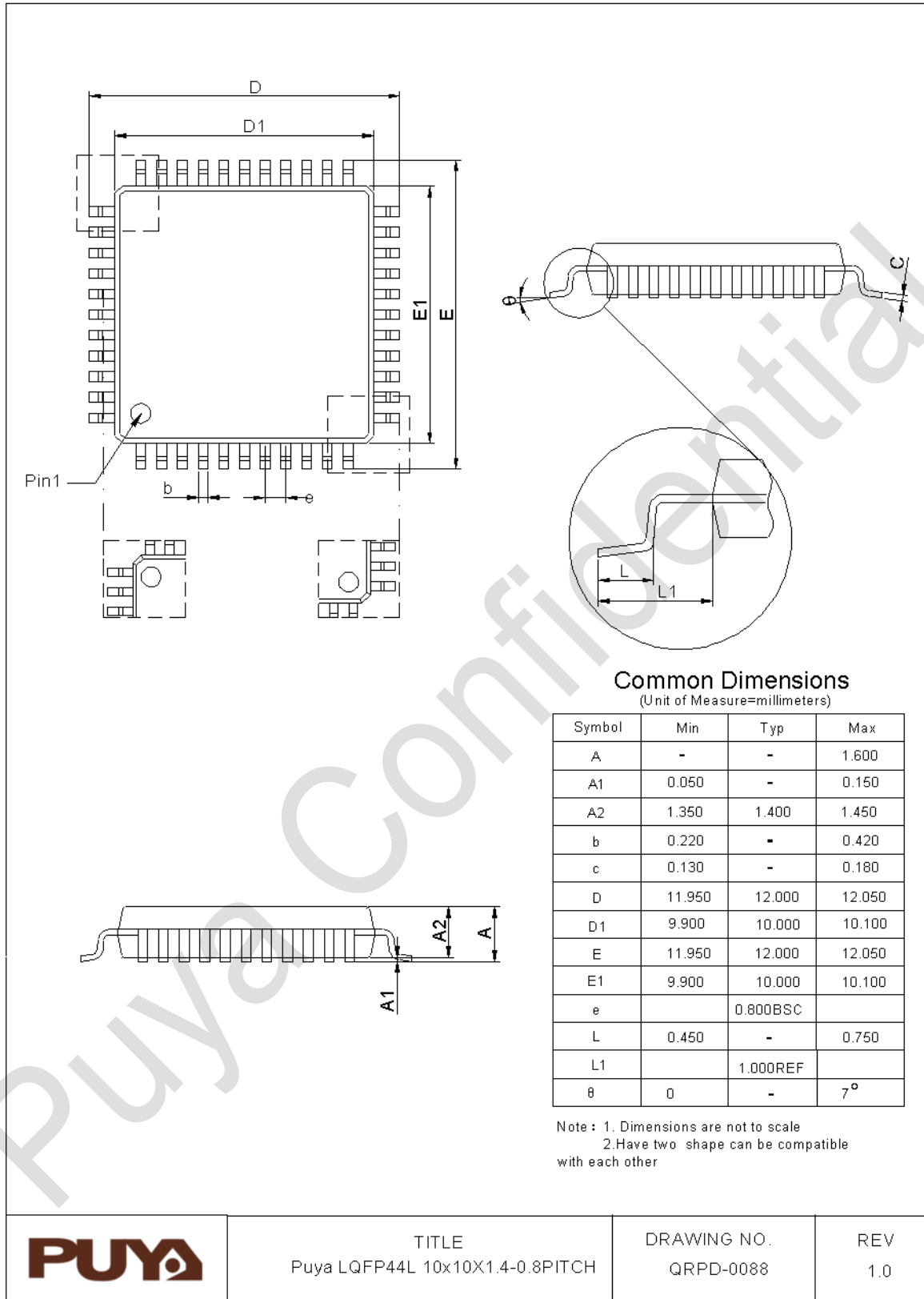
6.2. QFN64 package size



6.3. LQFP48 package size



6.4. LQFP44 package size



6.5. LQFP32 package size


Pin1

Note 2:

Common Dimensions
(Unit of Measure=millimeters)

| Symbol | Min | Typ | Max |
|----------|-------|----------|-------|
| A | - | - | 1.600 |
| A1 | 0.050 | - | 0.150 |
| A2 | 1.350 | 1.400 | 1.450 |
| b | 0.300 | - | 0.450 |
| c | 0.100 | - | 0.200 |
| D | 8.800 | 9.000 | 9.200 |
| D1 | 6.800 | 7.000 | 7.200 |
| E | 8.800 | 9.000 | 9.200 |
| E1 | 6.800 | 7.000 | 7.200 |
| e | | 0.800BSC | |
| L | 0.450 | - | 0.750 |
| L1 | | 1.000REF | |
| θ | 0 | - | 7° |

Note: 1. Dimensions are not to scale
2. Have two shape can be compatible with each other



TITLE
Puya LQFP32L 7x7X1.4-0.8PITCH

DRAWING NO.
QRPD-0040

REV
1.0

6.6. SOP28 package size

The image contains three technical drawings of the SOP28 package. The top drawing is a top view showing a rectangular package with 28 pins (14 on each long side). Dimensions labeled include 'b' (pin width), 'e' (pitch), 'E1' (width to last pin), and 'E' (total width). A pin 1 indicator is shown in the bottom-left corner. The middle drawing is a side view showing the package height and lead dimensions: 'D' (body length), 'A' (total height), 'A1' (lead height), and 'A2' (body height). The bottom drawing is a lead detail view showing the lead thickness 'c', the lead length 'L', the lead length to the end of the lead 'L1', and the lead angle 'θ'.

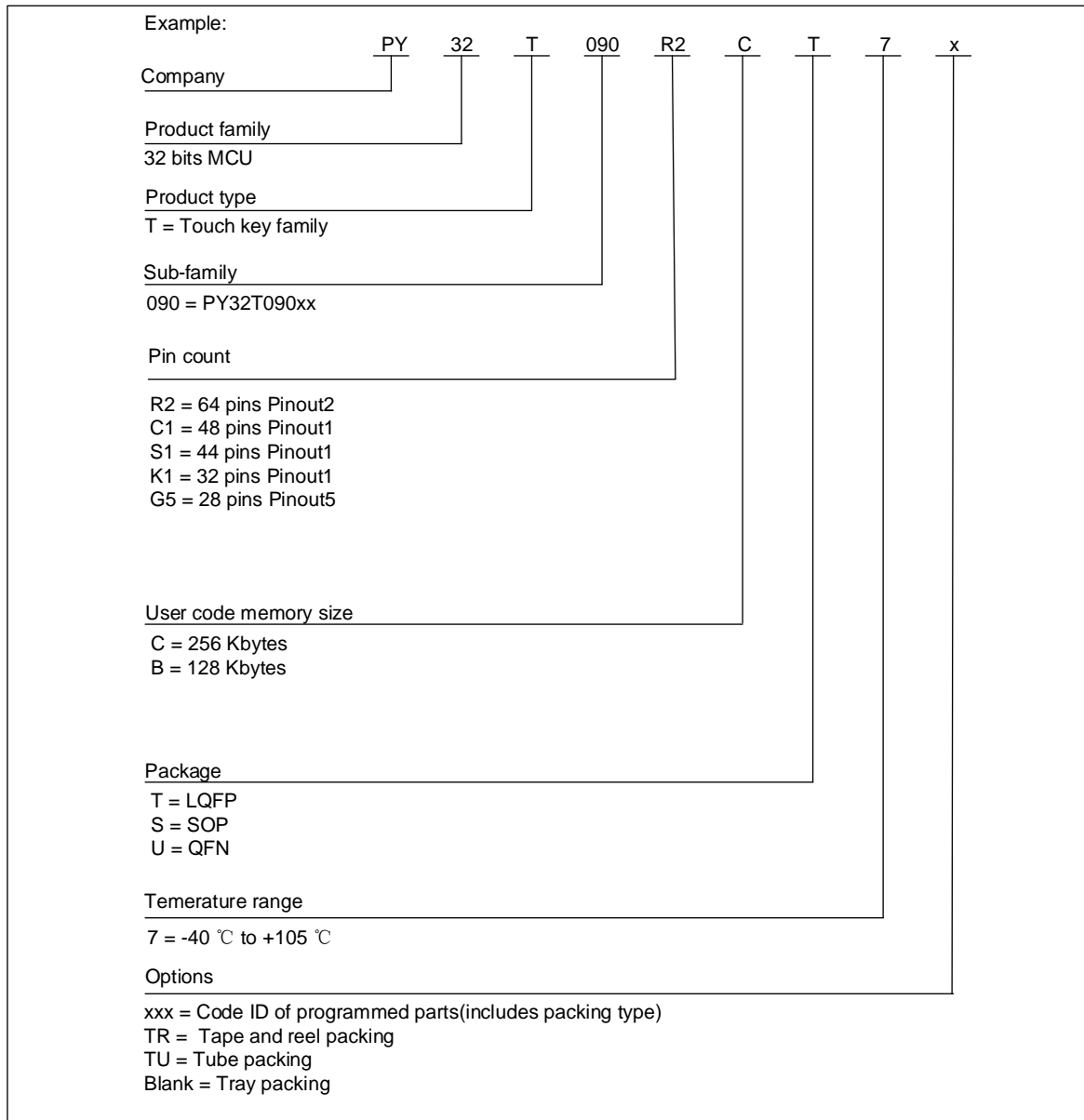
Common Dimensions
(Unit of Measure=millimeters)

| Symbol | Min | Typ | Max |
|--------|---------|-------|-------|
| A | 2.15 | - | 2.65 |
| A1 | 0.10 | - | 0.30 |
| A2 | 2.05 | - | 2.35 |
| b | 0.38 | - | 0.48 |
| c | 0.24 | - | 0.30 |
| D | 17.80 | 18.00 | 18.20 |
| E | 10.10 | 10.30 | 10.50 |
| E1 | 7.30 | 7.50 | 7.70 |
| e | 1.27BSC | | |
| L | 0.60 | - | 1.00 |
| L1 | 1.40REF | | |
| θ | 0 | - | 8° |

Note: Dimensions are not to scale.

| | | | |
|-------------|----------------------------------|--------------------------|------------|
| PUYA | TITLE PUYA SOP28 (300mil) POD | DRAWING NO. QRPD-0072 | REV 1.0 |
|-------------|----------------------------------|--------------------------|------------|

7. Ordering information



8. Version history

| Version | Date | Description |
|---------|------------|---|
| V0.1 | 2024.01.04 | Beta version |
| V0.5 | 2024.11.15 | Beta version |
| V0.6 | 2025.04.08 | Initial version |
| V0.7 | 2025.07.31 | Update product version and add QFN64 package. |
| V1.0 | 2025.08.15 | Official version |
| V1.1 | 2025.10.24 | 1. Revise the Pin definition of COMP in Table 3-2 2. Update production test data in Table 5-47 |
| V1.2 | 2026.02.12 | 1. Adjust the PDR hysteresis data in Table 5-6 2. Adjust the temperature sensor linearity data in Table 5-44 |
| V1.3 | 2026.05.21 | 1. Add new part number PY32T090G5CS7 |



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